

elementsix™
a De Beers Group Company

William Scalbert



INTRODUCTION





THIS SIMPLE CIRCLE IS SHAPING THE FUTURE

It may not look like it, but this circle represents an industry first. The CMX850 from Element Six is the world's most technically advanced and versatile grade PCBD, enabling tool makers to produce sharper, faster, multi-purposed performance enhancing tools - and reduce grinding costs by up to 25%. How? It's because of our continued commitment to innovation and excellence in the sector that tool makers and manufacturers around the globe are successfully using our CMX850 material today. Join them.

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SCOPE of HIPERDIAS PROJECT for Element Six

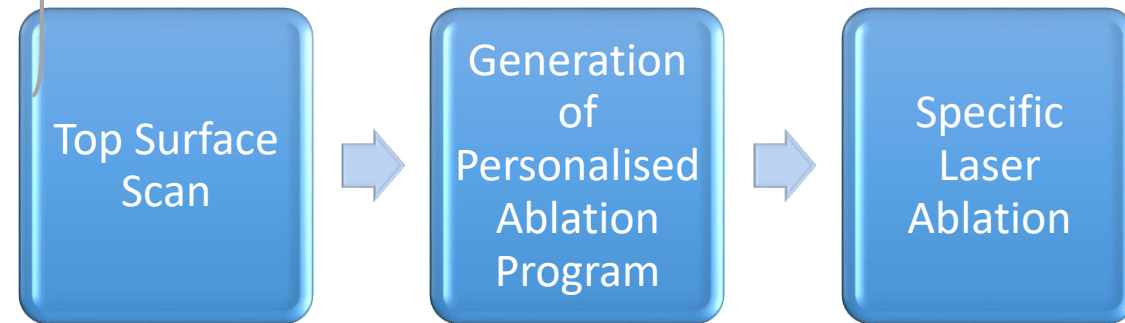
Main scope

Replacement of mechanical polishing machines by Laser machines to Laser ablate PCD up to a mirror surface finish:

- Low processing cost
- Fast processing
- Cold ablation -> no thermal effect
- Laser spot machining with controlled Laser parameters
- Automatic process
- Deal with various topographies thanks to top surface scanner/personalised program

Higher processing yield

DEVELOPMENT OF LASER POLISHING SYSTEM IN COLLABORATION WITH CLASS 4



SCOPE of HIPERDIAS PROJECT for Element Six

Further scope

If capable of polishing a 75 mm diameter disc, extremely wide opportunities arise!

- Polishing flat/non flat segments
- Polishing segment edges
- Polishing Syndrills
- Polishing 3D forms
- Polish other surfaces than PCD (PcBN)

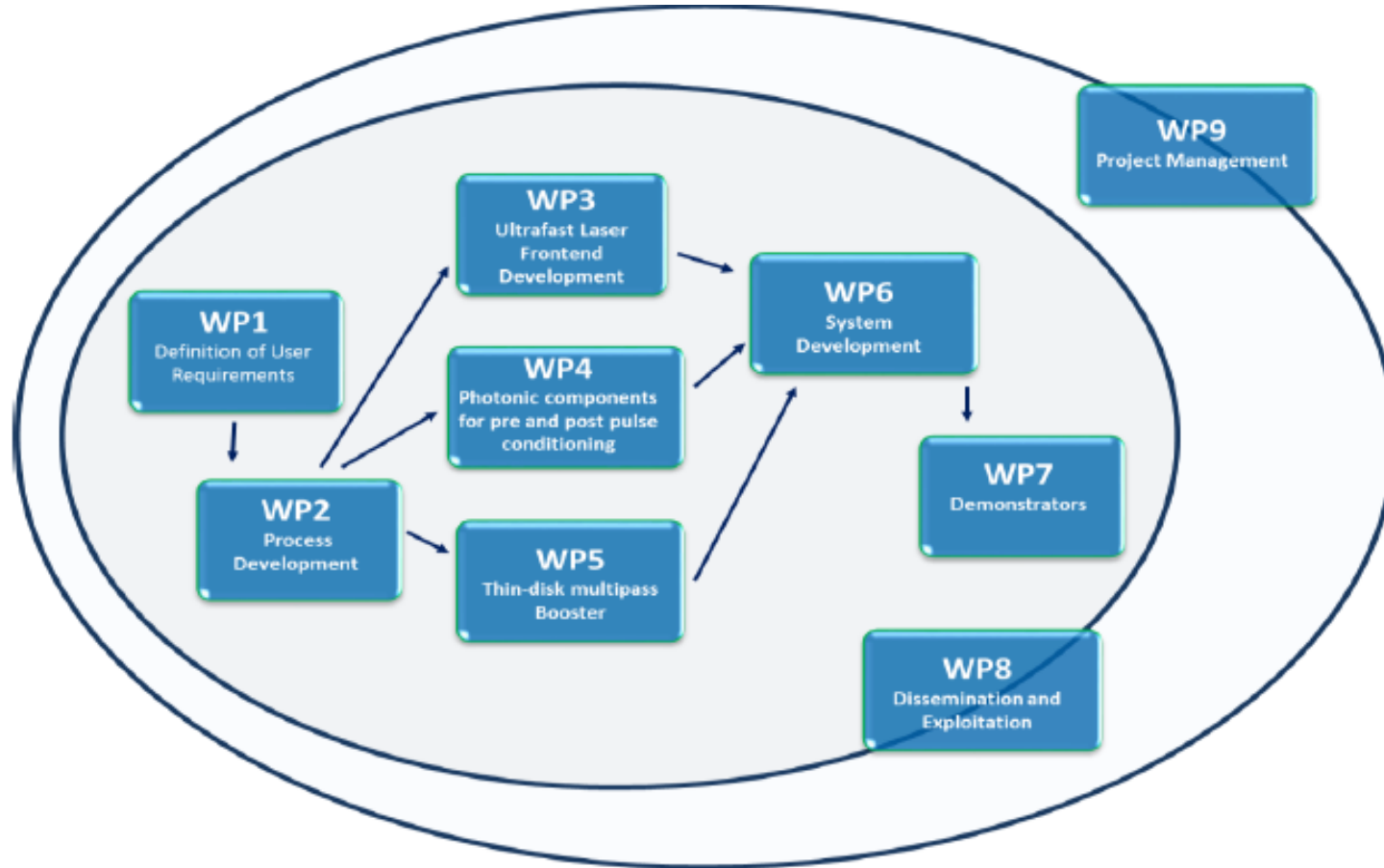


Oil & Gas Cutters

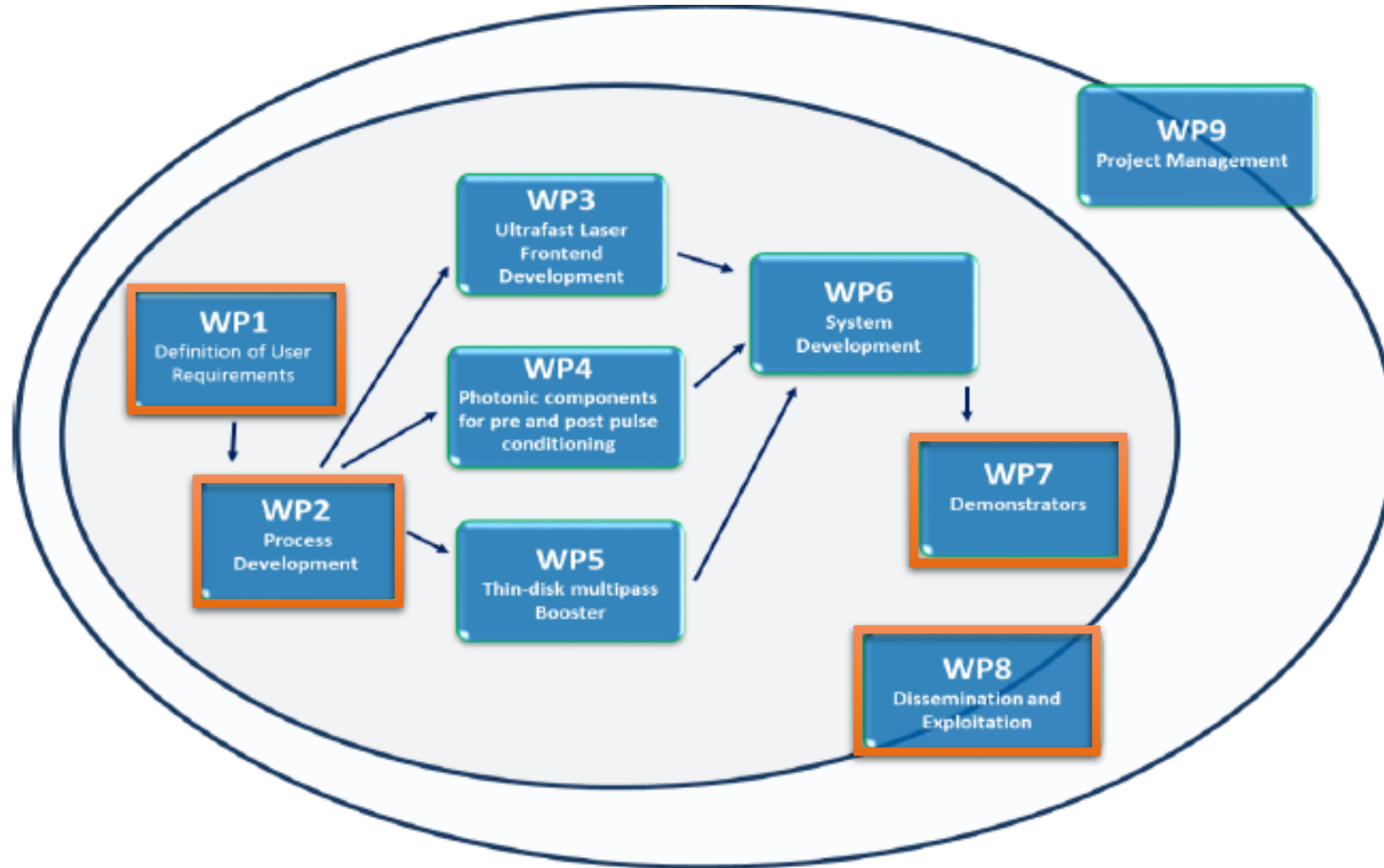


Advanced Material Cutters

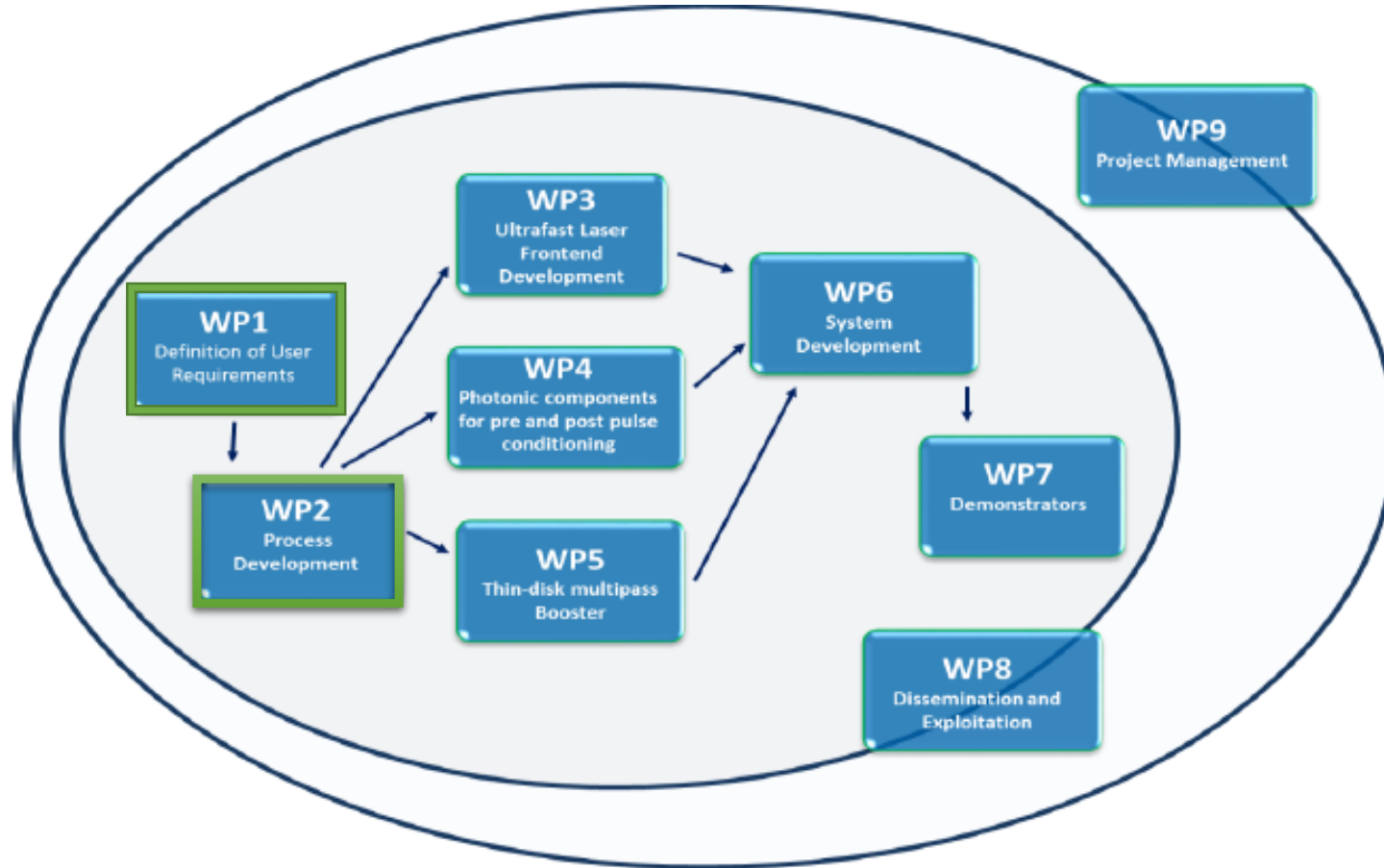
Work Packages



Element Six Work Packages




Work Packages presented today

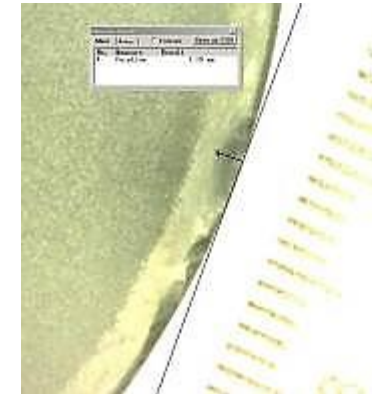


WP1

Definition of user requirements

Target Application

Key Performance Indicator	Unit	Target Value
Benchmarking product:		
<ul style="list-style-type: none"> PCD Syndite 		
Surface roughness	μm	≤ 0.01
Average ablation rate	mm ³ /s	≥ 0.15
Shape deviation	μm	≤ 2 (waviness)
Edge Chip		Must not encroach on the usable area (defined per disc). A maximum of three chips allowed as long as they are separated by the length of the chip. No more than 45° of the periphery can be affected by chipping. Chip-out cannot extend the thickness of the disc.
Pits	μm	A hole, cavity or small indentation in the PCD polished surface. Pitting is one or more small shallow craters on the surface. It has a definite depth. Typically can be large discrete pits or a scatter of pits smaller than 0.05mm diameter. See table 2 for diameter specifications. Pits with a significant* depth are not allowed.
Surface Cracks		A crack with a significant depth* is not acceptable. Requires case-by-case review.
Black spot (Binder components leakage)		Follow pitting specifications. Requires case-by-case review.





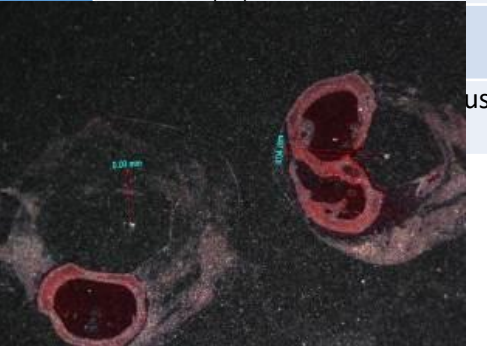
Edge Chipping



WP1 Definition of user requirements

Target Application

Key Performance Indicator	Unit	Target Value
Benchmarking product: <ul style="list-style-type: none"> PCD Syndite 		
Surface roughness	μm	≤ 0.01
Average ablation rate	mm^3/s	≥ 0.15
Shape deviation	μm	≤ 2 (waviness)
Edge Chip		Must not encroach on the usable area (defined per disc). A maximum of three chips allowed as long as they are separated by the length of the chip. No more than 45° of the periphery can be affected by chipping. Chip-out cannot extend the thickness of the disc.
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Surface Cracks		A crack with a significant depth* is not acceptable. Requires case-by-case review.
Black spot (Binder components leakage)		Follow pitting specifications. Requires case-by-case review.

Magnification	Image	Unit
>200 (XL)		um
200-100 (XL)		
100-50 (XS)	<p>Approximately 12 pits per disc</p> <p>CMX pit > 0.100mm (0.107x0.183mm)</p> <p>0.25pits/cm²</p>	mm
50-25 (XS)		um
<25		


CTH pit < 0.050mm (0.040x0.040mm)



WP1

Definition of user requirements

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Black spot (Binder components leakage)		Follow pitting specifications. Requires case-by-case review.




PCD Crack



WP1

Definition of user requirements

Target Application

Key Performance Indicator	Unit	Target Value
Benchmarking product:		
<ul style="list-style-type: none"> PCD Syndite 		
Surface roughness	μm	≤ 0.01
Average ablation rate	mm ³ /s	≥ 0.15
Shape deviation	μm	≤ 2 (waviness)
Edge Chip		Must not encroach on the usable area (defined per disc). A maximum of three chips allowed as long as they are separated by the length of the chip. No more than 45° of the periphery can be affected by chipping. Chip-out cannot extend the thickness of the disc.
Pits	μm	A hole, cavity or small indentation in the PCD polished surface. Pitting is one or more small shallow craters on the surface. It has a definite depth. Typically can be large discrete pits or a scatter of pits smaller than 0.05mm diameter. See table 2 for diameter specifications. Pits with a significant* depth are not allowed.
Surface Cracks		A crack with a significant depth* is not acceptable. Requires case-by-case review.
Black spot (Binder components leakage)		Follow pitting specifications. Requires case-by-case review.



PCD Black Dots



WP1	Definition of user requirements		
Target Application	Key Performance Indicator	Description	Target Value
	Inhomo	Surface inhomogeneous areas appear different in colour to the normal PCD surface. It has a degree of surface roughness with a definite depth and boundary	Refer to Table 4.2. Follow pitting specification (015). Fig 4.07
	Outer diameter finish	Outer diameter (OD) quality.	Edge imperfection must not encompass more than 120° of the periphery. Metal swarf must be removed. The metal ring surrounding the PCD shall be continuous and intact and shall not intrude into the PCD surface by more than 1mm.
	Surface Scratches	PCD surface scratches. Smaller grain grades tend to be more susceptible to scratching.	A scratch with a significant depth is not acceptable. A significant depth is detected by running a sharp edge over the scratch, See Code022.
	Polish quality	Quality standard of surface finish. A product maybe be partially polished with metal remain	Refer to Table 4.2. Fig 4.15 shows edge polishing fault or not fully polsihed
	Surface staining	The area can be clearly bounded and is easily observed both by the naked eye	Refer to Table 4.2. Follow pitting (015) specification.
	Metal Spots	Judged as a bright metallic area.	No contamination is allowed but traces of metal wrap, of negligible depth, are permitted on the periphery.
	Surface shading	PCD shading defines how dark is the colour of the PCD.PCDshading or toning defines how much grey exists in the colour.	Discs are to be judged on the amount of variation of shading and toning across the product by bare eye.
	Black spot	Typically found on polished PCD.	Follow Pitting specifications Code 015.
Bullet Holes / Grain growth	"Swiss cheese" type structure in the PCD layer. Grain Growth is defined as large crystals that appear on the surface of the disc or interface.	Code 015	



WP1

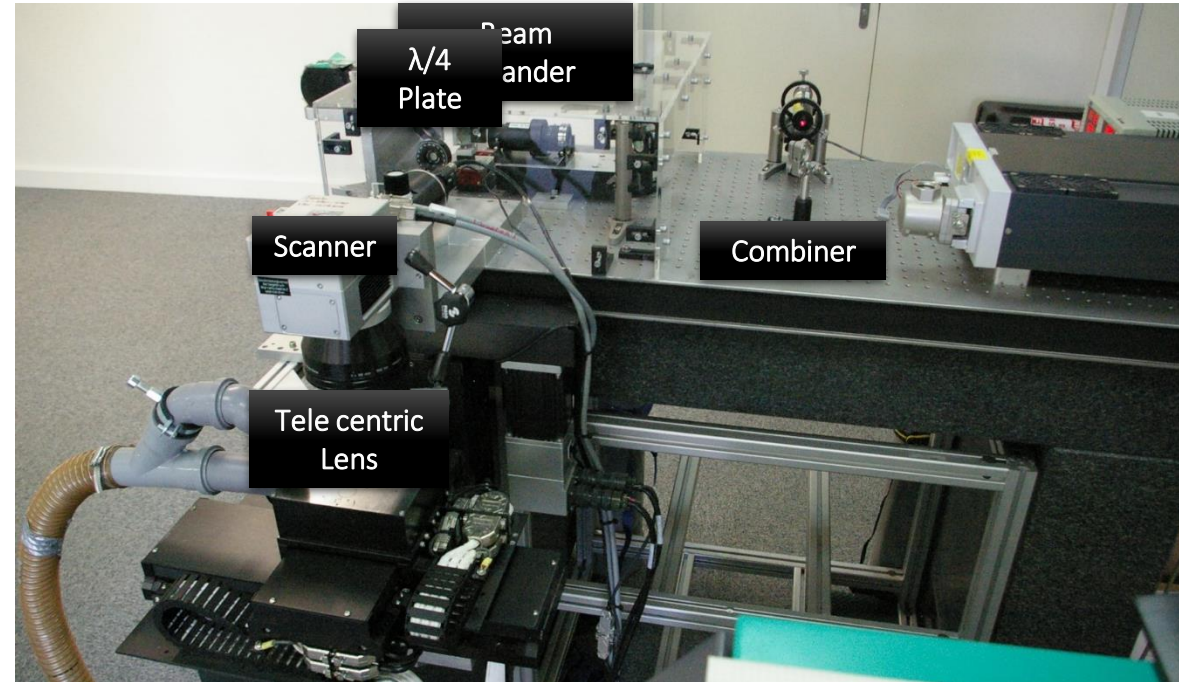
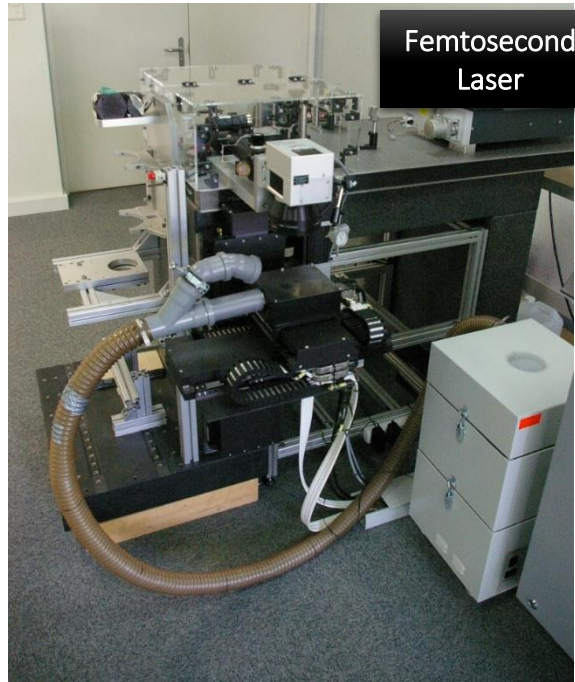
Definition of user requirements

Pre Trials Set Up

- 5 W Femtosecond Laser fully set up for pre-trials
- Ablation of PCD surface with 5 W Femtosecond Laser to establish window of parameters required for HIPERDIAS machine development

In collaboration with

CLASS4LASER
See the light

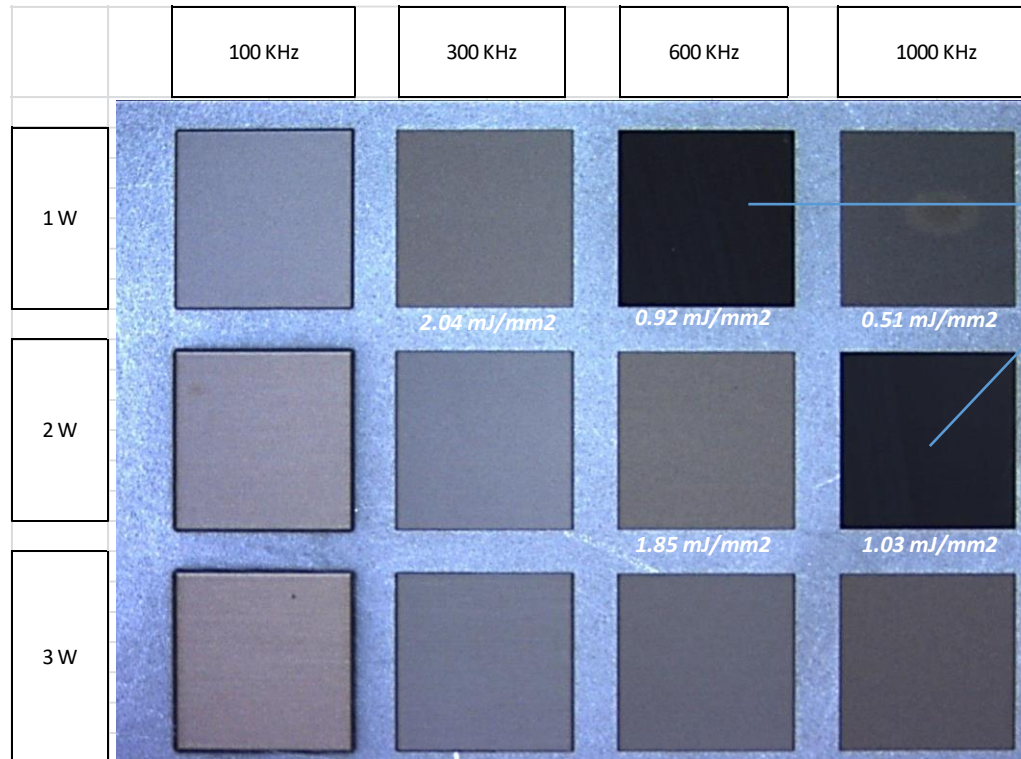


WP1

Definition of user requirements

Pre Trials

– Fluence threshold measurement at 280 fs



Graphitisation

Fluence Threshold
between 1 mJ/mm²
and 2 mJ/mm²

Parameters Set Up

λ	1030	ns
f'	100	mm
M^2	1.1	
Beam expander	4	
D	7.3	mm
$\omega_0 =$	21.74	μm

WP1

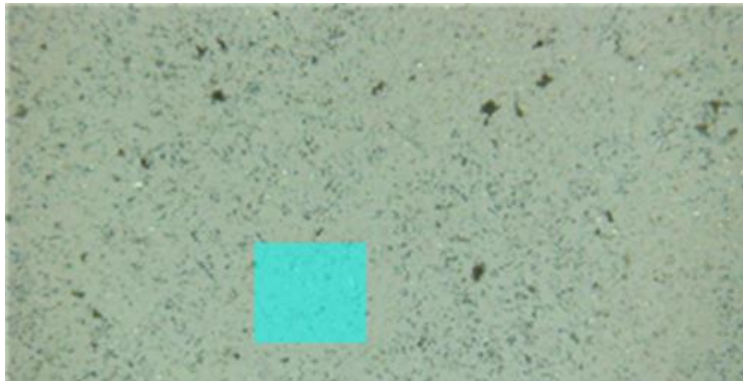
Definition of user requirements

Pre Trials Results

- Achievement of a surface with surface roughness Ra value between 0.14 – 0.34 μm with intensity of 1.36 mJ/mm^2
- Benchmark value = 0.06 – 0.13 μm (mechanically polished surface)

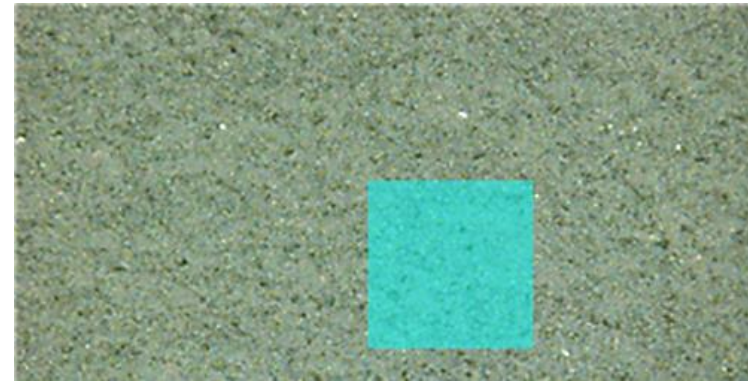
Mechanically polished PCD surface

	Rp	Rv	Rz	Ra	Rq
Seg.1	1.46 μm	1.14 μm	2.61 μm	0.13 μm	0.16 μm
	Rp	Rv	Rz	Ra	Rq
Seg.1	0.56 μm	0.45 μm	1.01 μm	0.04 μm	0.06 μm



Laser ablated PCD surface

	Rp	Rv	Rz	Ra	Rq
Seg.1	3.17 μm	2.79 μm	5.95 μm	0.34 μm	0.45 μm
	Rp	Rv	Rz	Ra	Rq
Seg.1	0.56 μm	0.98 μm	1.54 μm	0.14 μm	0.18 μm



WP1

Definition of user requirements

Laser Technology Specification

– Two steps processing to achieve high ablation rate

PARAMETER	1 st step processing	2 nd step processing
GOAL	Highest removal rate while lowering surface roughness of PCD surface	Lower removal rate while achieving lowest surface roughness possible to reach polished surface state
Power Average	High power average : 200 W Possibility to test 500 W ..?	Lower power average
Pulse Width	Few hundred femtoseconds to few picoseconds	Few hundred femtoseconds
Frequency	Over 1 MHz	Over 1 MHz
Wavelength	1030 nm (no special requirement)	1030 nm (no special requirement)



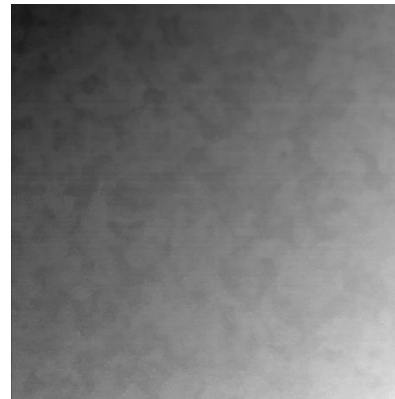
WP2

Process Development

Scanning Development

In collaboration with
CLASS4LASER
 See the light

- Development of topography sensor to overcome flatness issue and surface defects
- Topography sensor scans surface and creates a BITMAP image as below
- 2.000 x 2.000 pixels picture of a 10 x 10 mm steel surface
- 1 pixel = 5 μm
- Darker = deeper ablation



BITMAP image of feature to ablate



Microscope picture of ablated surface

- First ablation test = poor result...
- Need more development...



WP2

Process Development

Programming Development

*In collaboration
with*

CLASS4LASER
See the light



THANK YOU



Contribution of GLOphotonics



J.Alibert

GLOphotonics 123 Avenue Albert Thomas 87000, Limoges, France



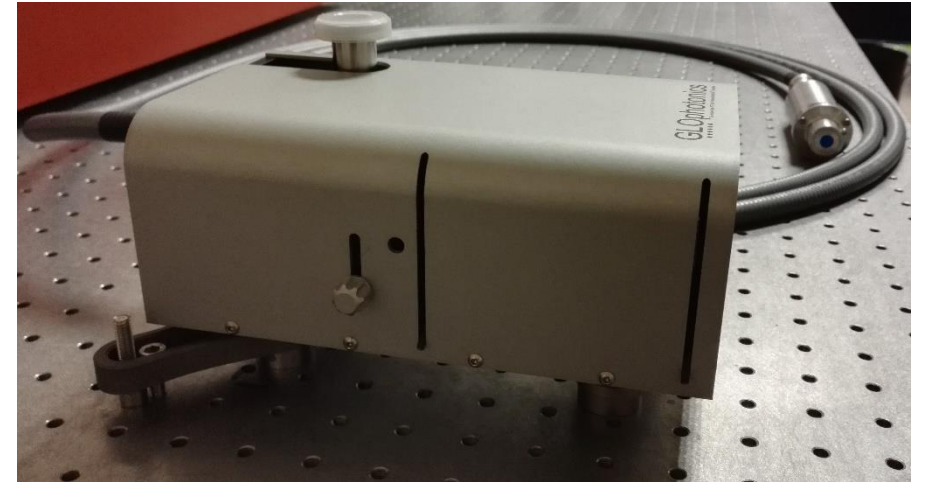
WP4

Photonic components for pre and post pulse conditioning

D4.4 task / Objective : Design, Fabrication and characterization of PMC module for beam delivery

Milestone MS4 – (T0+6)

- Design a PMC module including
 - HC-PCF fiber from GLOphotonics standard
 - integrated in coupling optics and compact design
 - Gas & vacuum management
 - Robust fiber housing
- Assembly and test prototype#1
 - Internal characterization with USP laser
 - Specification sheet production



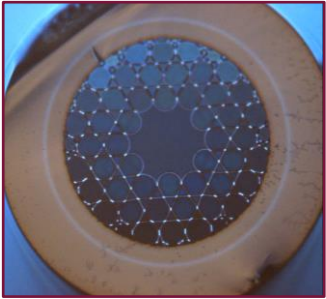
GLOphotonics
The Hollow-Core PCF and Photonic Waveguide Company



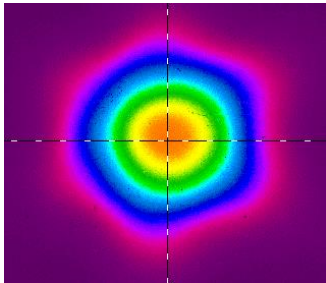
WP4 Photonic components for pre and post pulse conditioning

Design a PMC module including / HC-PCF fiber from GLOphotonics standard

PMC-C-Yb-7C



Optical micrograph of fiber end facet



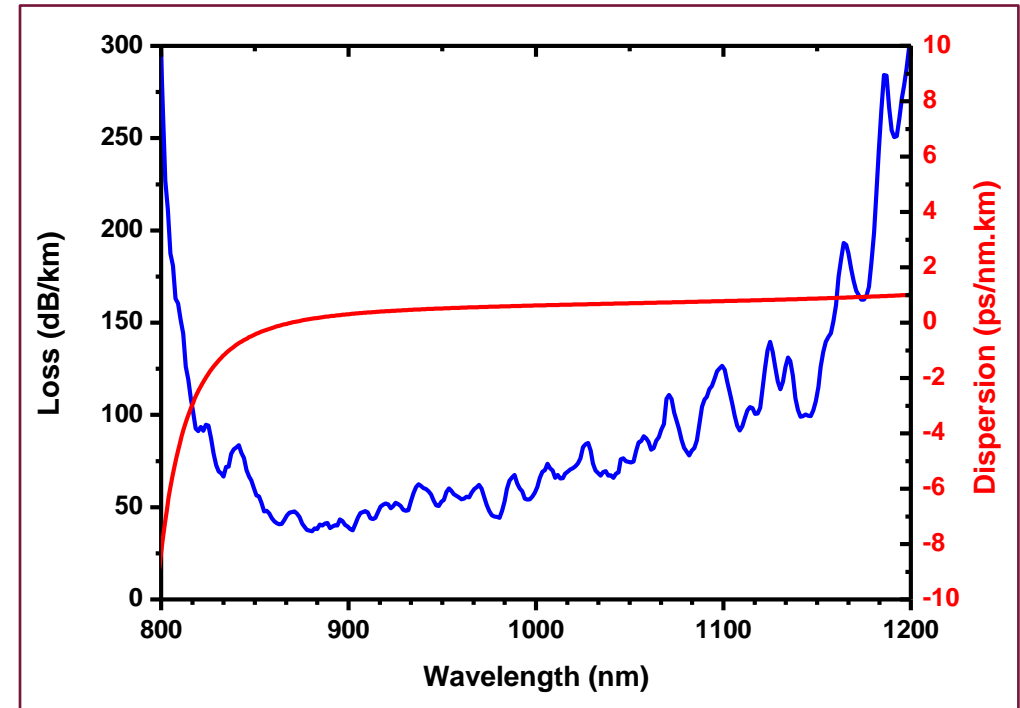
Typical output near field profile @ 1030nm

Physical Properties

Core contour	Hypocycloid with negative curvature parameter $b=1$
Inner Core Diameter	$57 \mu\text{m} \pm 1$
Outer Fiber Diameter	$320 \mu\text{m} \pm 1$
Fiber Coating Layer	Primary polymer coating

Optical Properties

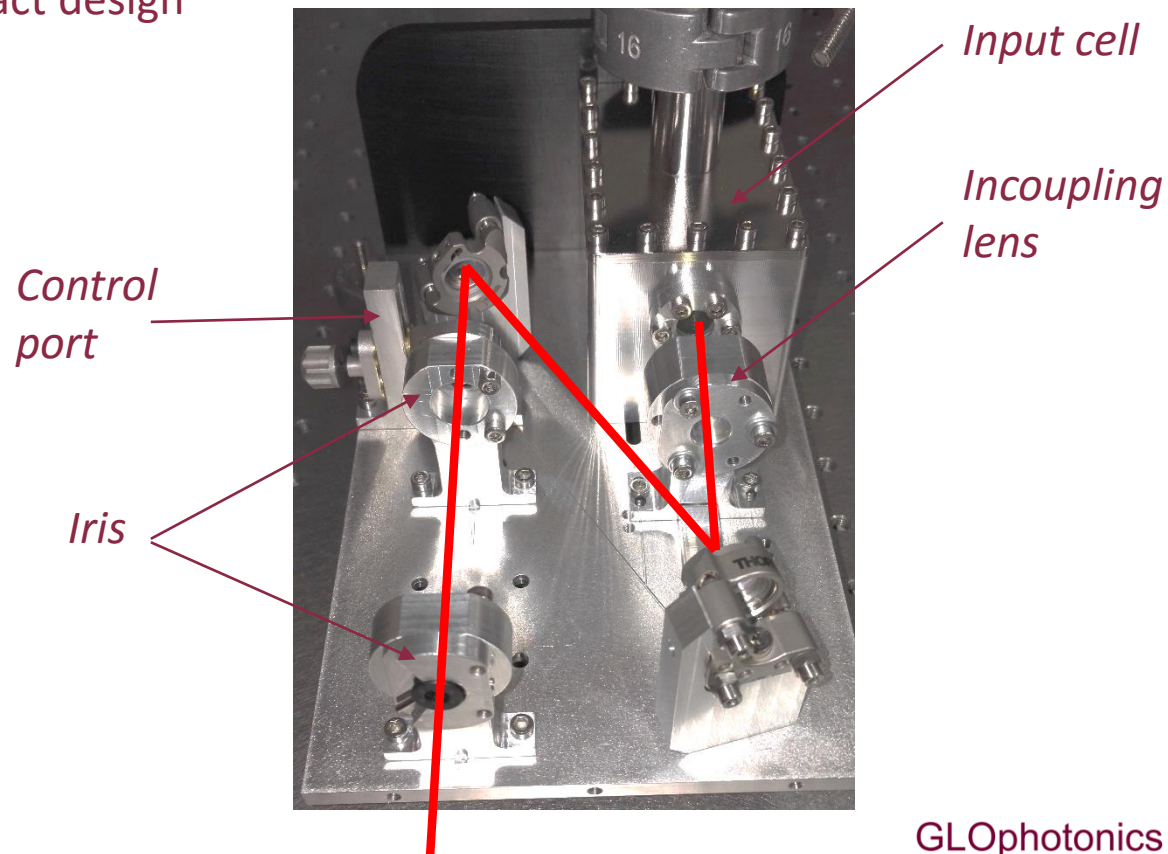
Center Wavelength	1030 nm
Attenuation @ 1030 nm	$50 \text{ dB/km} \pm 5$
Dispersion @ 1030 nm	$1 \text{ ps/nm/km} \pm 0.5$
Transmission band**	$>300\text{nm}$
<small>**Attenuation lower than 100 dB/km for the 900-1100nm</small>	
Mode Field Diameter ($1/e^2$)	$39 \mu\text{m} \pm 1$
3 dB bend loss radius @ 1030 nm	$5 \text{ cm} \pm 2$



WP4 Photonic components for pre and post pulse conditioning

Design a PMC module / integrated in coupling optics and compact design

- Compact imprint : 134mm x 212 mm
- Pré-aligned optics
- Iris & control port for user final alignment

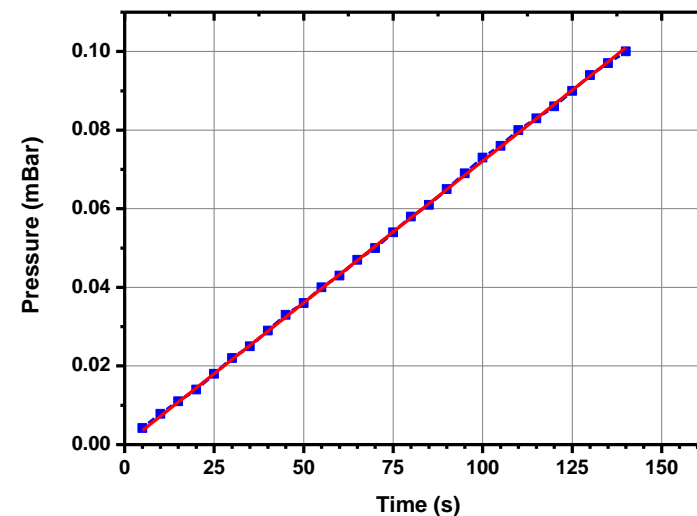


WP4

Photonic components for pre and post pulse conditioning

Design a PMC module / Gaz & vacuum management

- Standard KF 16 connection on input cell
- Hermetic output standard cell
- $<3e-4$ mbar.l/s (sensitivity limit of pressure rise test)

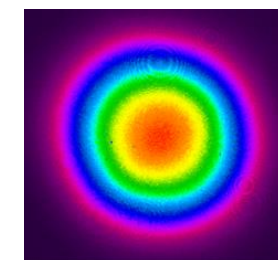
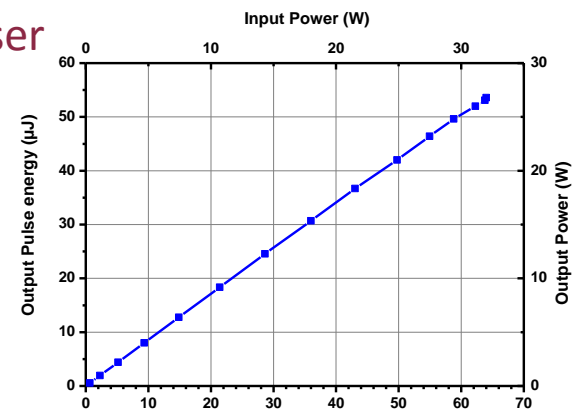


WP4 Photonic components for pre and post pulse conditioning

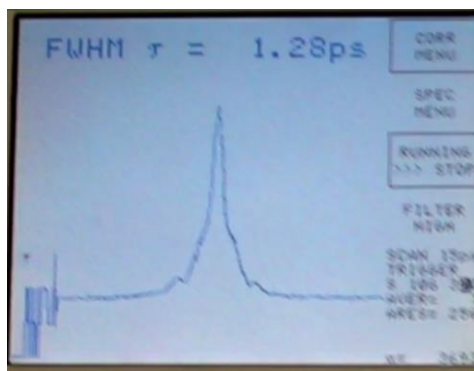
Assembly and test prototype#1 / Internal characterization with USP laser

Test with 800fs, 1030nm laser / module prototype#1 (5m)

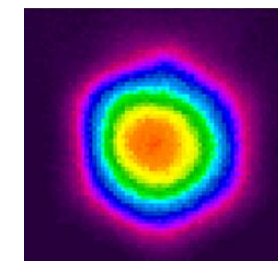
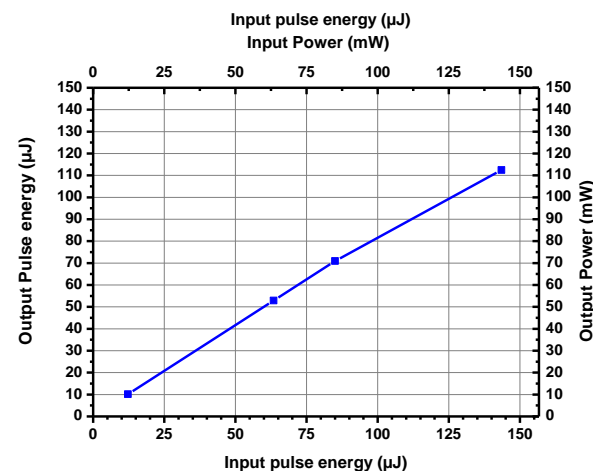
- >80% overall transmission (high energy, medium average power)
- Near diffraction limited output beam
- Preserved pulse width



Output far field profile



Autocorrelation trace for $E_{in}=129\mu\text{J}$



Output near field profile



WP4 Photonic components for pre and post pulse conditioning

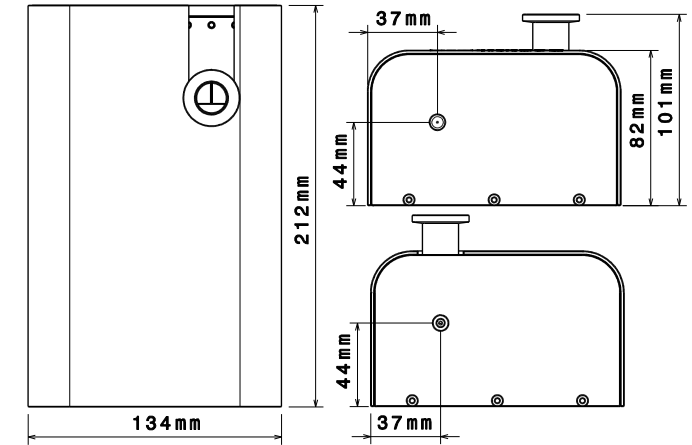
Assembly and test prototype#1 / Specification sheet production

Physical Properties

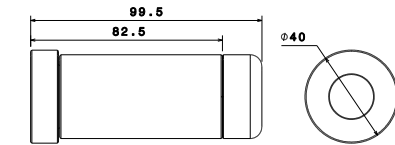
Fiber length	2 m ,3 m, 5 m
Output beam quality	$M^2 < 1.3$
Gas/Vacuum Connexion	KF16
Fiber Protection	Metallic monocoil
Monocoil OD ⁽¹⁾	11.3 mm
Output ⁽¹⁾	Sealed rounded cell compatible with optional collimation

Optical Properties

Center Wavelength	1030 nm
Transmission	>80%
Dispersion @ Center Wavelength	1 ps/nm/km \pm 0.5
Transmission band**	>200 nm
<small>**Attenuation lower than 100 dB/km</small>	
Input beam requirment	Collimated 2.5 mm \pm 0.1
Min bend radius	20 cm \pm 2
Max input power	50 W
Max input pulse energy	500 μ J



Module dimension



Output cell dimension

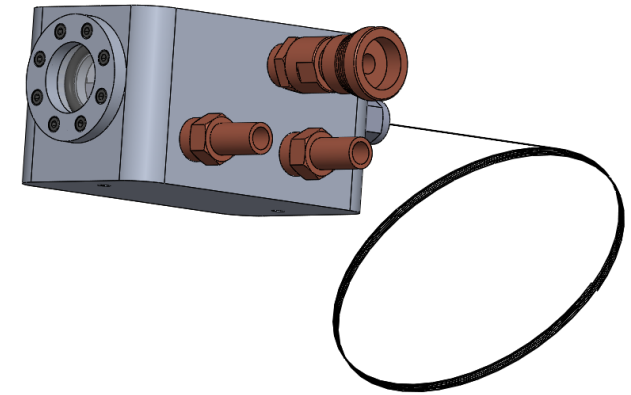


WP4

Photonic components for pre and post pulse conditioning

Next 6 month

- Specification refinement (Laser developer & end user)
- Design and production of prototype#2 (MS14)
- Qualification by a laser developer (MS14)
- Development of water cooled version for high power management



WP8

Dissemination & Exploitation (partner activities)

Peer review international conference:

1. Maurel M., GORSE A., BEAUDOU B., LEKIEFS Q., DEBORD B., GEROME F., BENABID F.: « **Kagome fiber based industrial laser beam delivery**», *Photonic West 2017*, submitted.





WP9 Project Management

Julie Devall



WP9 Project Management

T9.1	Management and coordination of the project
T9.2	Financial management of the project
T9.3	Management of ethical and gender related issues
T9.4	Establishment of consortium bodies, and of consortium meetings
T9.5	Management of the consolidation of technical and financial reports
T9.6	Monitoring and progress chasing and submission of deliverables and milestones



WP9 Project Management

Deliverable	Deliverable Title
D9.1	Project management handbook
D9.2	1st Periodic Report
D9.3	2nd Periodic Report
D9.3	2nd Periodic Report
D9.4	3rd Periodic Report & Final Report
D9.4	3rd Periodic & Final Reports

WP9

Project Management

Milestones

MS2	Project Handbook
MS9	Completion of financial dry-run with partners



- Quick overview
- Tasks Started / being monitored
- Deliverables Submitted
- Milestones Achieved



- Quick overview
- Tasks Started / being monitored
 - Currently 31 “active tasks”
 - 2 completed
 - 2 to start on the horizon (within the reporting period)
 - Total 35 tasks to report on in our yearly periodic reporting



WP No	WP Leader	Lead B	Participants	T.no	Task Description	Start	S.Date	Finish	F. Date
WP1	BOSCH	BOSCH	BOSCH,E6,C4L	T1.1	Collection of end-user application specifications	1	01/02/2016	4	31/05/2016
WP1	BOSCH	LASEA	C4L	T1.4	Interface requirements	1	01/02/2016	12	31/01/2017
WP4	XLIM	USTUTT	AMP,AMO	T4.1	Design of grating compressors	1	01/02/2016	18	31/07/2017
WP5	USTUTT	USTUTT	USTUTT	T5.1	Design of the thin-disk multipass amplifier	1	01/02/2016	6	31/07/2016
WP8	KITE	KITE	ALL	T8.1	Web site	1	01/02/2016	42	31/07/2019
WP8	KITE	KITE	ALL	T8.2	Dissemination	1	01/02/2016	42	31/07/2019
WP8	KITE	KITE	ALL	T8.5	Management of Intellectual Property	1	01/02/2016	42	31/07/2019
WP9	USTUTT	KITE	KITE	T9.1	Management and coordination of the project	1	01/02/2016	42	31/07/2019
WP9	USTUTT	KITE	KITE	T9.2	Financial management of the project	1	01/02/2016	42	31/07/2019
WP9	USTUTT	KITE	KITE	T9.3	Management of ethical and gender related issues	1	01/02/2016	42	31/07/2019
WP9	USTUTT	KITE	KITE	T9.4	Establishment of consortium bodies, and of consortium meetings	1	01/02/2016	42	31/07/2019
WP9	USTUTT	KITE	KITE	T9.5	Management of the consolidation of technical and financial reports	1	01/02/2016	42	31/07/2019
WP9	USTUTT	KITE	KITE	T9.6	Monitoring and progress chasing and submission of deliverables and milestones	1	01/02/2016	42	31/07/2019



WP No	WP Leader	Lead B	Participants	T.no	Task Description	Start	S.Date	Finish	F. Date
WP1	BOSCH	BOSCH	ALL	T1.2	Process and system specifications	2	01/03/2016	12	31/01/2017
WP1	BOSCH	BOSCH	C4L, E6	T1.3	Assessment and validation of technical progress	3	01/04/2016	12	31/01/2017
WP2	USTUTT	BOSCH	LASEA	T2.1	Fundamental process development 3D Si processing	3	01/04/2016	24	31/01/2018
WP2	USTUTT	C4L	USTUTT	T2.2	Fundamental process development fine cutting of metals	3	01/04/2016	23	31/12/2017
WP2	USTUTT	E6	C4L	T2.3	Fundamental process development diamond ablation	3	01/04/2016	23	31/12/2017
WP3	AMP	AMP	USTUTT	T3.1	50-W, 300-fs laser >1MHz at 1030nm	3	01/04/2016	9	31/10/2016
WP3	AMP	AMP	USTUTT, AMO	T3.2	200-W, ~500-fs laser >1MHz at 1030nm	3	01/04/2016	21	31/10/2017
WP3	AMP	AMP	ALL	T3.3	Flexible user interface including high speed modulation a high power pulse train	3	01/04/2016	21	31/10/2017
WP4	XLIM	AMO	USTUTT	T4.2	Development of a lithography process for the fabrication of pulse compression gratings	3	01/04/2016	30	31/07/2018
WP4	XLIM	GLO	AMP, XLIM	T4.4	Fabrication and characterization of photonic microcell (PMC) module	3	01/04/2016	36	31/01/2019
WP6	C4L	LASEA	AMP, C4L, BOSCH	T6.1	Definition of interfaces	3	01/04/2016	12	31/01/2017
WP6	C4L	USTUTT	AMP, C4L LASEA GLO	T6.2	Definition of laser & optics sizes; optics specifications (incl. fibre)	3	01/04/2016	15	30/04/2017
WP4	XLIM	AMO	USTUTT	T4.3	Development of an etching process for the fabrication of optical components	5	01/06/2016	30	31/07/2018

WP No	WP Leader	Lead B	Participants	T.no	Task Description	Start	S.Date	Finish	F. Date
WP5	USTUTT	USTUTT	AMP	T5.2	Assembly & characterization of Yb:YAG thin-disk multipass amplifier	6	01/07/2016	22	30/11/2017
WP8	KITE	KITE	ALL	T8.3	Exploitation	7	01/08/2016	42	31/07/2019
WP8	KITE	KITE	ALL	T8.4	Intellectual property and supply chain	7	01/08/2016	42	31/07/2019
WP8	KITE	KITE	ALL	T8.6	Training	7	01/08/2016	42	31/07/2019
WP6	C4L	C4L	LASEA	T6.3	Development of the interfaces	8	01/09/2016	22	30/11/2017
WP6	C4L	C4L	USTUTT,AMP, LASEA	T6.4	System layout and build-up	8	01/09/2016	36	31/01/2019
WP6	C4L	C4L	USTUTT, AMP, LASEA	T6.5	Integration of laser and optics	8	01/09/2016	24	31/01/2018
WP4	XLIM	GLO	AMP, XLIM	T4.5	Design/Fabrication of photonic microcell module with integrated coupling optics	12	01/01/2017	36	31/01/2019
WP4	XLIM	XLIM	GLO	T4.6	Design and Fabrication of polarization maintaining hollow-core photonic crystal	12	01/01/2017	36	31/01/2019



- Quick overview

Deliverables (retrospective review)

Due Month	DoA Month	WP No	Deliverable	Deliverable Title	Lead Beneficiary	Submitted?
1	Feb-16	WP9	D9.1	Project management handbook	KITE	Yes
3	Apr-16	WP8	D8.1	Project website established	KITE	Yes
3	Apr-16	WP8	D8.2	Communication kit	KITE	Yes
4	May-16	WP1	D1.1	End-user application specifications	BOSCH	Yes
4	May-16	WP4	D4.1	Report on simulation of pulse compression gratings with diffraction efficiency $\geq 99\%$ over large spectral bandwidth (5-10 nm) around 1030 nm	USTUTT	Yes
4	May-16	WP8	D8.3	Video presentation of the Hiperdias project	KITE	No
6	Jul-16	WP5	D5.1	Design of the multi-pass amplifier	USTUTT	Yes



- Quick overview

Deliverables (on horizon in this reporting period)

Due Month	DoA Month	WP No	Deliverable	Deliverable Title	Lead Beneficiary
9	Oct-16	WP3	D3.1	50-W, 300-fs,>1-MHz laser for seeding an Yb:YAG amplier (1)	AMP
9	Oct-16	WP3	D3.2	50-W, 300-fs,>1-MHz laser for seeding an Yb:YAG amplier (2)	AMP
12	Jan-17	WP1	D1.2	Process and system specifications	E6
12	Jan-17	WP1	D1.3	Prototypes and progress validation	BOSCH
12	Jan-17	WP1	D1.4	Definition of software-technical Interface	LASEA
12	Jan-17	WP4	D4.2	Report on first fabrication of pulse compression grating with 98% diffraction efficiency on large area, rectangular substrate material	AMO
12	Jan-17	WP6	D6.1	Definition of interfaces	LASEA
12	Jan-17	WP8	D8.4	Draft exploitation and dissemination plan	KITE
12	Jan-17	WP9	D9.2	1st Periodic Report	USTUTT



- **Quick overview**

Milestones (achieved so far)

- **MS1 Press Release - WP8 – Kite M01**
- **MS2 Kick-off Meeting and election of Consortium Bodies – WP8 – Kite M02**
- **MS3 First Design high efficient grating mirrors - WP4 – USTUTT M03**
- **MS4 PMC Module for fibre beam delivery prototype -WP4 – GLO M06**

Milestones (on horizon)

- **MS5 Specification for laser parameters established –WP1 –BOSCH M08 (Due now)**
- **MS6 1st generation grating mirror on large area rectangular substrates fabricated – WP4 –AMO M08 (Due now)**
- **MS7 Interface definition fixed – WP1,WP3, WP6 – LASEA M08 (Due now)**
- **MS8 A 50w, 300 fs at >1mhz seed laser – WP3 - AMP M09**
- **MS9 Completion of financial reporting “dry run” with all partners –WP9 M09**
- **MS10 Key performance indicators for productivity progress specified – WP1 – BOSCH – M10**
- **MS11 Key performance indicators for quality standards specified – WP1 –BOSCH – M12**
- **MS12 Specification for system technology established – WP1 –BOSCH –M12**
- **MS13 Fully optical characterisation of grating mirror regarding diffraction efficiency and LIDT – WP4 –AMO – M12**

- Quick overview

Milestones (on horizon continued)

- MS14 PMC module for fibre beam delivery prototype #2 – WP4 –GLO M12
- MS15 Design of HC-PCF with improved PER at 1 um (>20 dB) – WP4 - XLIM M12
- MS16 System layout fixed – WP3, WP4, WP5, WP6 – C4L M12



- Quick overview

Milestones (on horizon continued)

- **MS14 PMC module for fibre beam delivery prototype #2 – WP4 –GLO M12**
- **MS15 Design of HC-PCF with improved PER at 1 um (>20 dB) – WP4 - XLIM M12**
- **MS16 System layout fixed – WP3, WP4, WP5, WP6 – C4L M12**



WP9

Project Management (Periodic Reporting)

Technical Report – Project Coordinator’s Project Summary (for the period)

- *Project Summary – to be completed by the coordinator*

The Project Coordinator is expected to answer the following questions;

- *Summary of the context and overall objectives of the project*
- *Work performed from the beginning of the project to the end of the period covered by the report*
- *Progress beyond the state of the art and expected potential impact (including the socio-economic and the wider societal implications of the project so far)*
- *Address (URL) of the projects public website*
- *Any supporting documents (images etc.)*

Technical Report - All WP Leader updates (for the period)

- *All WP Leaders to provide an overall summary of the progress so far for the period*
- *To break down the summary at task level*
- *Name the participants involved in each of the tasks*
- *Describe any deviations from the Description of Work (resources, timescales, scope)*
- *Describe any corrective actions that took place on the WP to rectify any deviations*



Work package no.	WP 1	Plan-Start:	1	Plan-End:	12
Lead Participant	5-BOSCH	Actual-Start:		Actual-End:	
Work package title	Definition of User Requirements				
Activity Type	RTD				
Participant involved	BOSCH, USTUTT,AMP, C4L, AMO, XLIM, LASEA, GLO, E6				
Work package summary of progress towards objectives					
<i>Please provide an overall summary of the period here</i>					



Task no.	T1.1	Plan-Start:	M1	Plan-End:	M4
Lead Participant	BOSCH	Actual-Start:		Actual-End:	1
Task title	Collection of end-user application specifications				
Participant involved	C4L, E6				
Progress of work;					
<i>Your update here</i>					



WP1 Deliverables and Milestones due in this period					
Lead Participant	BOSCH	Date due:		Date submitted:	
Deliverable no. & title	D1.1 End-user application specifications				
Participant involved					
Progress of work					
<i>Your update here</i>					



<https://ec.europa.eu/research/participants/grants-app/reporting/DLV-687880>

Grant Management		Project Continuous Report										
687880 (HIPERDIAS)	RIA	Summary for publication	Deliverables	Milestones	Critical Risks	Publications	Dissemination	Patents (IPR)	Innovation	SME Impact	Gender	
THE FRAMEWORK PROGRAMME FOR RESEARCH AND INNOVATION HORIZON 2020	Call: H2020-ICT-2015 Topic: ICT-27-2015 Unit: CNECT/A/04											



WP9

Project Management

Task 9.3 Management of ethical and gender related issues (USTUTT, KITE M01 – M42)

The HIPERDIAS Consortium takes seriously issues related to ethics in science and gender aspects. Their management is detailed in Section 1.3. Monitoring and reporting will be carried out by the CPO. At the end of the project, ethical and gender related issues will be covered in the final report, under the heading 'awareness and wider societal implications'.

Grant Management | Project Continuous Report

687880 (HIPERDIAS) RIA

Summary for publication: Deliverables: Milestones: Critical Risks: Publications: Dissemination: Patents (IPR): Innovation: SME Impact: Gender:

Gender

Gender Dimension in the Project

Does the project include a gender dimension in research? Yes No

Gender of R&D participants involved in the project

Please include in the count the participants working for Third Parties (if appropriate)

Organisation	Number of Female participants	Number of Male participants	Total Number of participants
1 - UNIVERSITAET STUTTGART			0
2 - AMPLITUDE SYSTEMES SA			0
3 - CLASS 4 LASER PROFESSIONALS AG			0
4 - GESELLSCHAFT FÜR ANGEWANDTE MIKRO UND OPTOELEKTRONIK MIT BESCHRANKTERHAFTUNG AMO GMBH			0
5 - ROBERT BOSCH GMBH			0
6 - UNIVERSITE DE LIMOGES			0
7 - LASER ENGINEERING APPLICATIONS SA			0
8 - GLOPHOTONICS			0
9 - ELEMENT SIX LIMITED			0
10 - Kite Innovation (Europe) Limited			0

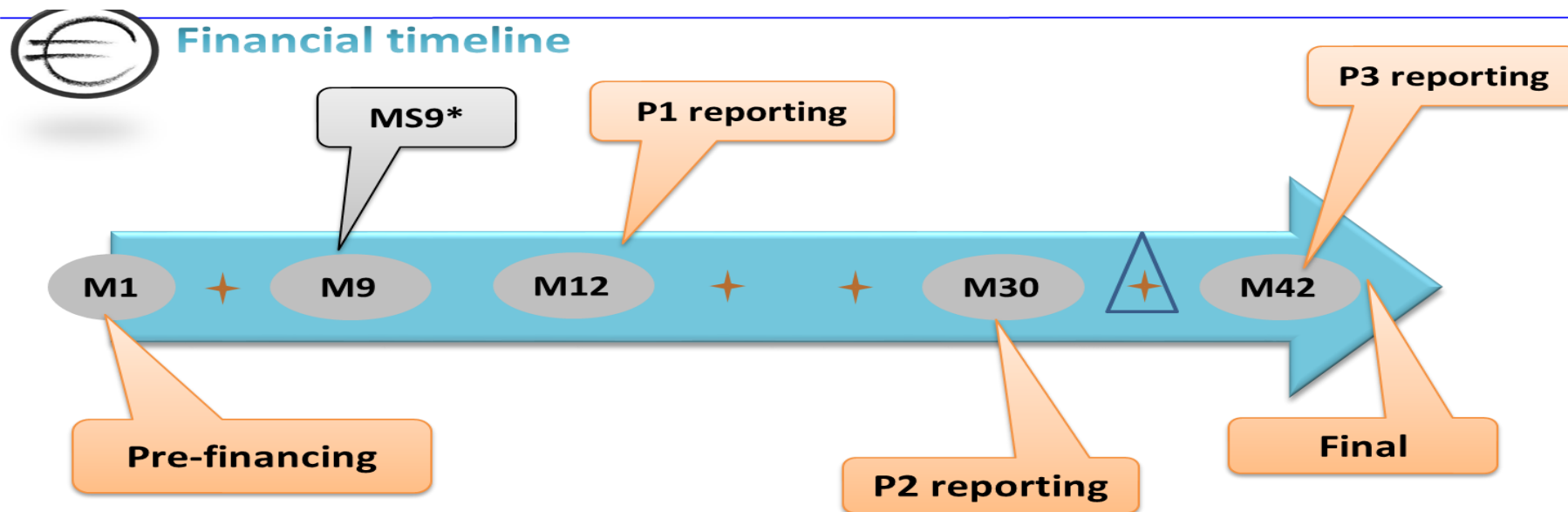
Handwritten notes: Handle it and the other... (faint text)



WP9

Project Management

T9.2 Financial management of the project



✦ – at six monthly intervals, the management board will request updated technical & financial reports

*MS9 – Completion of reporting “dry run” with all partners. T9.2 Means of verification: Draft financial report generated



WP9		Project Management							
Partner	Partner short Name	Total EU Contribution (€)	Pre-financing distribution			90% limit of max grant amount	Max interim payments during project	Max final payment at the end of project	Total check = net pre finance + Period payment + final payment
			Received	Guarantee Fund	Total Net amount transferrable				
1	USTUTT	€ 909,187.50	€ 393,950.94	€ 45,459.38	€ 348,491.57	€ 818,268.75	€ 424,317.81	€ 136,378.13	€ 909,187.50
2	AMP	€ 555,750.00	€ 240,806.48	€ 27,787.50	€ 213,018.98	€ 500,175.00	€ 259,368.52	€ 83,362.50	€ 555,750.00
4	AMO	€ 371,742.50	€ 161,076.03	€ 18,587.13	€ 142,488.90	€ 334,568.25	€ 173,492.22	€ 55,761.38	€ 371,742.50
5	BOSCH	€ 499,002.50	€ 216,217.78	€ 24,950.13	€ 191,267.66	€ 449,102.25	€ 232,884.47	€ 74,850.38	€ 499,002.50
6	XLIM	€ 299,500.00	€ 129,773.35	€ 14,975.00	€ 114,798.35	€ 269,550.00	€ 139,776.65	€ 44,925.00	€ 299,500.00
7	LASEA	€ 441,750.00	€ 191,410.28	€ 22,087.50	€ 169,322.78	€ 397,575.00	€ 206,164.72	€ 66,262.50	€ 441,750.00
8	GLO	€ 289,750.00	€ 125,548.68	€ 14,487.50	€ 111,061.18	€ 260,775.00	€ 135,226.32	€ 43,462.50	€ 289,750.00
9	E6	€ 123,417.50	€ 53,476.80	€ 6,170.88	€ 47,305.93	€ 111,075.75	€ 57,598.95	€ 18,512.63	€ 123,417.50
	E6 UK	€ 8,832.50	€ 3,827.12	€ 441.63	€ 3,385.50	€ 7,949.25	€ 4,122.13	€ 1,324.88	€ 8,832.50
10	KITE	€ 141,375.00	€ 61,257.79	€ 7,068.75	€ 54,189.04	€ 127,237.50	€ 65,979.71	€ 21,206.25	€ 141,375.00
TOTAL		€ 3,640,307.50	€ 1,577,345.24	€ 182,015.38	€ 1,395,329.87	€ 3,276,276.75	€ 1,698,931.51	€ 546,046.13	€ 3,640,307.50



WP9

Project Management

Financial Reporting

We are reporting on all costs which are eligible

- Actual and incurred during the project
- Needed solely for work on the project
- Recorded in the accounts
- Salary costs should be backed up by timesheets



WP9

Project Management

Financial Reporting

Examples of ineligible costs

- Exchange rate losses
- Costs already considered
- Costs already included in “indirect costs”
- Costs which may be considered excessive

Remember if you exceed 325,000 during the course of the project, you will be required to carry out an audit by an external auditor

Remember to keep all records as the EU at any time can carry out their own audit



WP9

Project Management

Indirect Costs

Are costs that are not directly linked to the action implementation and therefore cannot be attributed directly to it.

Indirect costs are eligible if they are declared on the basis of the **flat-rate of 25% of the eligible direct costs** (see Article 5.2), from which are excluded:

- costs of subcontracting and
- costs of in-kind contributions provided by third parties which are not used on the beneficiary's premises;



WP9

Project Management

Financial Dry run – to be complete by 1st Nov

Spreadsheet sent out to financial partners, complete by 3rd week of Oct.





David Bruneel

Jose Antonio Ramos



- Please provide an update of the progress made so far on the project by Work package, any deliverables you have contributed to and milestones worked on.
 - You may present this by whatever means you see fit (i.e. include photos, link to video etc) but please use this official Hiperdias template.
 - It may be the case that you have not worked on all work packages - delete as appropriate
 - You may add to the amount of slides here, simply duplicate the format
-
- Delete this information slide from your final presentation

WP1 Definition of user requirements

Work completed

T1.4 : Definition of the interfaces :

Description of the task: Definition of the requirements of the software/technical interfaces to be developed. These activities will focus on aspects as electrical, mechanical, and optical and software interfaces between the different units (laser, scanner, axis, opto-mechanical element).

Create and provide a document that defines and lists all the interfaces between the different components of the system. This document is a living document to be completed during the definition tasks. Every partner has to fill its corresponding tab with the different interfaces details of the component(s) he is in charge, and if necessary to adapt it. This document gathers all information from the different partners for the different interfaces.

Item	M1	M2	M3	M4	M5	M6	M7	M8	M9	M10	M11	M12	...
WP1 - Definition of User Requirements								M1.1		M1.2		M1.3	
T1.1 Collection of end-user application specifications				D1.1									M1.4
T1.2 Process and system specifications													D1.2
T1.3 Assessment and validation of technical progress													D1.3
T1.4 Interface requirements													D1.4



Interfaces requirements_USTUTT_AM



WP1

Definition of user requirements

Next 6 months

T1.4: Make the document fully completed by all the involved partners. Highlight any mismatch between the different units and propose a solution.

The gathered information will then be used in the T6.1 which consists in describing the technical details of interfaces that will have to be developed or modified by the different partners to overcome any mismatch.



WP2

Process Development

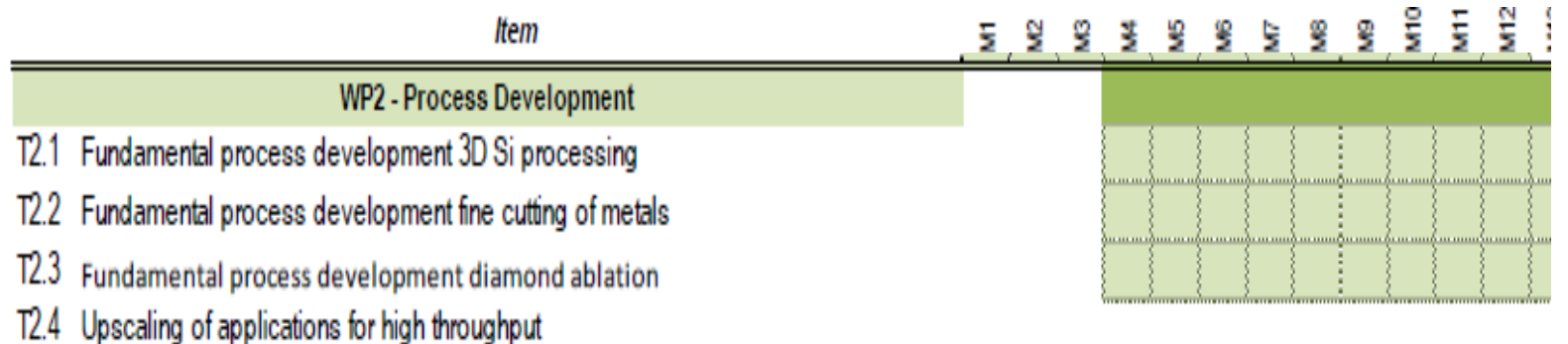
Work completed

T2.1 : Fundamental process development 3D Si processing

A study of the process of silicon has been carried out using an actual setup available at LASEA.

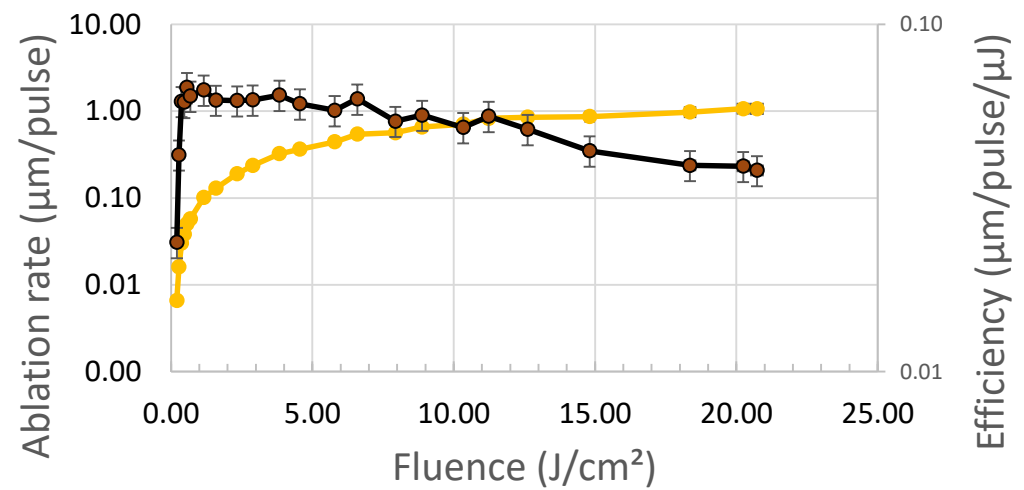
The goal of this study is to point out the best conditions of machining in terms of laser parameters and quality.

This first study revealed that the use of a not too high energy density should be used in order to avoid degradation of the quality with edge burrs appearing. A maximum energy density can be determined which corresponds to the start of the apparition of the burrs.



WP2	Process Development
<p><i>Work completed</i></p> <p><i>T2.1 : Fundamental process development 3D Si processing :</i></p> <p><i>Spot diameter : 13 μm</i></p> <p><i>Speed : 1m/s</i></p> <p><i>5 pulses (cumulated)</i></p> <p><i>Critical energy density : $\sim 0.7 \text{ J/cm}^2$</i></p> <p><i>Ablation rate : 60 nm/pulse</i></p> <p><i>Efficiency : 62nm/pulse/μJ</i></p>	

Ablation and efficiency - 1D

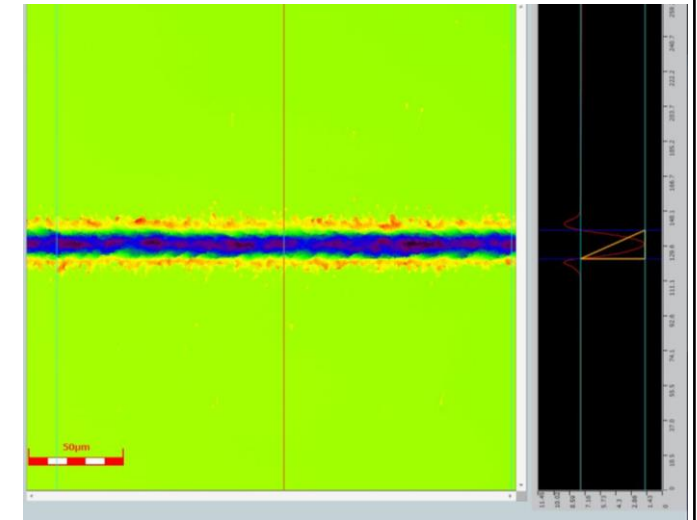
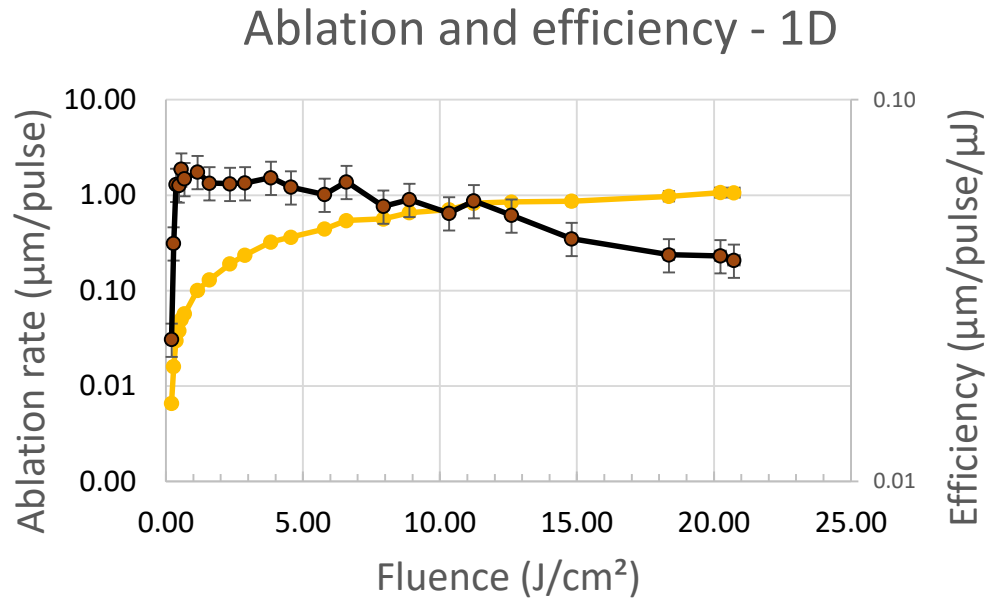
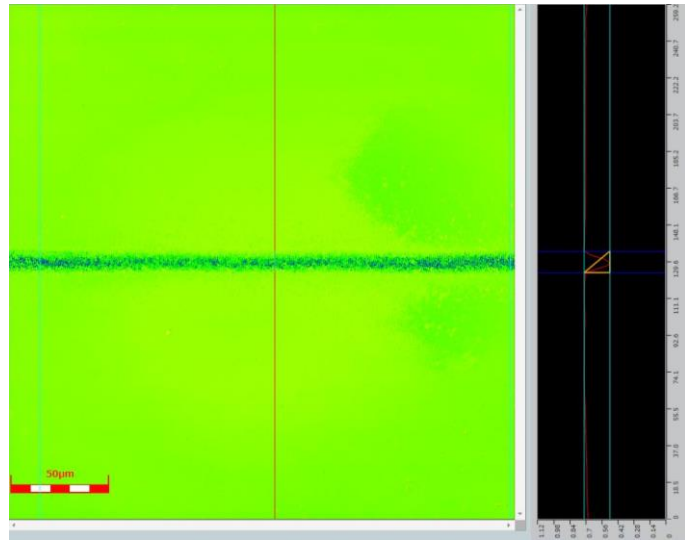


WP2

Process Development

Work completed

T2.1 : Fundamental process development 3D Si processing :



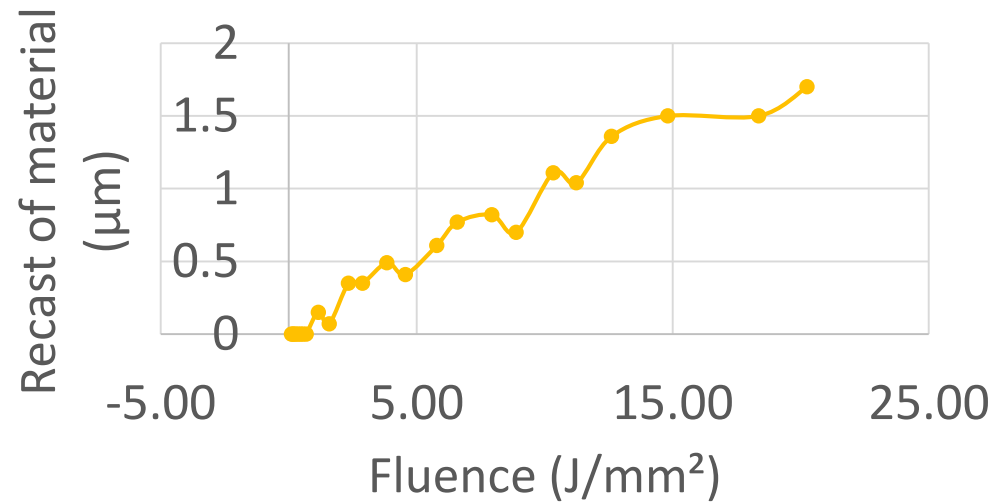
WP2

Process Development

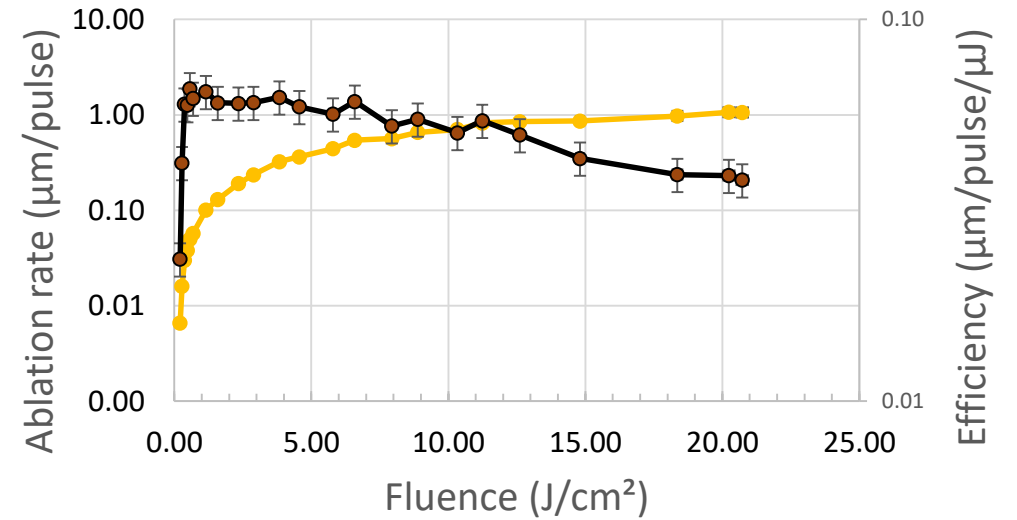
Work completed

T2.1 : Fundamental process development 3D Si processing :

Edge burr



Ablation and efficiency - 1D



WP2

Process Development

During the next 6 months the volumic ablation rate will be investigated.

The critical energy density determined allows to give an approximation of the corresponding focal length.

Input beam diameter = ~15mm

Laser power 500 W – 1000 W @1MHz

Power (W)	Pulse energy (mJ)	Pulse energy -20% losses (mJ)	Focal length (mm)	Max. Energy density (J/cm ²)	Optical Spot Diameter (μm)
500	0,5	0,4	500	21	50
1000	1	0,8	500	42	50
500	0,5	0,4	1000	5	100
1000	1	0,8	1000	10	100

Next 6 months

During the next 6 months more experiments will be carried out in order to develop the processes requested (high speed ablation rate, drilling, edge steepness, ...)



WP6

Thin-disk Multi-pass Booster

Work completed

No work has been carried out during so far.

Next 6 months

T6.1: Definition of interfaces : highlight mismatches in interfaces.

Exchange with the partners in order to propose solutions and/or modifications.

Item	M1	M2	M3	M4	M5	M6	M7	M8	M9	M10	M11	M12
WP6- System development	[Green bar]		[Green bar]									
T6.1 Definition of interfaces												D6.1
T6.2 Definition of laser & optics sizes; optics specifications (incl. fibre)												
T6.3 Development of the interfaces												
T6.4 System layout and build-up												
T6.5 Integration of laser and optics												
T6.6 Test and evaluation												



WP6

Thin-disk Multi-pass Booster

Next 6 months



WP8

Dissemination & Exploitation (partner activities)

What dissemination activities has your organisation taken to promote the Hiperdias project?

Please list here and you may include images/photos etc.



UNIERSITÄT STUTTGART
(USTUTT), Institut für
Strahlwerkzeuge (IFSW)
(WP2, 4, 5 & 7)



WP2

Process Development

Work not yet started for USTUTT

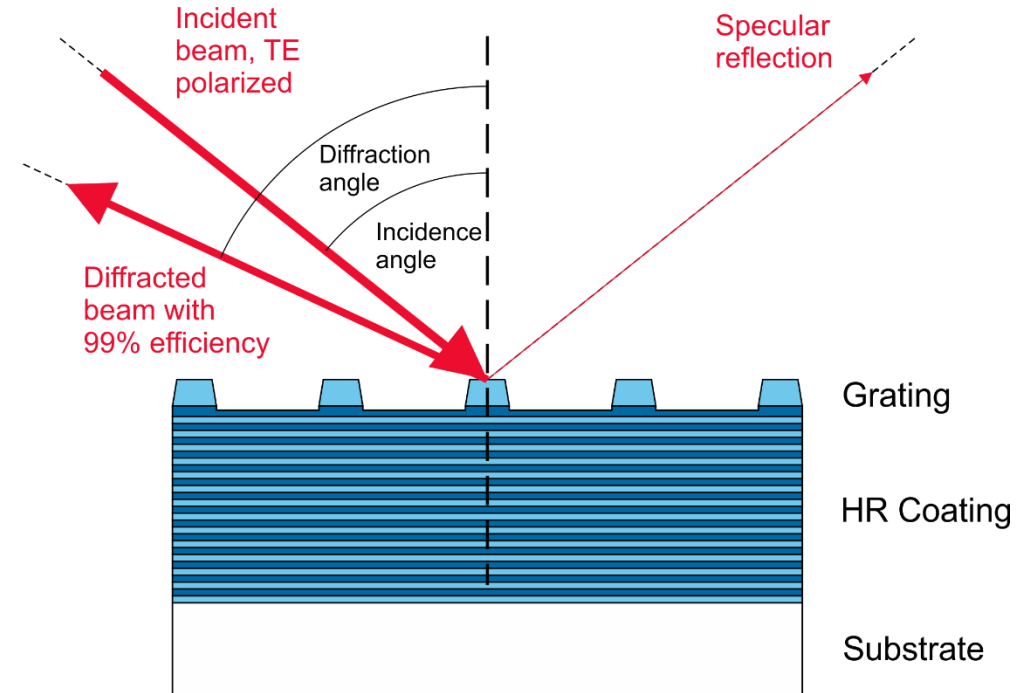


WP4

Photonic components for pre and post pulse conditioning

Task 4.1: Design of grating compressors

- Target parameters (defined together with AMP and AMO)
 - Period = **610 nm (1640 l/mm)**
 - AOI=51.4° i.e. Separation angle=13.7°
 - Diffraction efficiency>99% over >10nm spectral bandwidth around 1030 nm
 - Chosen material for dielectric layers: **Ta₂O₅/SiO₂** (maybe HfO₂/SiO₂ at later stage)
 - designs were evaluated for 3 different suppliers (providing layers with slightly different **refractive indices**)

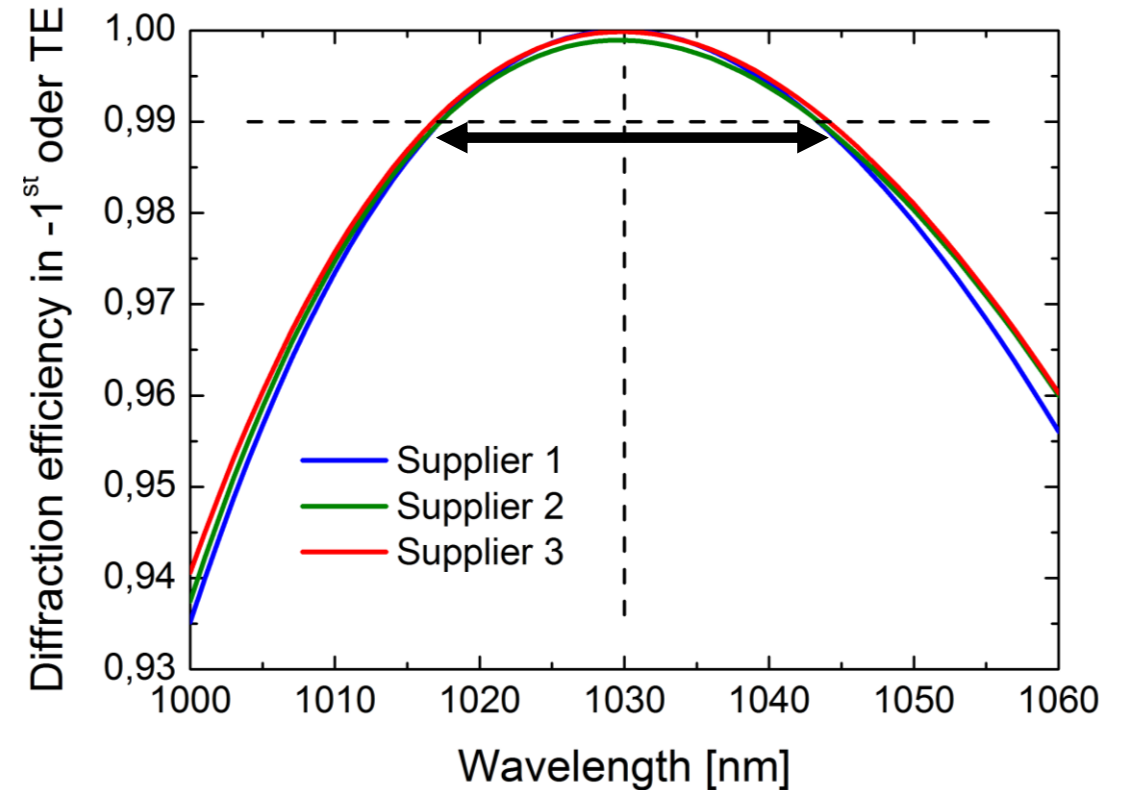
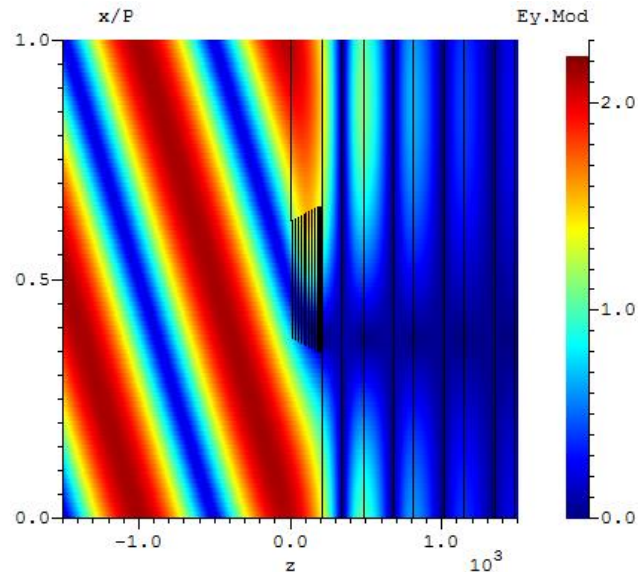


WP4

Photonic components for pre and post pulse conditioning

Task 4.1: Design of grating compressors (due month 6, completed)

- Simulation results: Calculated Diffraction efficiency and LIDT
- → DE (-1st) >99% over >20 nm around 1030nm
- → LIDT* : 0.35 – 0.5 J/cm²



*Gallais et.al, APPLIED OPTICS / Vol. 53, No. 4 / 1 February 2014

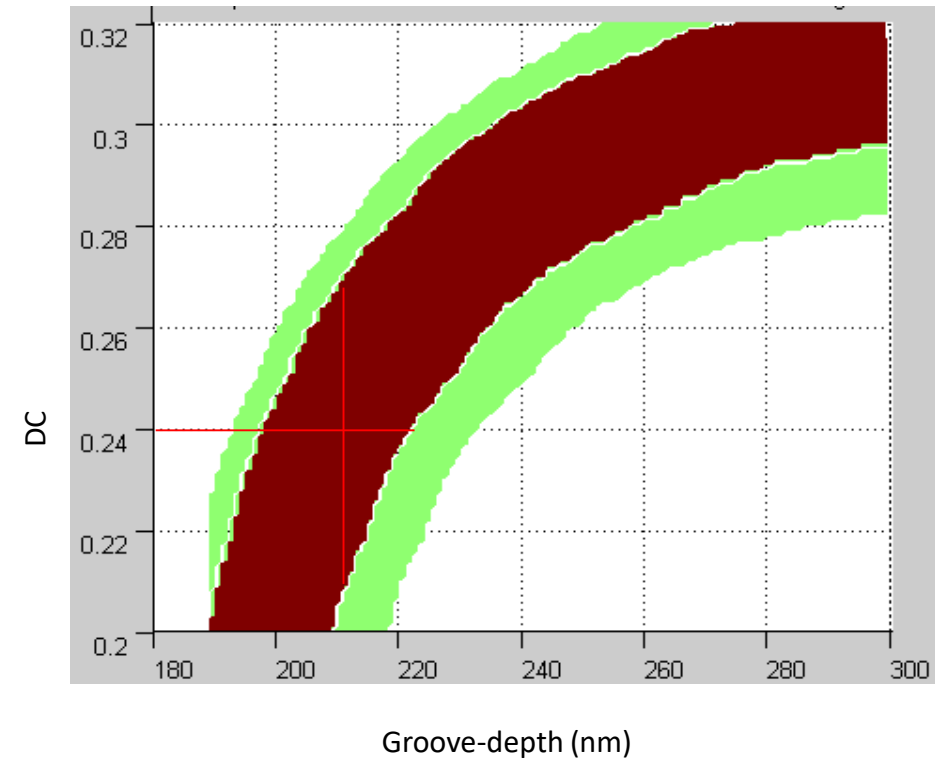


WP4

Photonic components for pre and post pulse conditioning

Task 4.1: Design of grating compressors

- *Tolerances analysis: Calculated Diffraction efficiency and LIDT*
- → *Groove depth = 210 nm (+/- 10-20 nm for a fixed DC)*
- → *Duty-cycle = 24% (+/- 2-3%, for a fixed groove depth)*
- ***Parameters were communicated to AMO for the production of the gratings***



WP4

Photonic components for pre and post pulse conditioning

Next 6 months

- *Task 4.2: Optical characterization of the fabricated gratings by AMO: measurement of diffraction efficiency over a spectral bandwidth of >20 nm around 1030 nm*
- *Design optimization (Task 4.1): design iteration taking into account the measured diffraction efficiency in order to identify the cause of deviations (in case some) from initial design.*
- *LIDT measurements (collaboration with an external partner)*



WP5

Thin-disk Multi-pass Booster

- **Task 5.1 (D 5.1) Design of the multipass amplifier (due month 6, completed)**

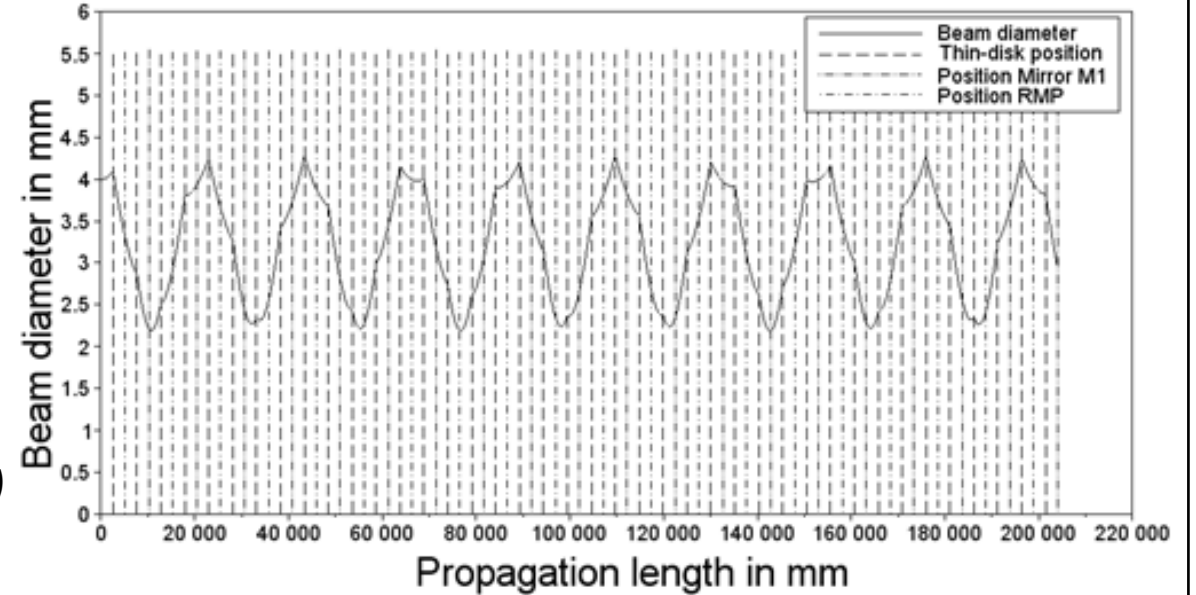
- *Design should be suitable for:*

- ❖ *Seed (Satsuma) with 50 W, 1.25 MHz, 300 fs (D3.1)*

- ➔ *Amplification to 500 W, 1.25 MHz, sub-500 fs*

- ❖ *Seed Satsuma with 200 W, 1.25 MHz, sub-500 fs (D3.3)*

- ➔ *Amplification to 1000 W, 1.25 MHz, sub-1000 fs*



WP5

Thin-disk Multi-pass Booster

- **Task 5.1 (D 5.1) Design of the multipass amplifier (due month 6, completed)**
 - *Beam propagation simulated (scheme allows adaption if needed)*
 - *Amplification **factor of ≥ 10** needed!!!*
 - ➔ *We decided (based on previous experiments) on a concept with **80 mirrors** in an array*
 - ➔ *It allows 80 reflections on the disk in double-pass and **40 reflections in single-pass through the amplifier***
 - ➔ *Single-pass will be needed to be able to pick single pulses (based on IP USTUTT proposed in the project RAZipol)*

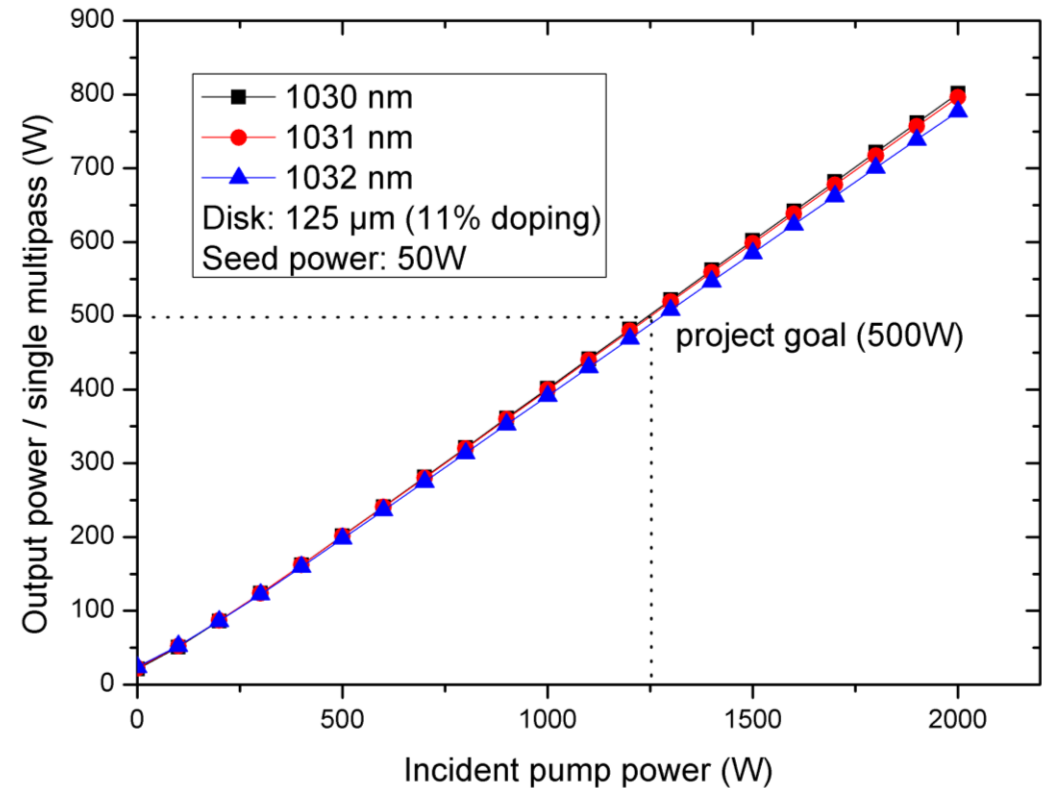


WP5

Thin-disk Multi-pass Booster

• **Task 5.1 (D 5.1) Design of the multipass amplifier (due month 6, completed)**

- *First (simplified) Simulation results of amplification*
- *Slope efficiency ~ 40%*
- ➔ *Challenge: Broad spectrum (6-8 nm) of fs pulses and center wavelength adaption of Satsuma to 1030 nm may influence the amplification process*



WP5

Thin-disk Multi-pass Booster

- ***New experimental tests (within project Razipol) on amplification of fs pulses***

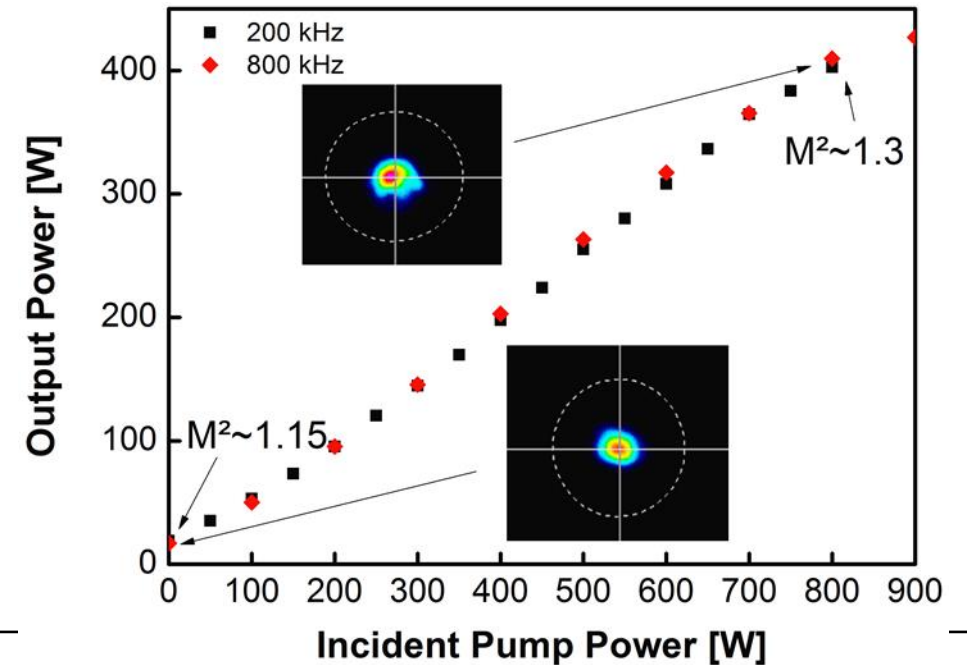
- *40 W Seed power, 200/800 kHz, 805 fs (loaned seed)*
- *60 passes over the disk (different disk than disk planed in Hiperdias)*

➔ *400 W of output power, 885 fs, 200/800 kHz*

➔ *Amplification of broad fs pulses is possible*

➔ *We observe spectral broadening at high intensities*

➔ *Here, compression to **sub-200 fs** was possible*



WP5

Thin-disk Multi-pass Booster

Ongoing work and planned for the next months:***Task 5.2: Assembly & characterization of a Yb:YAG thin-disk multipass amplifier (Scheduled for M22)***

- *Several components already delivered*
- *Few more parts (optics, custom-designed mechanics and seed source) are still to be delivered*
- *Working on controls and safety of the amplifier*
- *Assembly of amplifier*
- *Measurements and characterization*

Task 5.3: Second and third harmonics generations (Scheduled for M20-M28):

- *Design and simulations have started*

Tasks 5.4: Integration of the Yb:YAG thin-disk multipass amplifier (not yet started)***Task 5.5: Demonstration of a 1kW, sub-1ps laser system (not yet start)***

WP7

Demonstrators

Work not yet started for USTUTT



Deliverables

Number	Deliverable title	Delivery date	Current status
D 4.1	Report on simulation of pulse compression gratings with diffraction efficiency $\geq 99\%$ over large spectral bandwidth (5-10 nm) around 1030 nm.	M4	Submitted
D 5.1	Design of multipass amplifier	M6	submitted
D 5.2	Thin-disk multipass amplifier with 500W, 1MHz, sub-500fs	M22	Not yet Submitted
D 5.3	Demonstration of 200W green and 100W UV laser beams at 1MHz and sub-500 fs pulse	M28	Not yet Submitted
D 5.4	Thin-disk multipass amplifier with 1000W, ≥ 1 MHz, sub-1ps	M38	Not yet Submitted



Milestones			
Number	Milestone title	Estimated date	Current status
M 4.1	First design, high efficient grating mirrors	M3	Achieved
M 4.4	Fully optical characterization of grating mirror regarding diffraction efficiency and LIDT	M12	Not yet achieved
M 4.8	Demonstration of optimized grating mirrors, 99% diffraction efficiency	M18	Not yet achieved
M 5.1	Yb:YAG thin-disk multipass amplifier delivering 500W at a sub-500fs pulse duration and a repetition rate $\geq 1\text{MHz}$.	M22	Not yet achieved
M 5.2	Demonstration of a 200W green and 100W UV laser beams at 1MHz and sub-500 fs pulse.	M28	Not yet achieved
M 5.3	Yb:YAG thin-disk multipass amplifier delivering 1000W at a sub-1ps pulse duration and a repetition rate $\geq 1\text{MHz}$.	M38	Not yet achieved



Thank you for your attention



Contribution of XLIM-GPPMM



F. Gérôme, J. M. Blondy, and F. Benabid

GPPMM group, Xlim Research Institute, CNRS UMR 7252, University of Limoges, Limoges, France



WP4

Photonic components for pre and post pulse conditioning

D4.5 task / Objective : Conception and fabrication of HC-PCF with improved PER (> 20 dB) at 1 μm



WP4

Photonic components for pre and post pulse conditioning

*Work completed**Two designs investigated (simulations and fabrications):*

- 1. Hypocycloid-core Kagomé IC HC-PCF*
- 2. IC HC-PCF with a single ring of tubular lattice cladding*



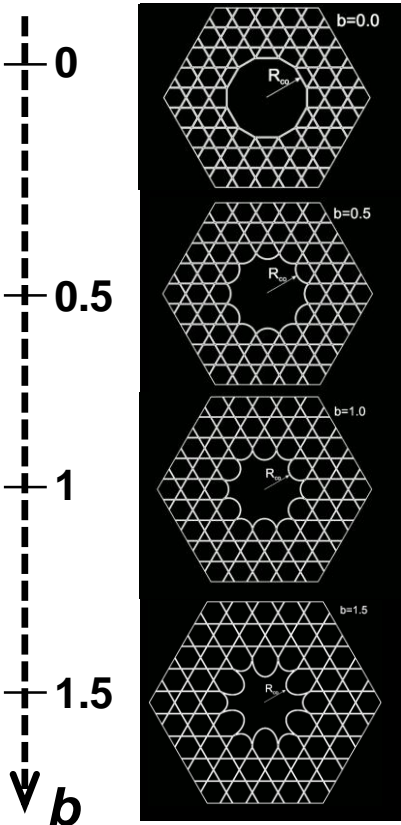
WP4

Photonic components for pre and post pulse conditioning

B. Debord et al. Opt. Express **21**, 28597-28608 (2013)

M. Alharbi et al. Opt. Express **21**, 28609-28616 (2013)

1. Hypocycloid-core Kagomé IC HC-PCF



1

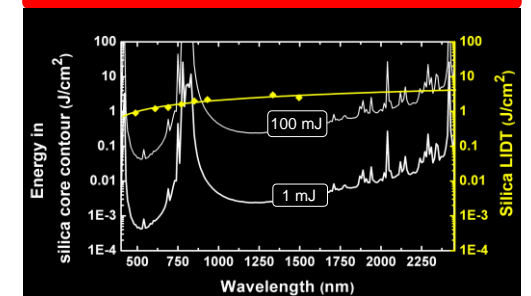
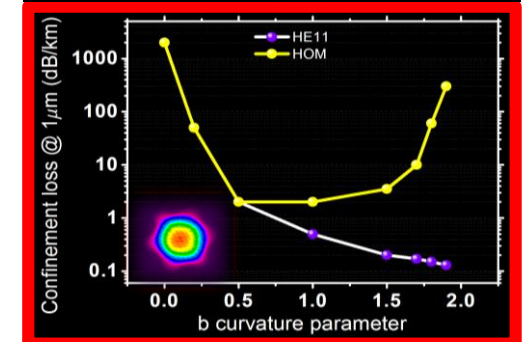
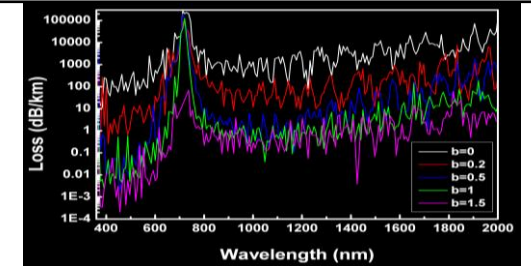
**Strong propagation loss decrease
(orders of magnitude)**

2

**Single mode operation
with high PER
(Gaussian-like mode)**

3

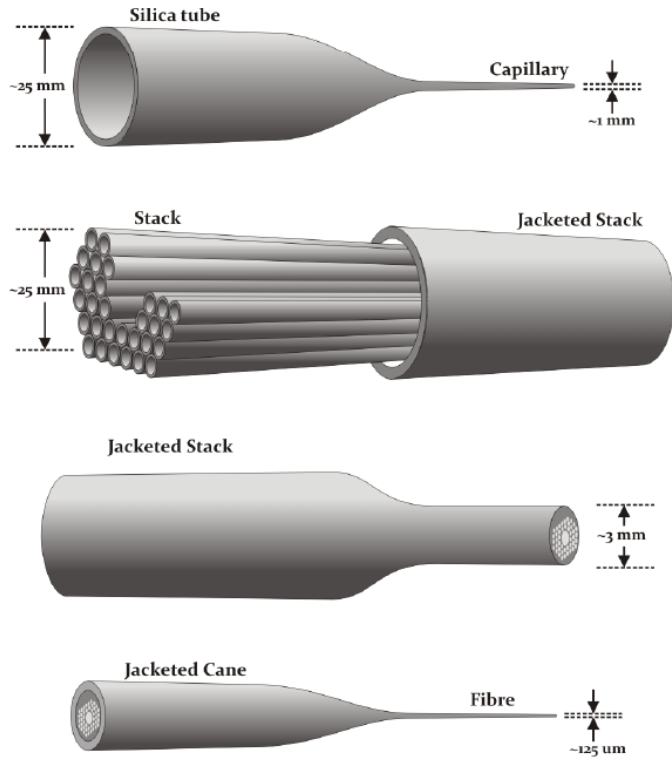
**Decrease of power overlap with
silica surround to a ppm level
(10000 times lower than PBG)**



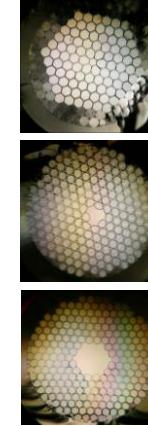
WP4

Photonic components for pre and post pulse conditioning

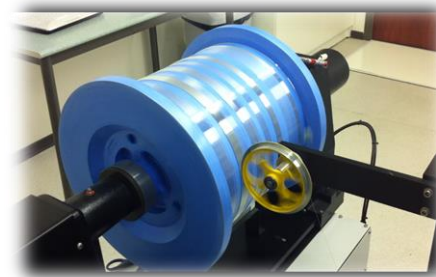
1. Hypocycloid-core Kagomé IC HC-PCF



Stack and draw process



State-of-the-art drawing towers

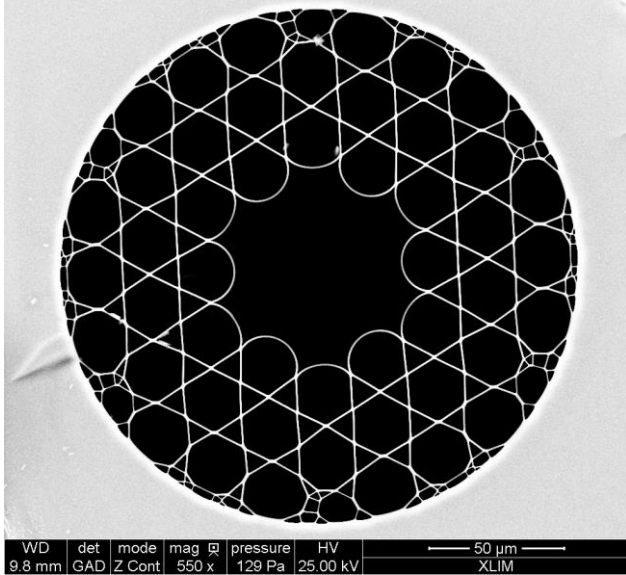


WP4

Photonic components for pre and post pulse conditioning

B. Debord et al. submitted to Photonic West (2017)

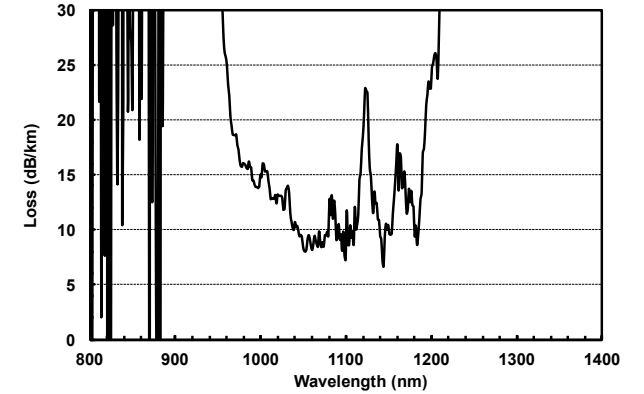
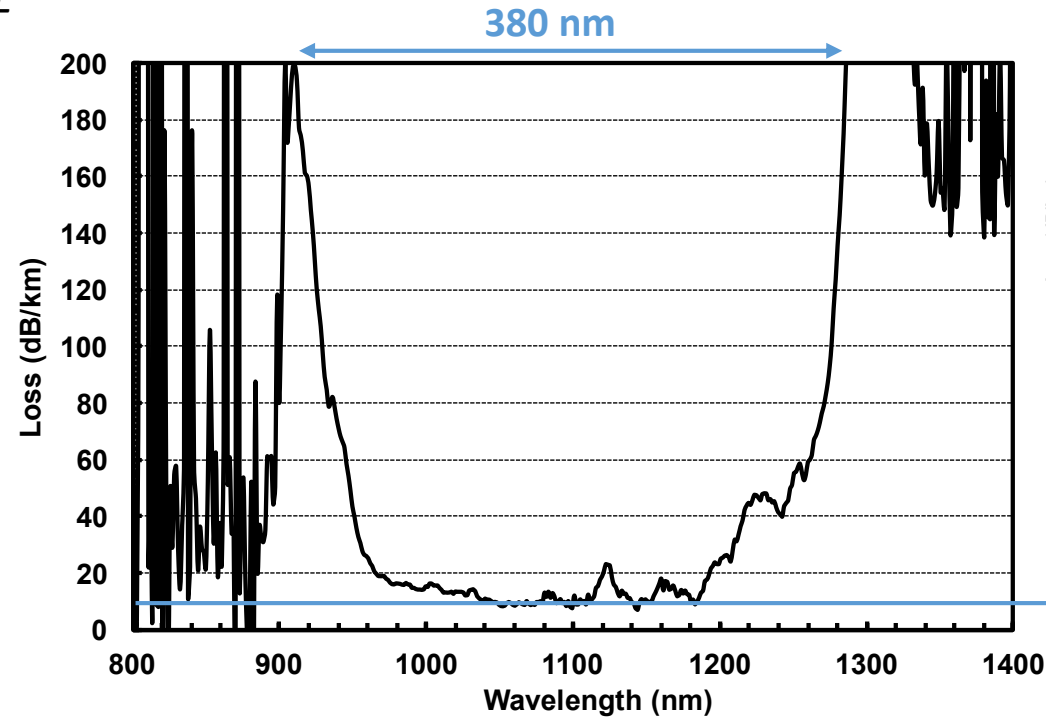
1. Hypocycloid-core Kagomé IC HC-PCF



Core Diameter..... 60-72 μm

MFD..... 42 μm

b..... 0.9



Min loss: 8.5 dB/km *

* Cut-back done between 106 m and 3.8 m

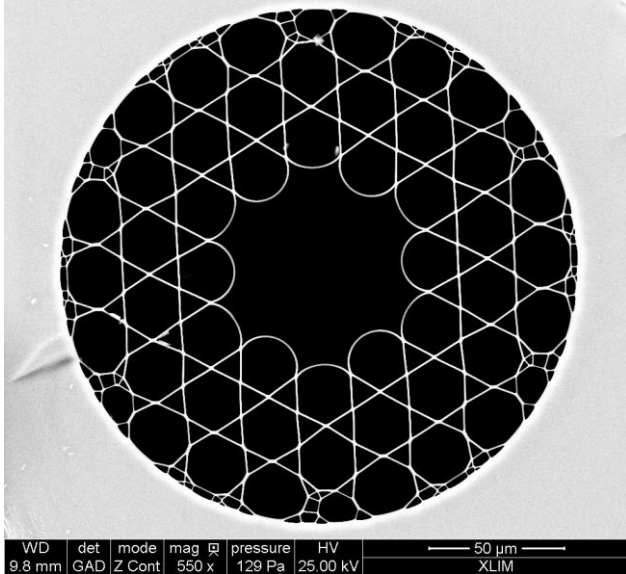


WP4

Photonic components for pre and post pulse conditioning

B. Debord et al. submitted to Photonic West (2017)

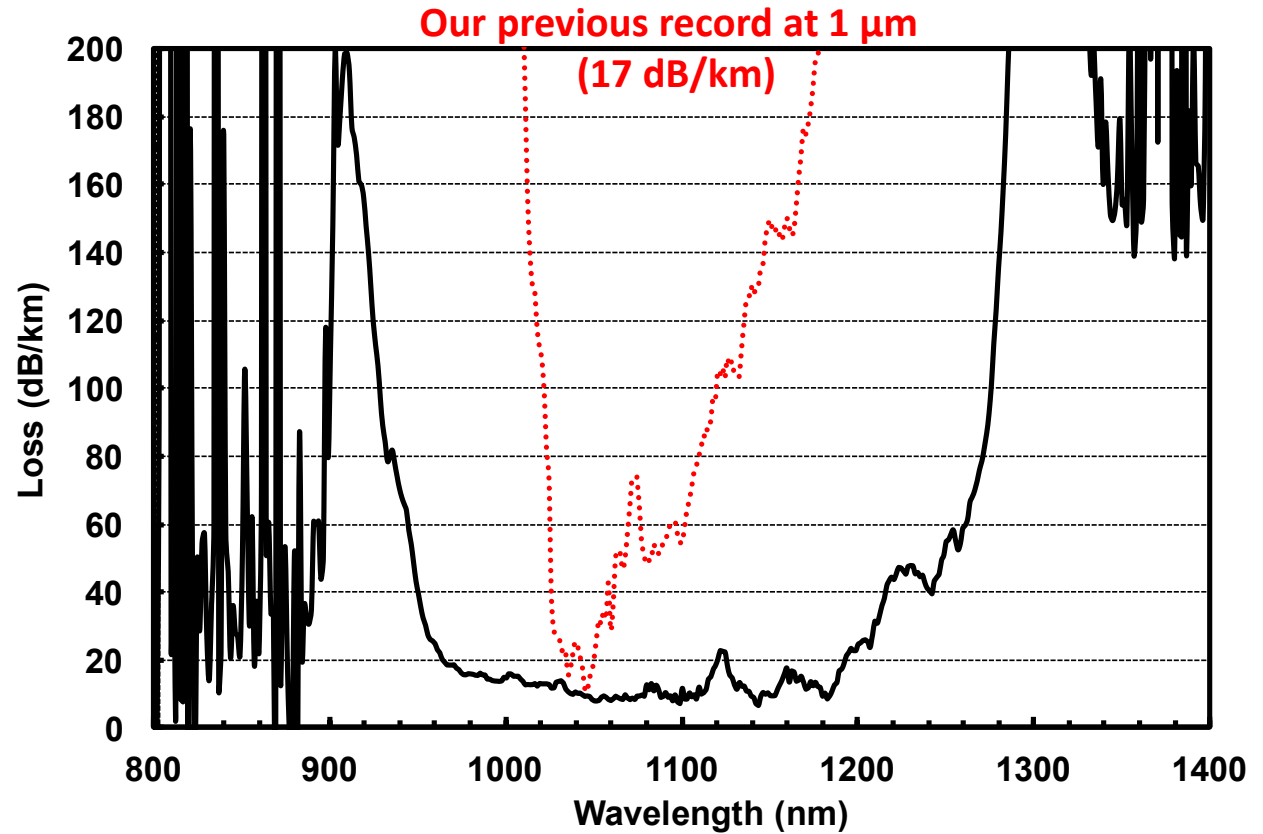
1. Hypocycloid-core Kagomé IC HC-PCF



Core Diameter..... 60-72 μm

MFD..... 42 μm

b..... 0.9

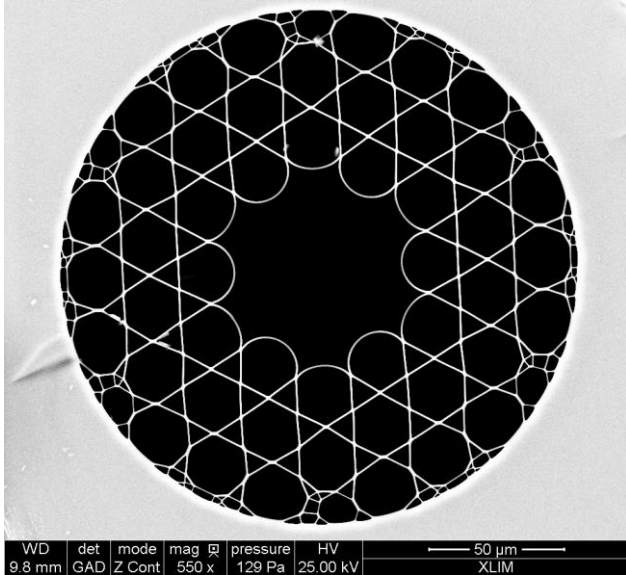


WP4

Photonic components for pre and post pulse conditioning

B. Debord et al. submitted to Photonic West (2017)

1. Hypocycloid-core Kagomé IC HC-PCF



« Modal properties (S^2 and PER) under progress »

See Next 6 months plan

Core Diameter..... 60-72 μm

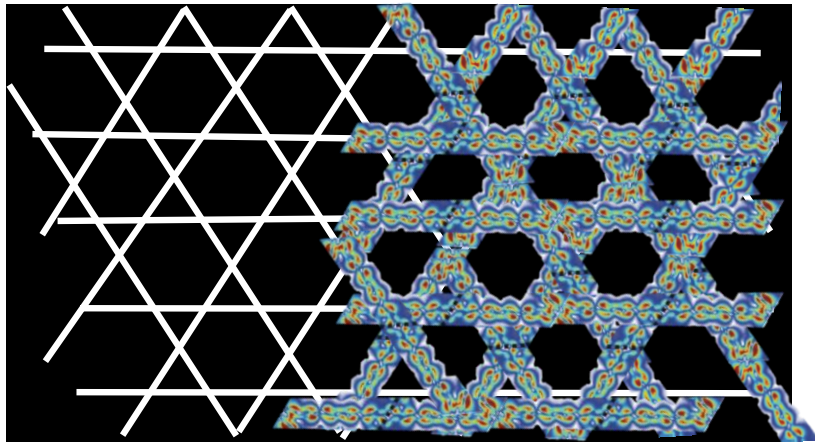
MFD..... 42 μm

***b*..... 0.9**

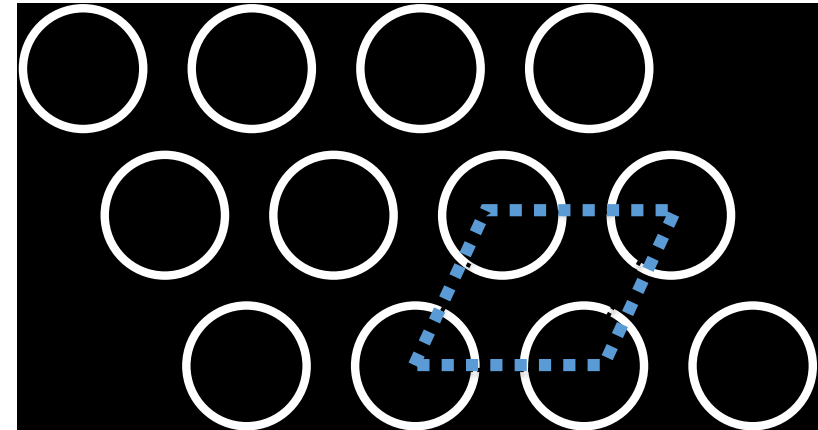


WP4

Photonic components for pre and post pulse conditioning

*2. IC HC-PCF with a single ring of tubular lattice cladding***↘ Kagome lattice**

- ✓ Long silica struts
- ✓ Typical azimuthal number $m \approx 200$

↘ Tubular lattice

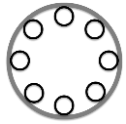
- ✓ No connecting nodes



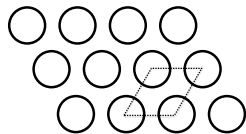
WP4 Photonic components for pre and post pulse conditioning

2. IC HC-PCF with a single ring of tubular lattice cladding

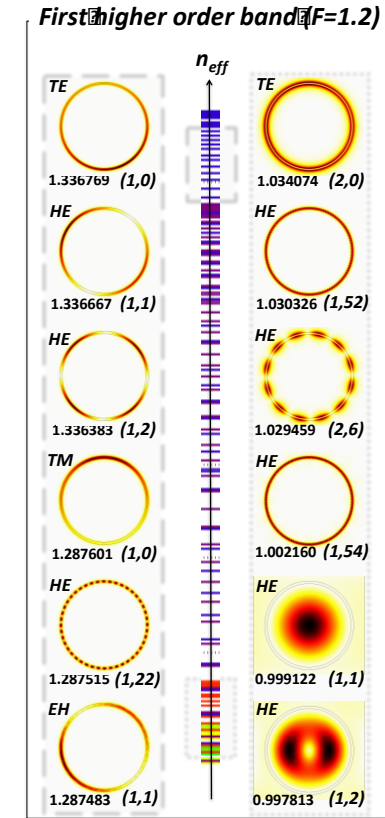
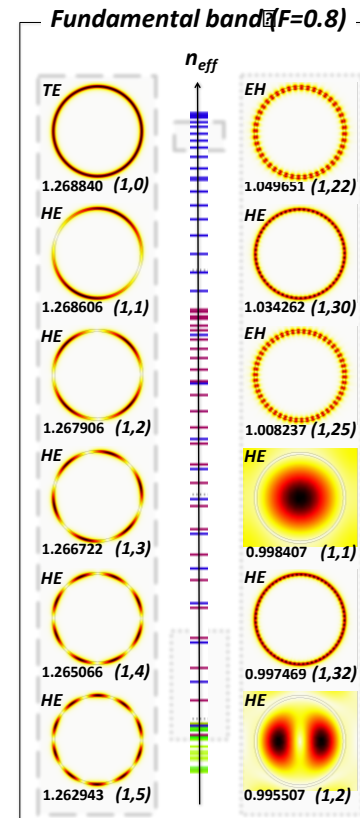
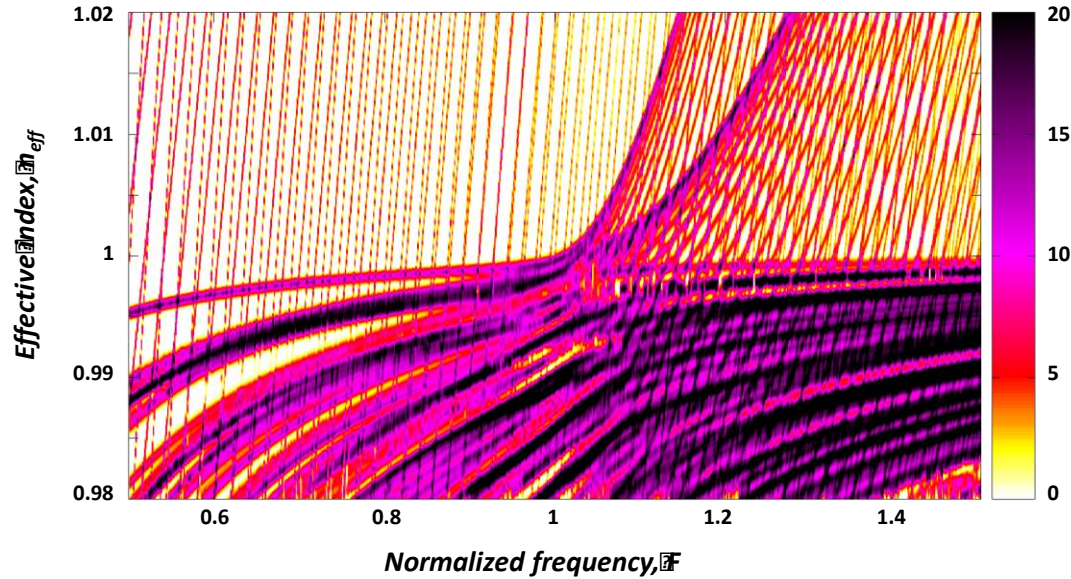
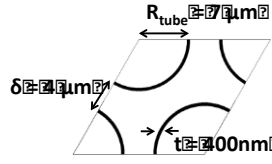
Single-ring tubular lattice HC-PCF



Tubular lattice








Unit cell



WP4 Photonic components for pre and post pulse conditioning

2. IC HC-PCF with a single ring of tubular lattice cladding

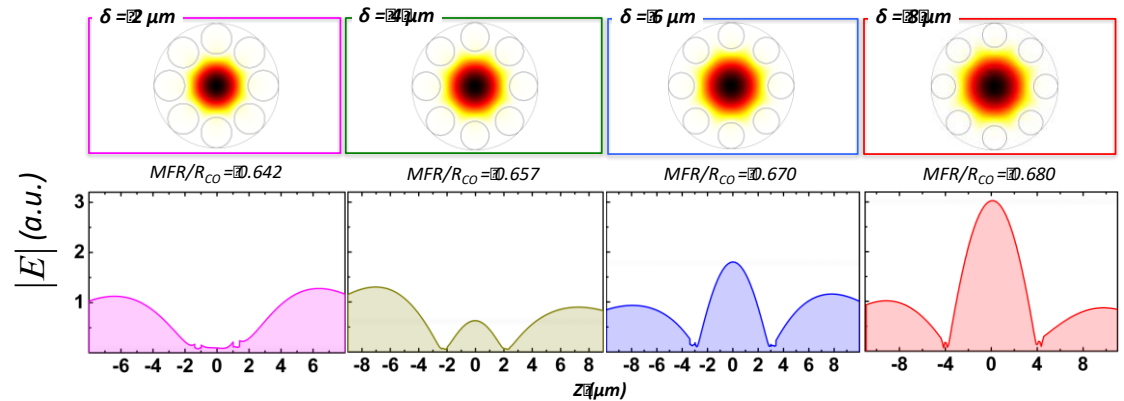
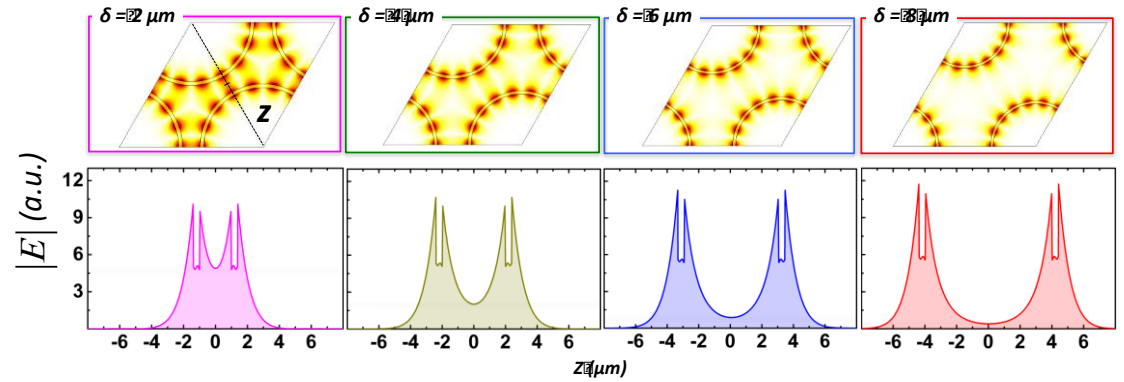
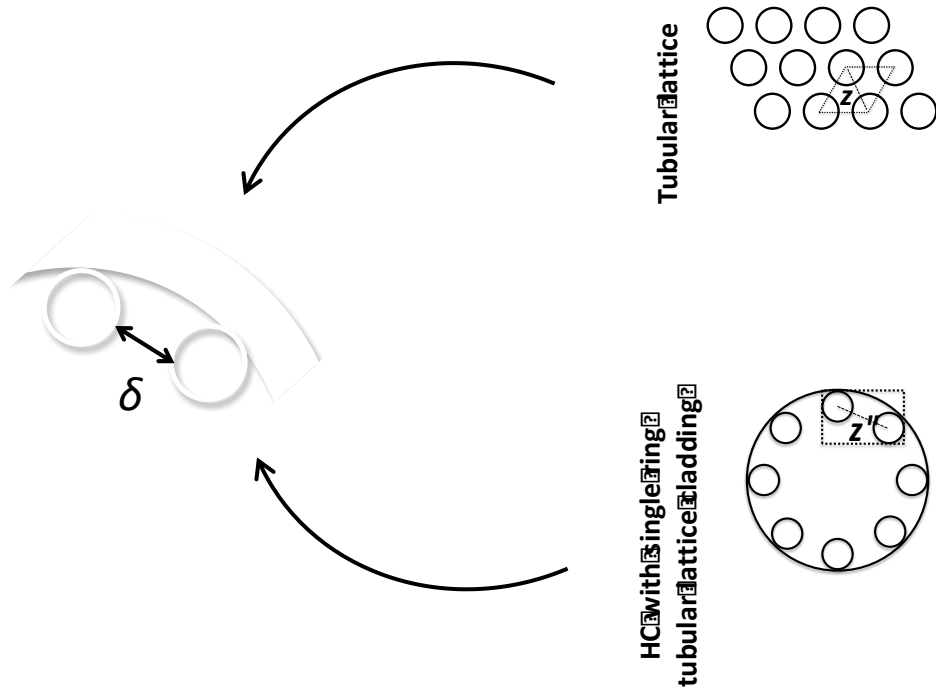
		Geometrical parameters	Scaling laws	Limitations
Core	Core radius R_{co}		Large $R_{co} \nearrow$ IC (loss $\sim R_{co}^4$)	Ratio between R_{co} and R_t for single mode operation
	Tube radius R_t		$R_t \nearrow$ IC	- If too large: Coupling between core and tube mode - Keeping the circular shape of the tube
Cladding	Strut thickness t		Thin struts \nearrow IC	Induced surface roughness
	Gap between two tubes δ		- Large: avoid mode coupling between 2 adjacent tubes	- If too large: Core mode not sufficiently confined
	Number of tubes N			



WP4

Photonic components for pre and post pulse conditioning

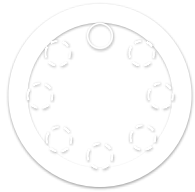
2. IC HC-PCF with a single ring of tubular lattice cladding



WP4

Photonic components for pre and post pulse conditioning

2. IC HC-PCF with a single ring of tubular lattice cladding



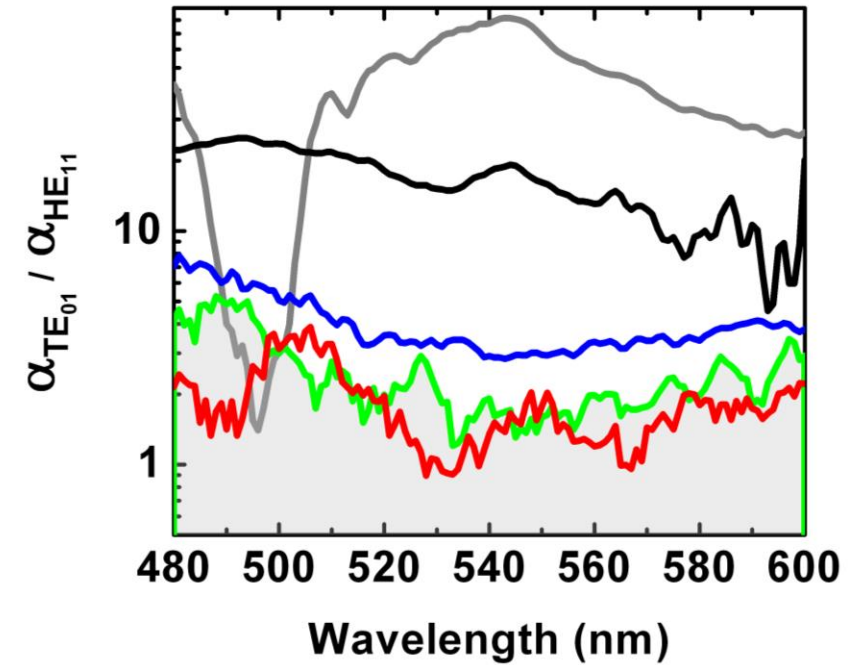
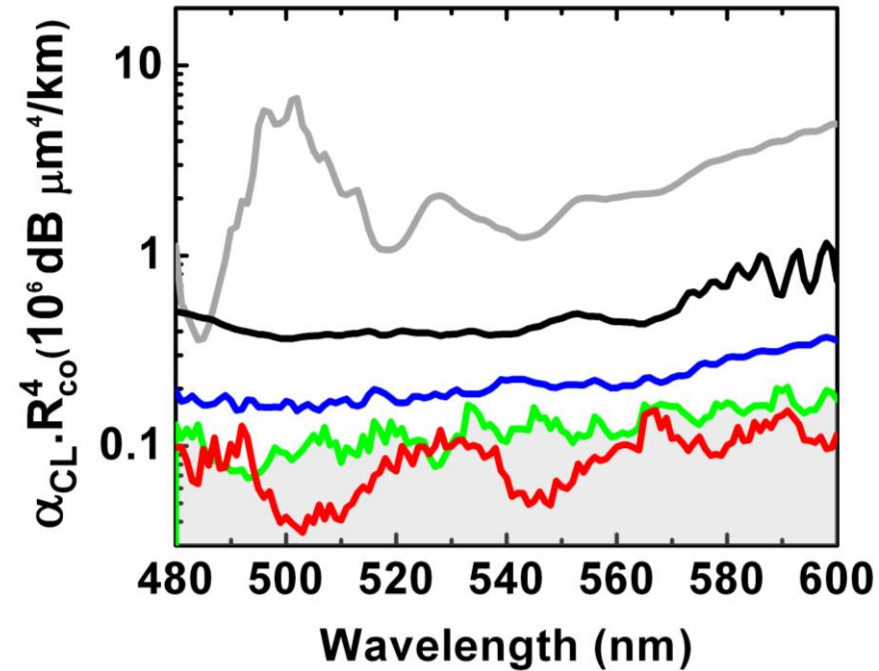
— $N=5$

— $N=6$

— $N=7$

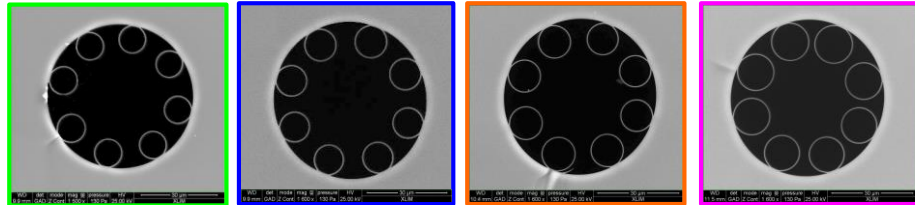
— $N=8$

— $N=9$

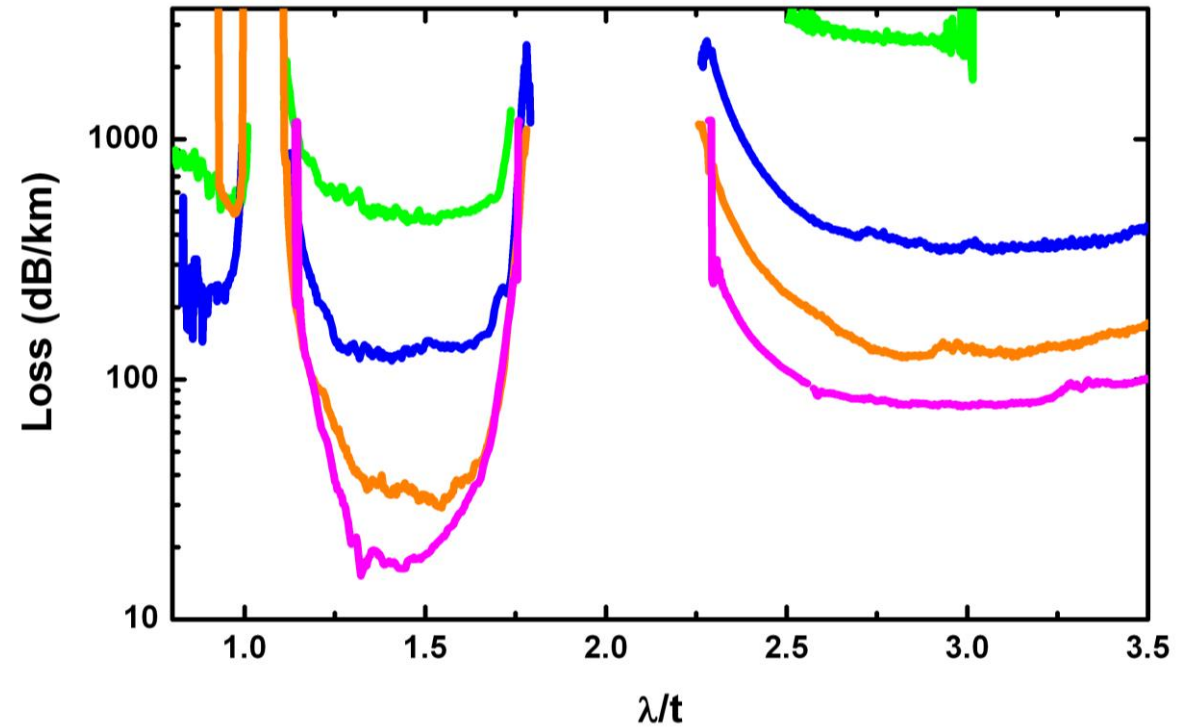


WP4 Photonic components for pre and post pulse conditioning

2. IC HC-PCF with a single ring of tubular lattice cladding

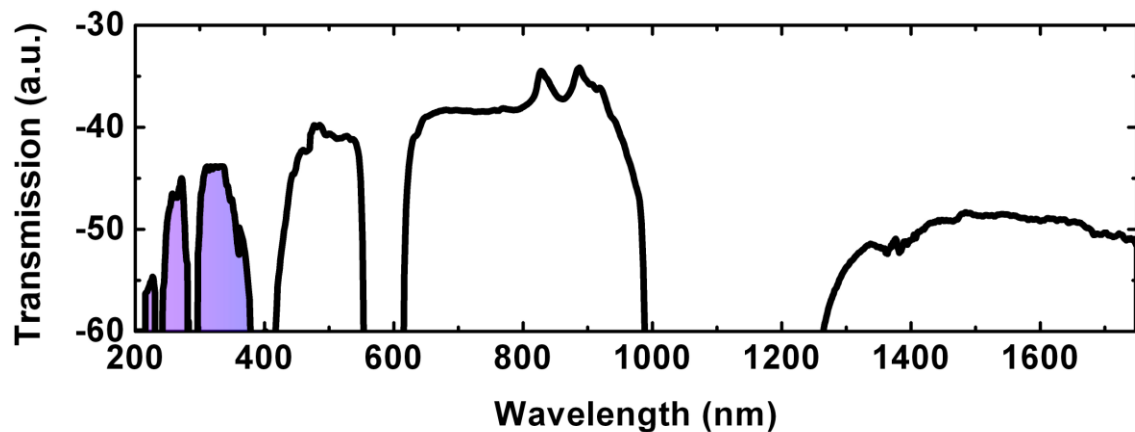
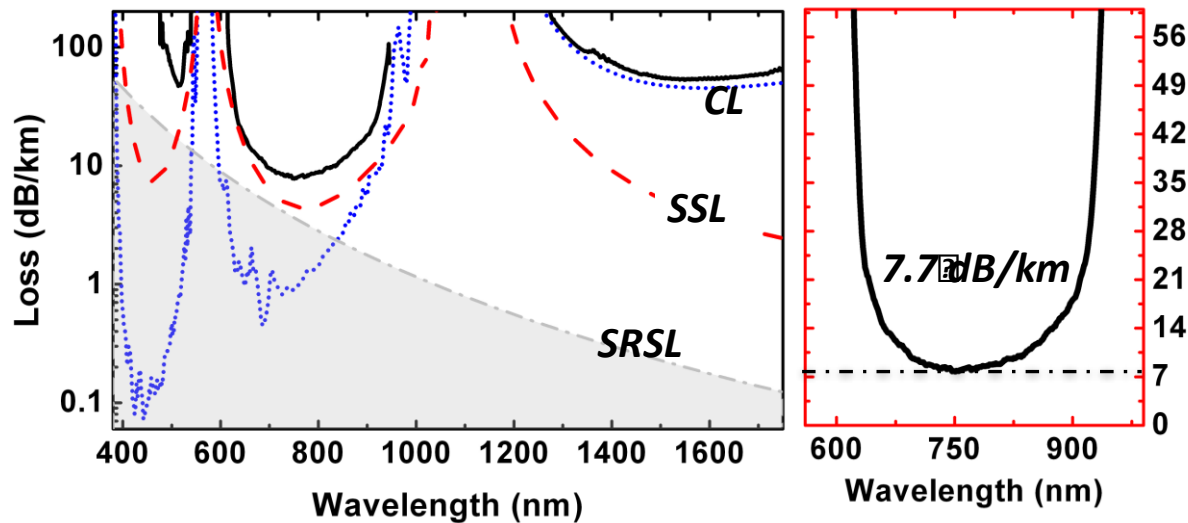


δ [μm]	8	5	3.7	2.7
R_t [μm]	5.1	5.54	5.88	6.15
t [nm]	580	500	465	415
R_c [μm]	18.5	16.5	15.25	13.75

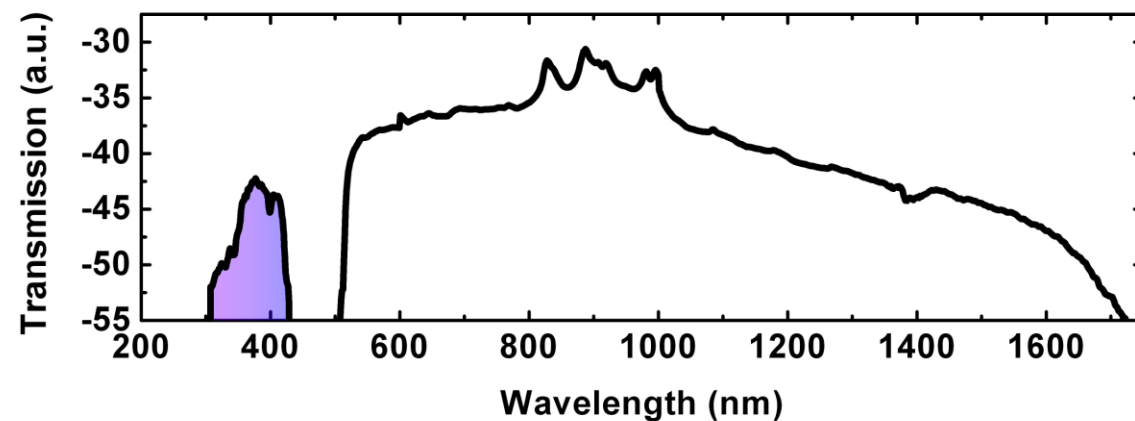
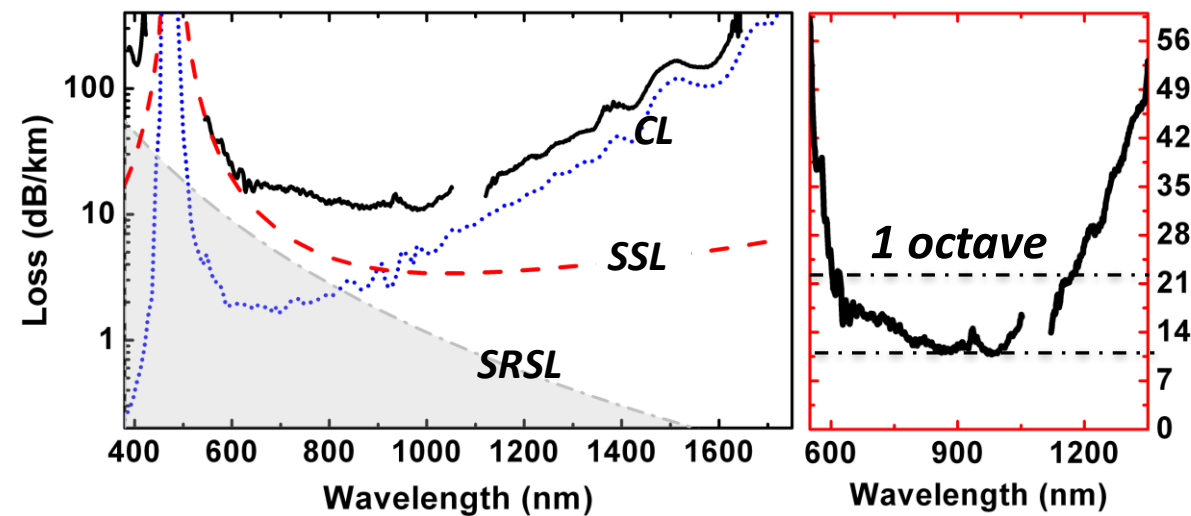


Optimized Fiber #1

B. Debord et al., CLEO US postdeadline, JTh4C.8 (2016)



Optimized Fiber #2



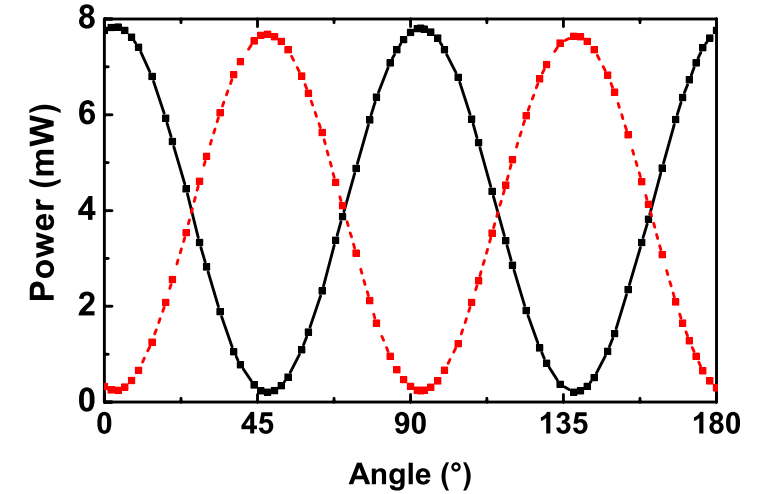
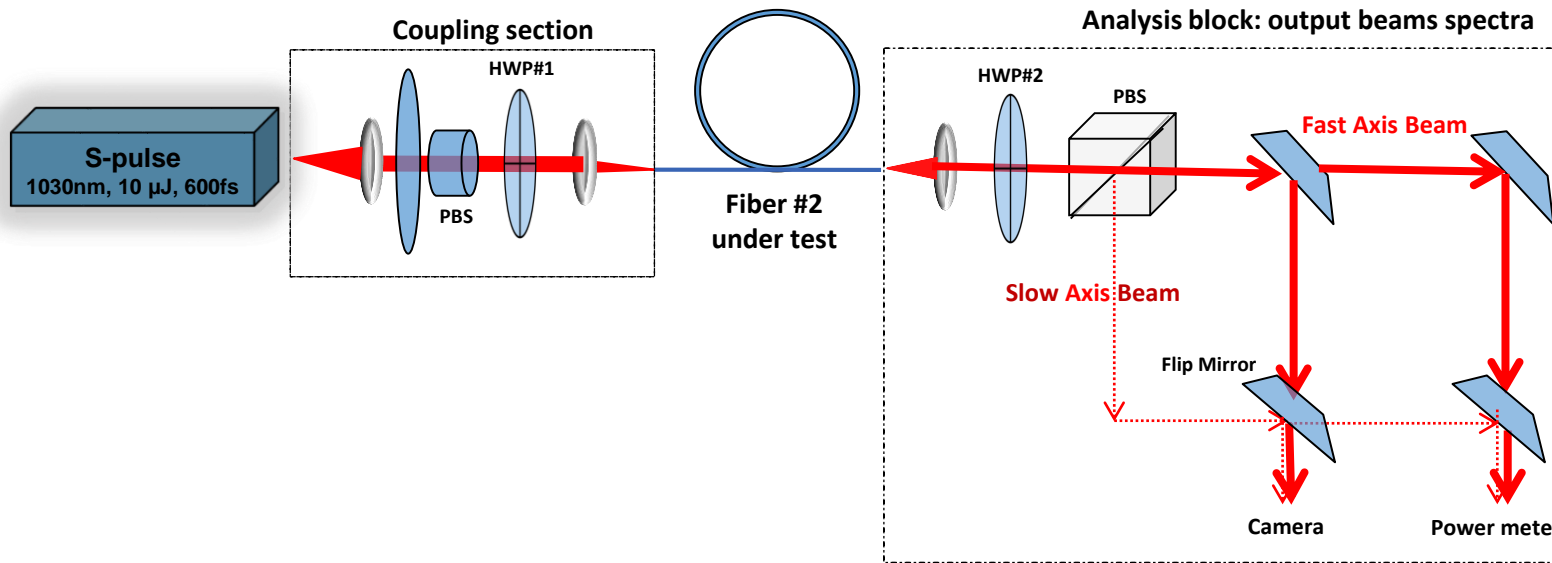
WP4

Photonic components for pre and post pulse conditioning

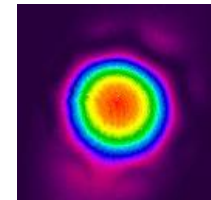
B. Debord *et al.*, submitted to Optica (2016)

2. IC HC-PCF with a single ring of tubular lattice cladding

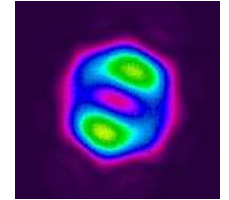
2.1. PER measurement



Maximum power



Minimum power

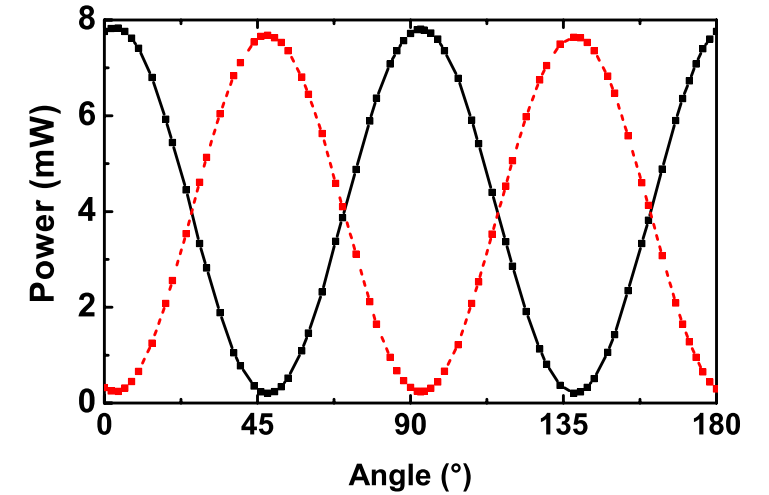
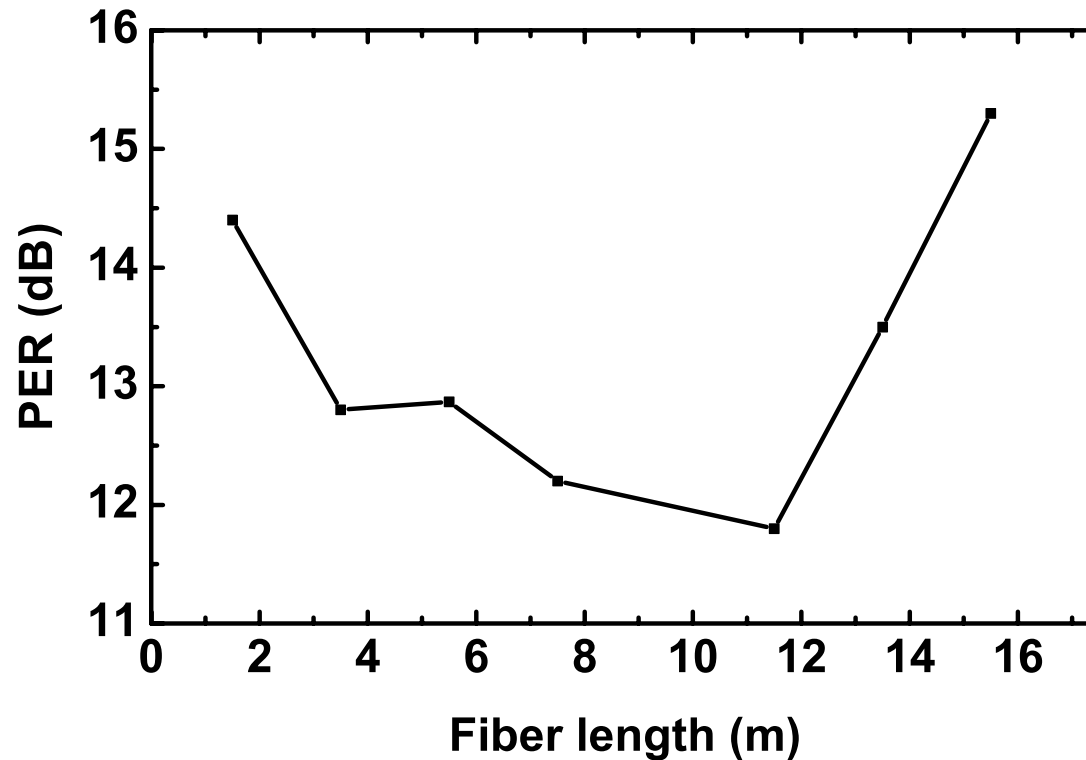


WP4

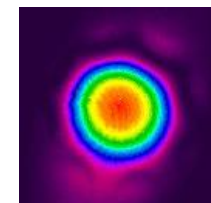
Photonic components for pre and post pulse conditioning

B. Debord *et al.*, submitted to Optica (2016)

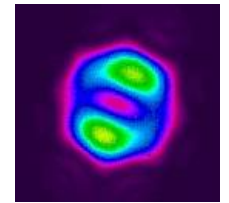
2. IC HC-PCF with a single ring of tubular lattice cladding



Maximum power



Minimum power



WP4

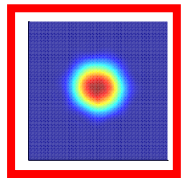
Photonic components for pre and post pulse conditioning

B. Debord et al., submitted to Optica (2016)

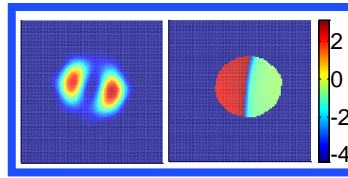
2. IC HC-PCF with a single ring of tubular lattice cladding

2.2. S^2 measurement (collaboration*)

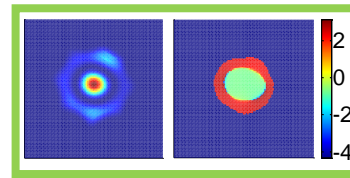
Fundamental mode



First HOM

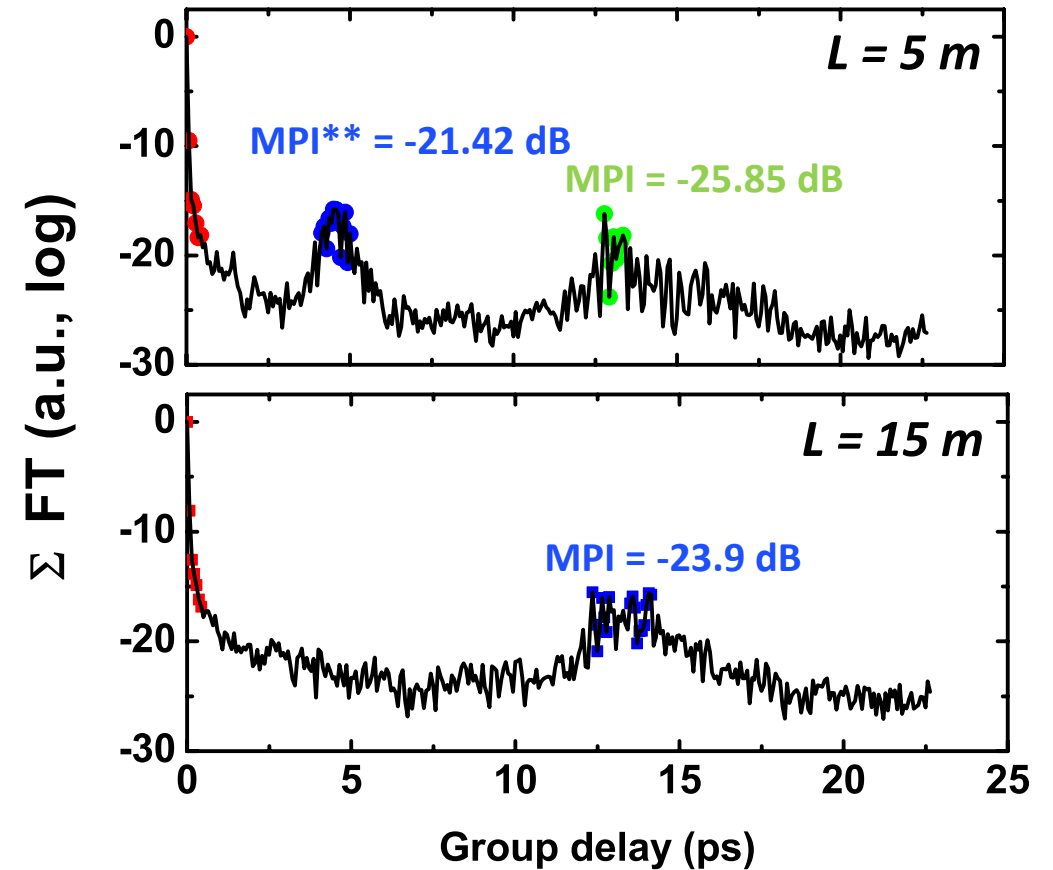


Second HOM



* $R_b = 35 \text{ cm} / \lambda: 1010\text{-}1070 \text{ nm}$ (40 pm)

** MPI = Multi-path interference



WP4

Photonic components for pre and post pulse conditioning

Next 6 months

- 1. Investigation of the modal properties of the hypocycloid-core Kagomé IC HC-PCF*
- 2. Test of energy handling capabilities of the IC HC-PCF with a single ring of tubular lattice cladding*
- 3. Start to set a home-made S^2 set-up*
- 4. Continue on the fabrication of IC HC-PCF*



WP8

Dissemination & Exploitation (partner activities)

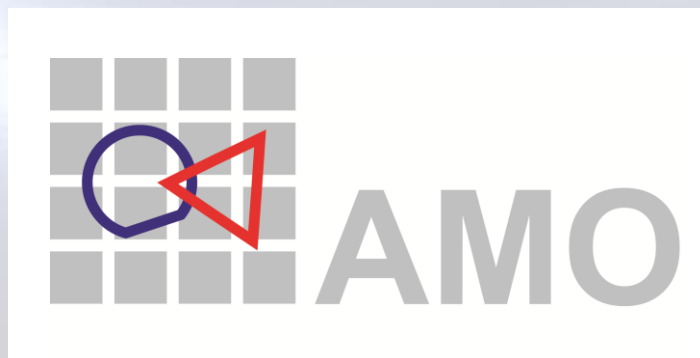
Peer review journal:

1. DEBORD B., AMSANPALLY A., CHAFER M., BAZ A., MAUREL M., BLONDY J-M., HUGONNOT, E., SCOL, F., VINCETTI L., GEROME F., BENABID F.: « **Ultra-low transmission loss (7.7 dB/km @750 nm) inhibited-coupling guiding hollow-core photonic crystal fibers with a single ring of tubular lattice cladding** », *Optica*, submitted in september 2016.

Peer review international conference:

1. DEBORD B., AMSANPALLY A., CHAFER M., BAZ A., VINCETTI L., BLONDY J-M., GEROME F., BENABID F.: « **7.7 dB/km losses in inhibited coupling hollow-core photonic crystal fibers** », *CLEO US*, Postdeadline, JTh4C.8, San Jose, California, 5 - 10 June 2016.
2. BENABID F.: « **Hollow core photonic crystal fibre: Novel light guidance and myriad of gas-photonic applications**», *XXI Rinem*, invited talk, Parma, Italy, 12 - 14 September 2016.
3. DEBORD B., Maurel M., AMSANPALLY A., ADNAN M., BEAUDOU B., BLONDY J-M., VINCETTI L., GEROME F., BENABID F.: « **Ultra-low loss (8.5 dB/km @ Yb-laser region) inhibited-coupling Kagome HC-PCF for laser beam delivery applications** », *Photonic West 2017*, submitted.
4. Maurel M., GORSE A., BEAUDOU B., LEKIEFS Q., DEBORD B., GEROME F., BENABID F.: « **Kagome fiber based industrial laser beam delivery**», *Photonic West 2017*, submitted.

AMO GmbH



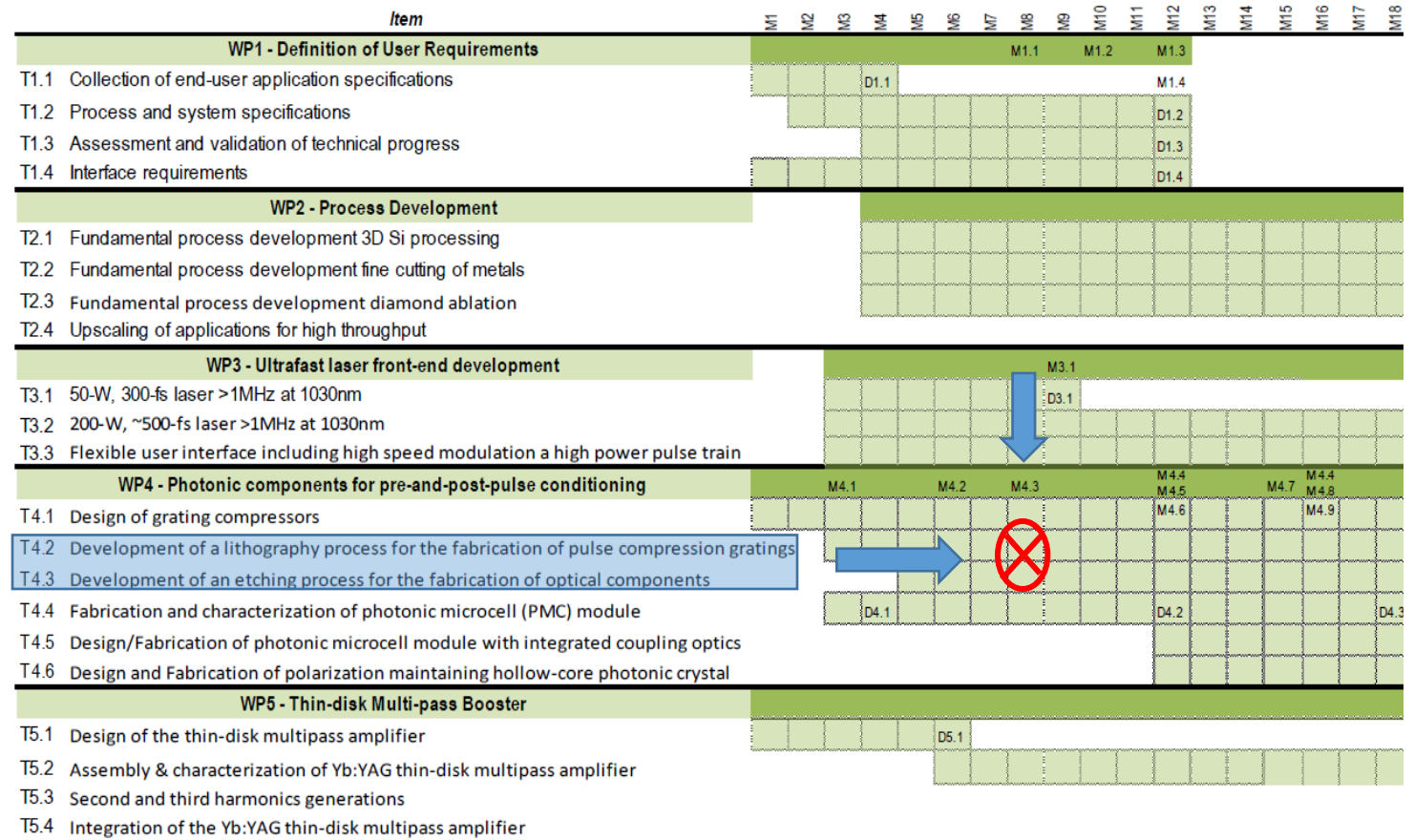
Michael Moeller



Our role:

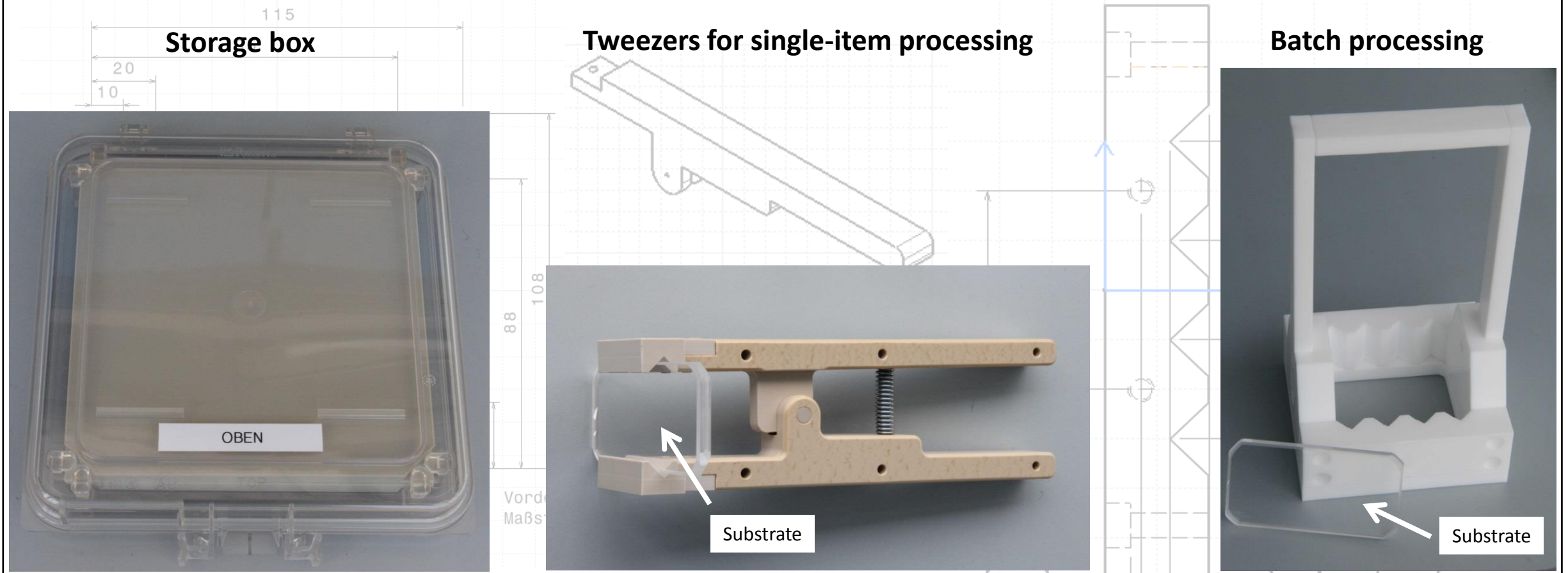
- AMO mainly active in WP4 (T4.2 and T4.3)
- Process development PC-grating fabrication

Gantt chart:



WP4

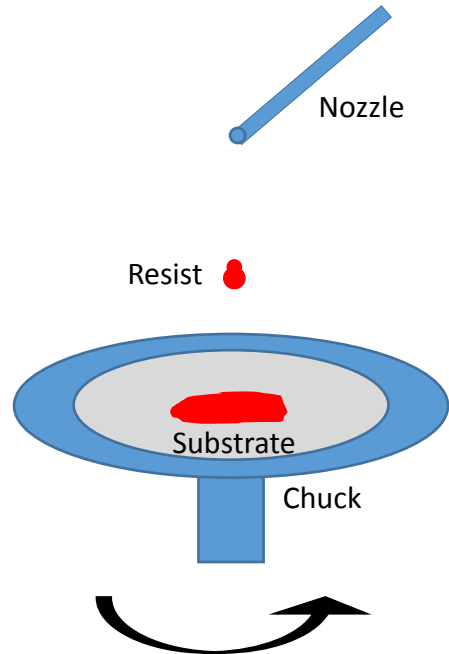
Photonic components for pre and post pulse conditioning
Processing equipment



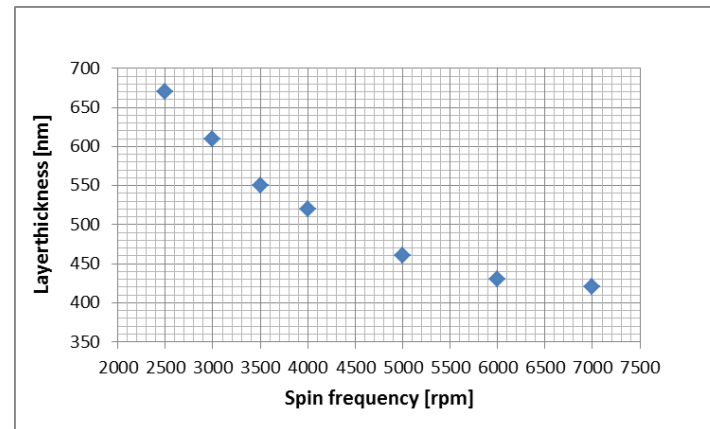
WP4

Photonic components for pre and post pulse conditioning
Modification spin coater Suess Microtec RCD8

Spin coating

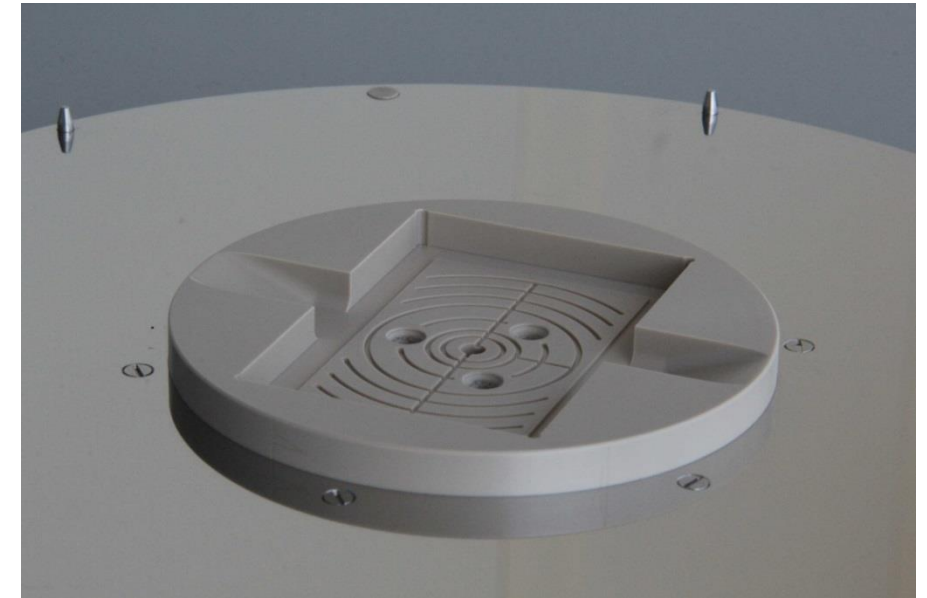


Spin curve



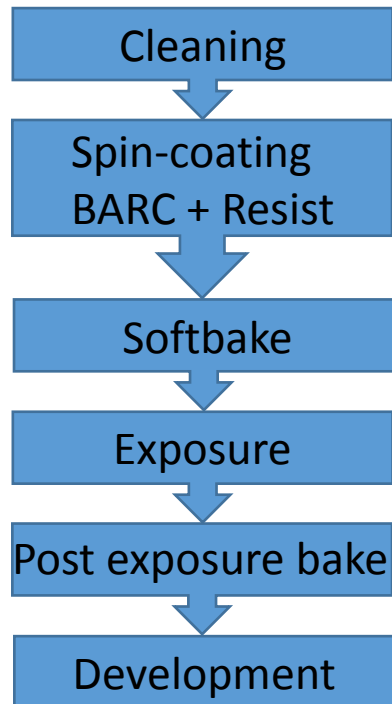
f(viscosity, rotation frequency, acceleration, duration)

New chuck system + Gyrset system for square substrates

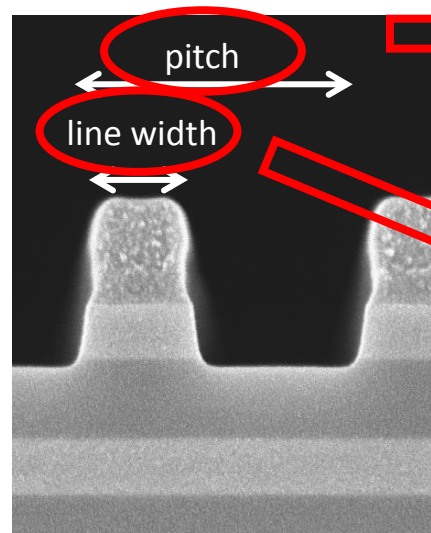


WP4 Photonic components for pre and post pulse conditioning
Lithography process development

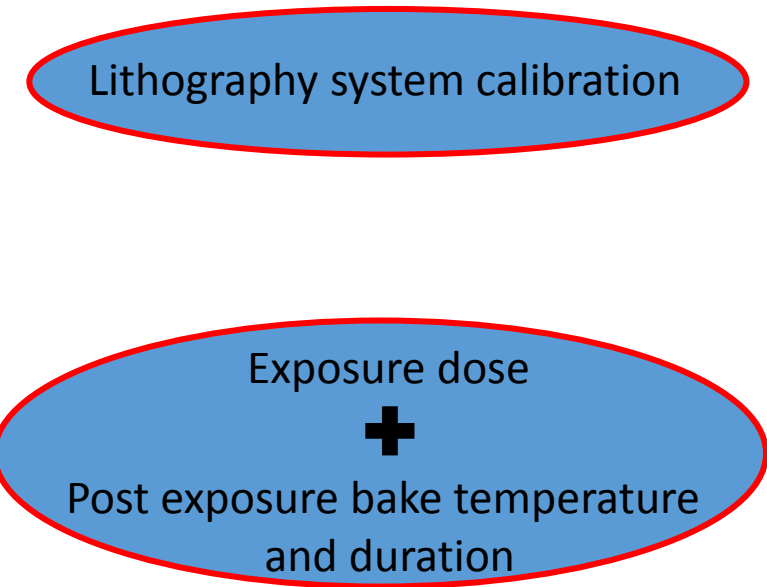
Lithography process steps



Geometric design parameter from IFSW for the PC gratings



Controlling the design parameter during the lithography process



WP4 Photonic components for pre and post pulse conditioning
Lithography system pitch calibration

Reference grating



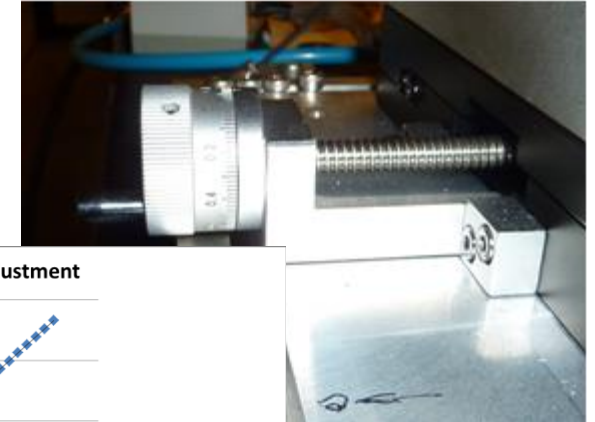
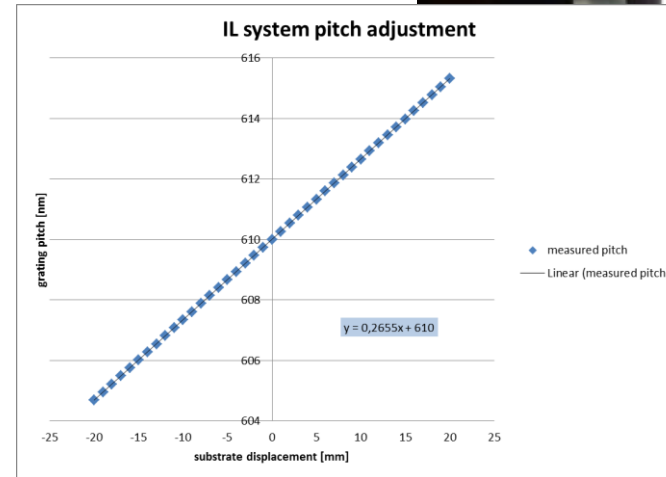
Extern calibration service



Optical diffraction measuring setup



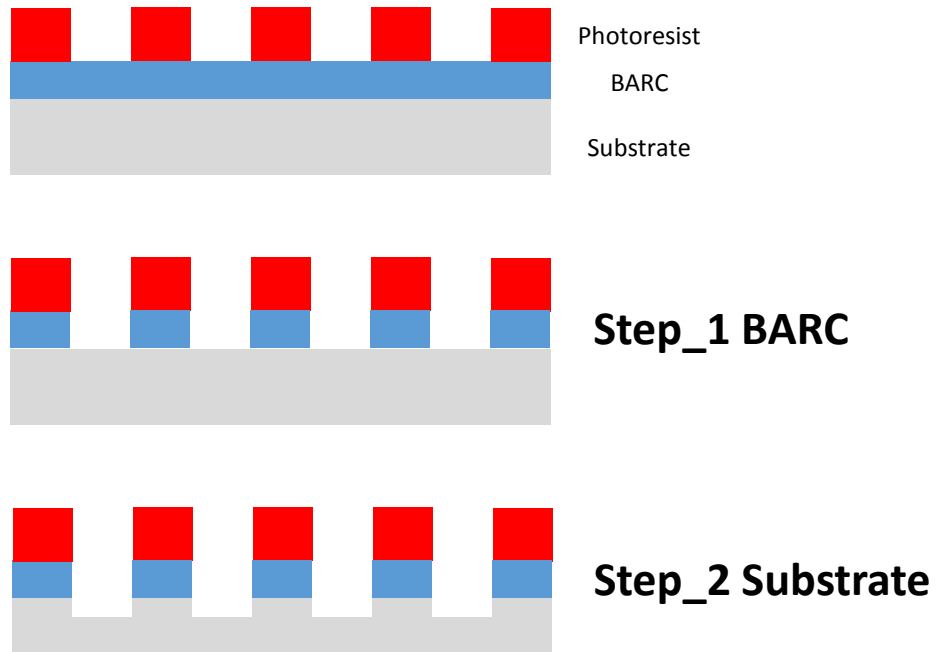
- substrate preparation
- grating definition
- pattern transfer
- Al covering



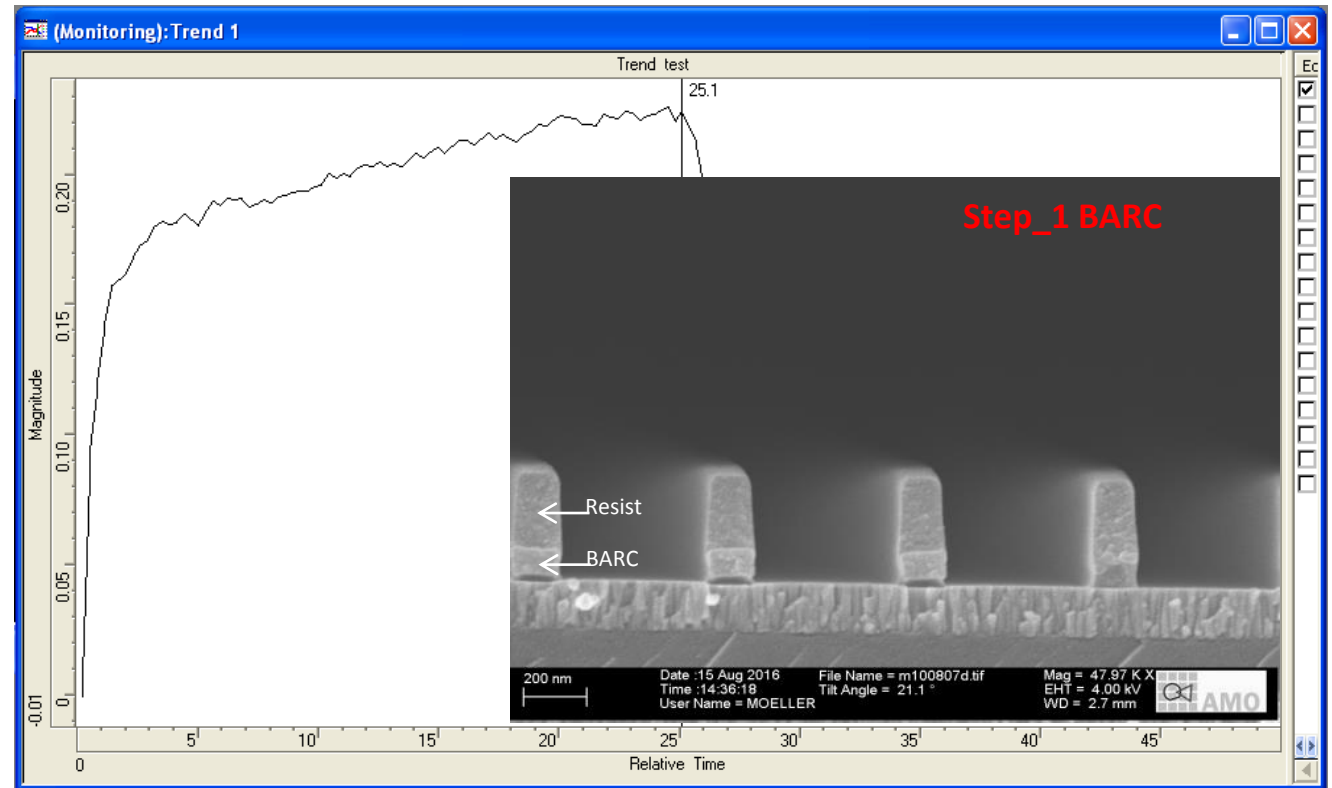
WP4

Photonic components for pre and post pulse conditioning
Etch process development

Etch process



Automatic endpoint detection via plasma spectroscopy

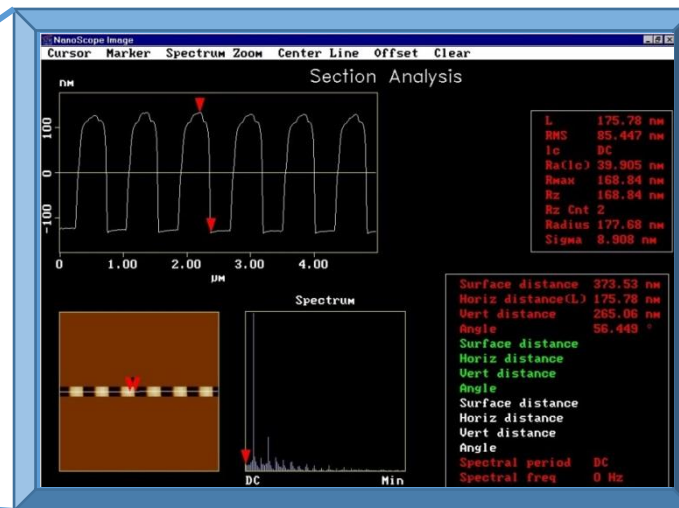
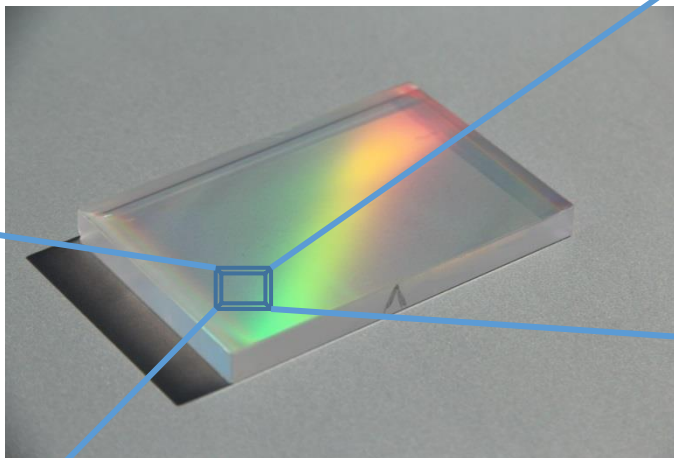
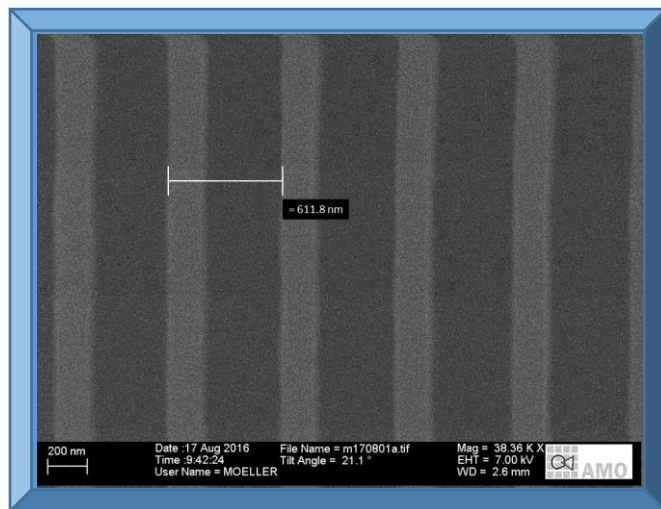


WP4

Photonic components for pre and post pulse conditioning

1st generation grating mirror on large area, rectangular substrates fabricated according to HIPERDIAS design No. 1

SEM photograph



AFM analysis



Milestone 4.3 successfully completed



WP4

Photonic components for pre and post pulse conditioning

Summary:

- *Processing equipment developed and tested successfully*
- *New customized mechanical chuck and software for the spin coater RCD8 was installed*
- *Fabrication of a reference grating is completed*
- *Pitch adjustment from lithography system verified*
- *Automatic endpoint detection tested in combination with etch process Step_1 BARC*
- *Milestone 4.3 fulfilled*



WP4

Photonic components for pre and post pulse conditioning

Next 6 months*Spin coating:*

- *Integration and start-up of the Gyrset system for the coating of square substrates*
- *Process development and optimization with focus on uniformity and reproducibility*

Lithography process:

- *Influence of exposure dose and PEB on linewidth of the grating*
- *Strategies to improve linewidth reproducibility*

Etch process:

- *Endpoint detection system compatibility to etch process Step_2 Substrate*

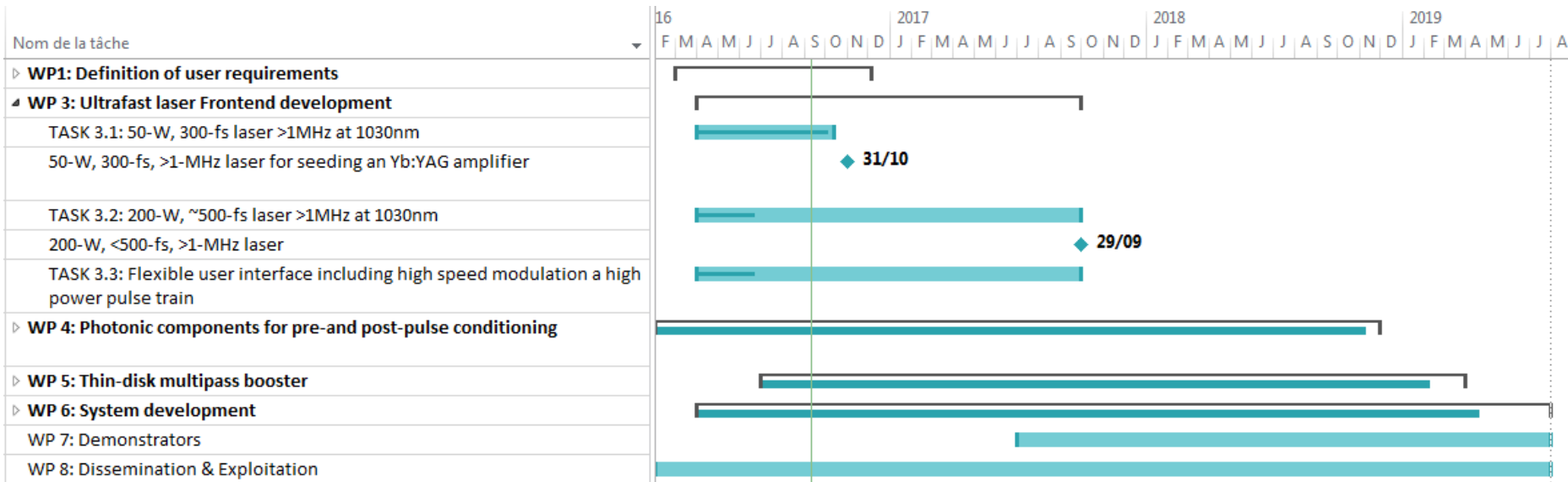


Amplitude Systèmes

B. Weichelt, M. Delaigue, J. Pouysegur, F. Morin,
C. Hönninger



- WPs with contributions from Amplitude



This project has received funding from the European Union’s Horizon 2020 research and innovation programme under grant agreement No 687880

CONFIDENTIAL

WP 1: Definition of user requirements

- Participation in the definition of process and system specifications
 - Discussions with and input from Bosch and C4L
 - This input is taken into account in Amplitude's user interface development (task 3.3) and as far as possible anticipated in the deliverables D3.1 (50-W femtosecond laser) and D3.2 (200-W femtosecond laser)
 - <1ps pulse duration
 - Max. pulse energy $\sim 500\mu\text{J}$
 - Typical pulse repetition rate ranges (< 2 MHz)

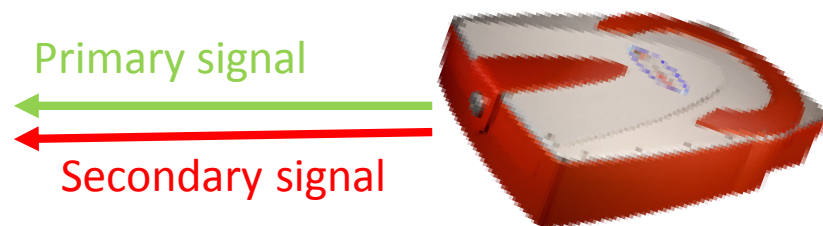
 - Flexible burst mode
 - Synchronisation to scanner
 - Real pulse on demand & triggering by scanner control or...
 - ...fast changing of pulse divider or...
 - ...other approaches



WP 3: Ultrafast laser Frontend development

- T3.1: 50-W femtosecond laser

- Task ~95% finished
- 50-W laser should be shipped to IFSW this week



- Further specific laser features:

- Zero diffraction order output to ensure saturation of downstream thin disk amplifier and avoid first pulse problematic or damage
- Synchronisation to scanner (supersync), synchronisation scheme follows below
- Burst mode possible



WP 3: Ultrafast laser Frontend development

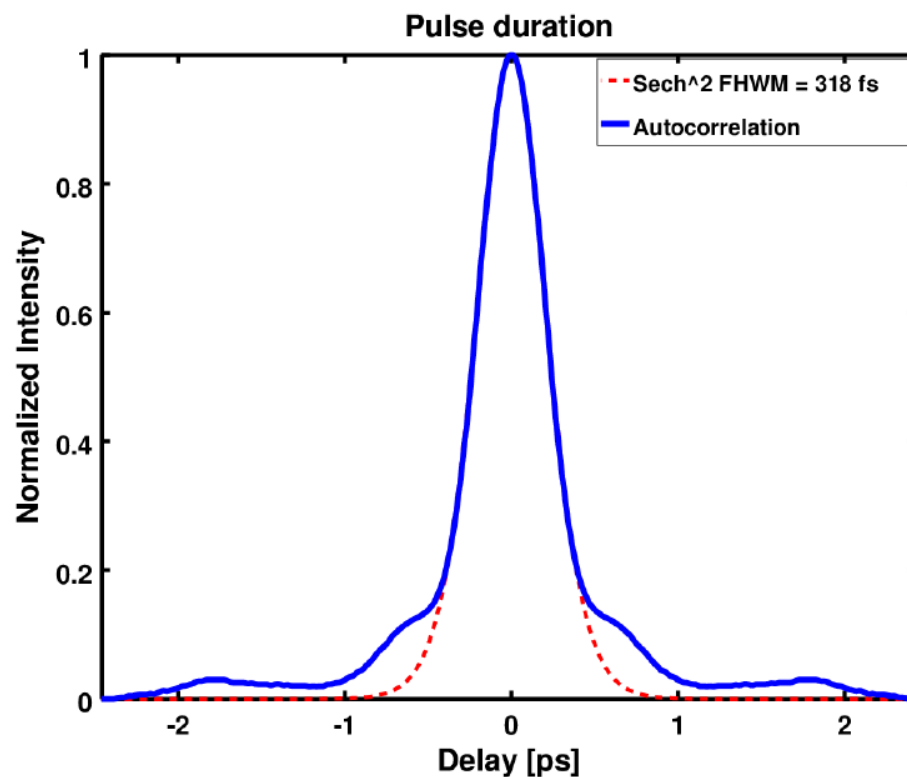
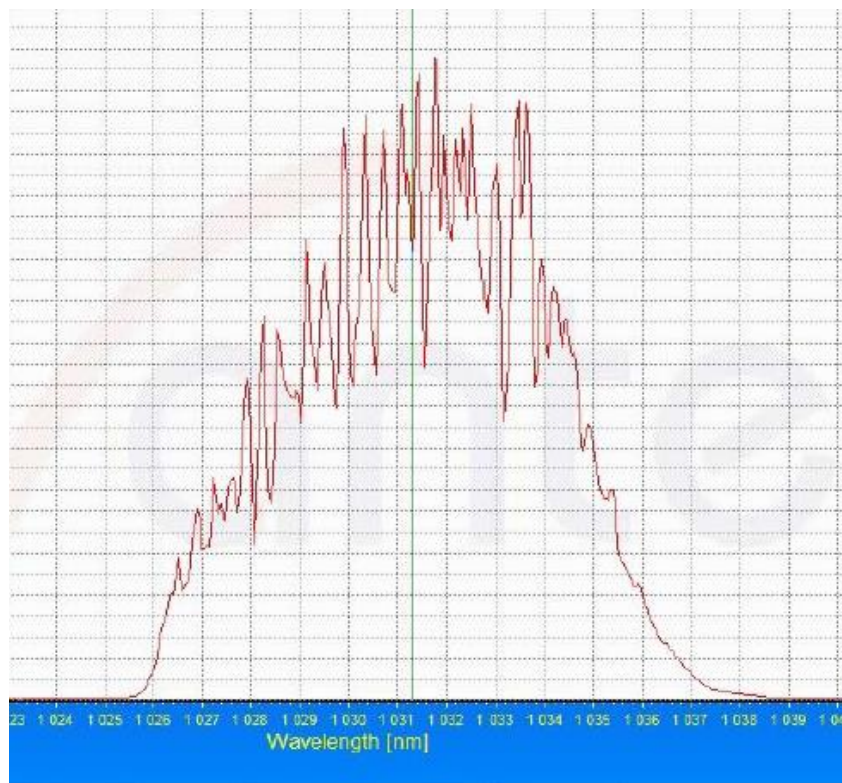
- T3.1: 50-W femtosecond laser

	Laser Parameters		Unit	Target		Measurement		
				1250 kHz	2 MHz	1250 kHz	2 MHz	
IR	*Energy per pulse		μJ	≥ 40	≥ 25	40.8	25.8	
	*Average power		W	≥ 50	≥ 50	51.02	51.6	
	Center wavelength		nm	1030 +/- 5		1031.3	1031.3	
	Bandwidth FWHM			≤ 10		6.8	6.7	
	*Pulse duration		fs	< 400		320	310	
	Pulse energy over 12h		Average	μJ	≥ 40	N/A	40.8	N/A
			RMS	%	< 2		0.10	
	Polarization ratio		-	$> 100:1$		2516:1		
	M ²		M ² _x	-	< 1.30		1.15	
			M ² _y	-			1.08	
	Beam diameter		W _{0x}	mm	2.5 +/- 0.5		2.35	
			W _{0y}				2.09	
	Beam ellipticity		%	$< 13\%$		11.1		
	Astigmatism			$< 50\%$		8		
	Waist ellipticity			$< 13\%$		3.0		
Pointing stability		μrad	< 100		x: 37	y: 48		



WP 3: Ultrafast laser Frontend development

- T3.1: 50-W femtosecond laser

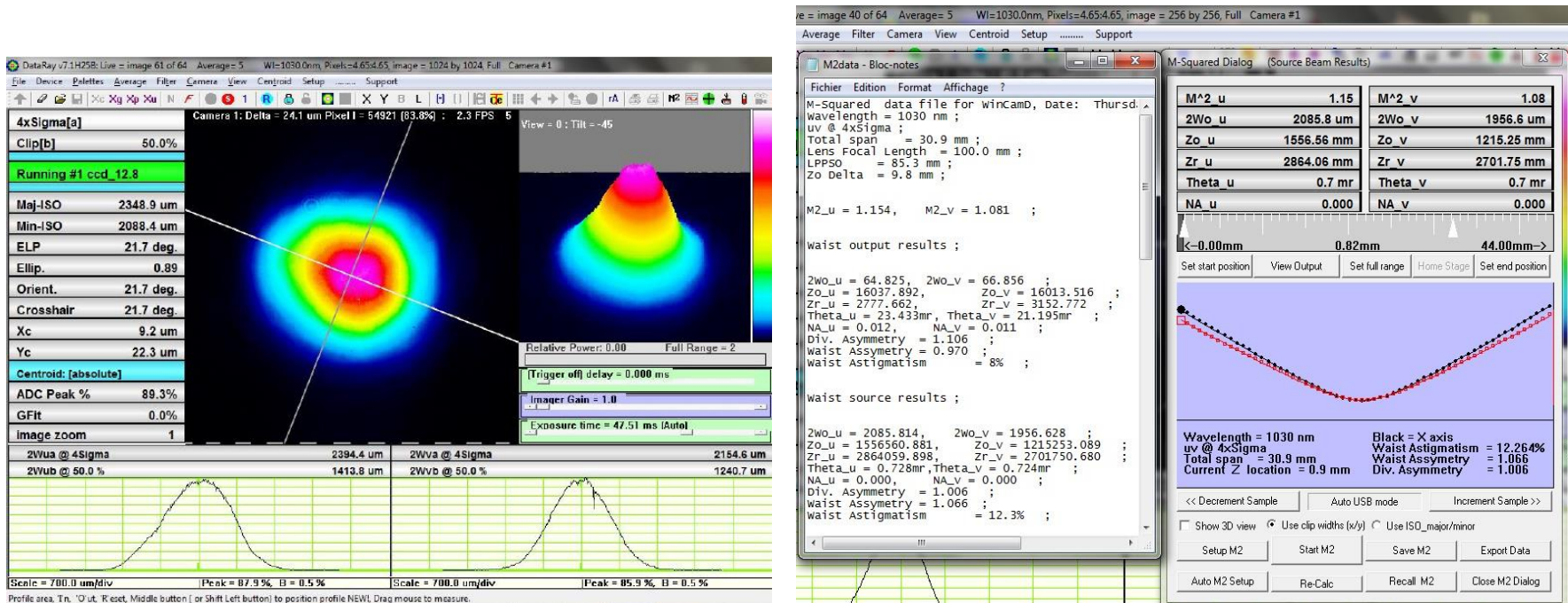


This project has received funding from the European Union's Horizon 2020 research and innovation programme under grant agreement No 687880

CONFIDENTIAL

WP 3: Ultrafast laser Frontend development

- T3.1: 50-W femtosecond laser



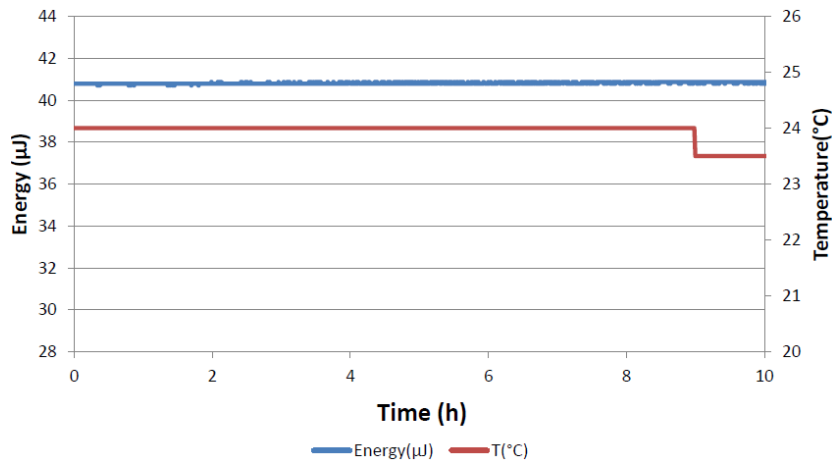
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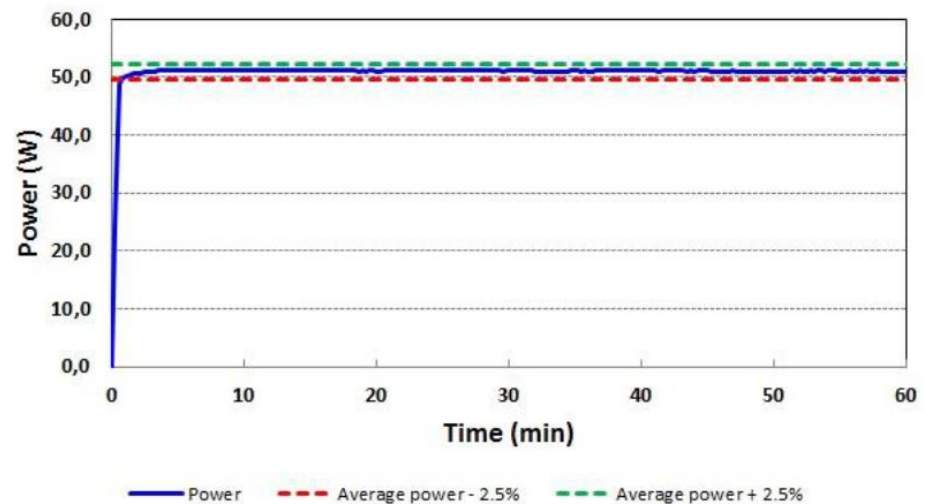
WP 3: Ultrafast laser Frontend development

- T3.1: 50-W femtosecond laser

Long term stability



Power warm-up time



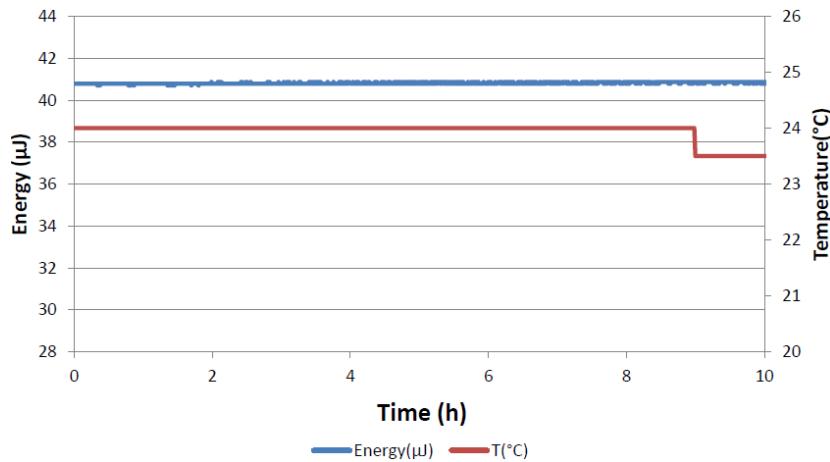
This project has received funding from the European Union's Horizon 2020 research and innovation programme under grant agreement No 687880

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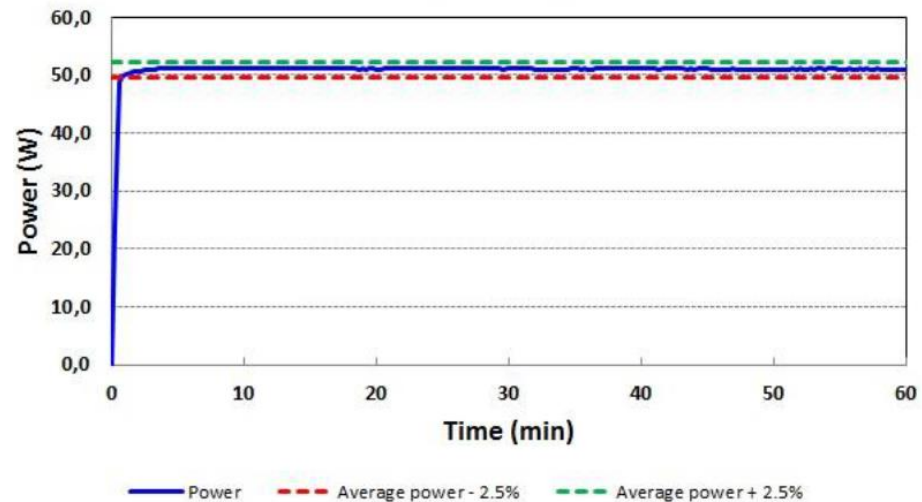
WP 3: Ultrafast laser Frontend development

- T3.1: 50-W femtosecond laser

Long term stability



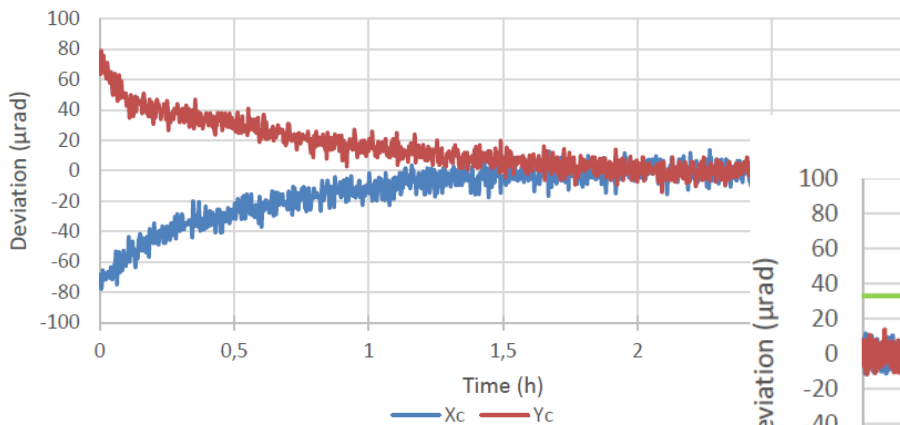
Power warm-up time



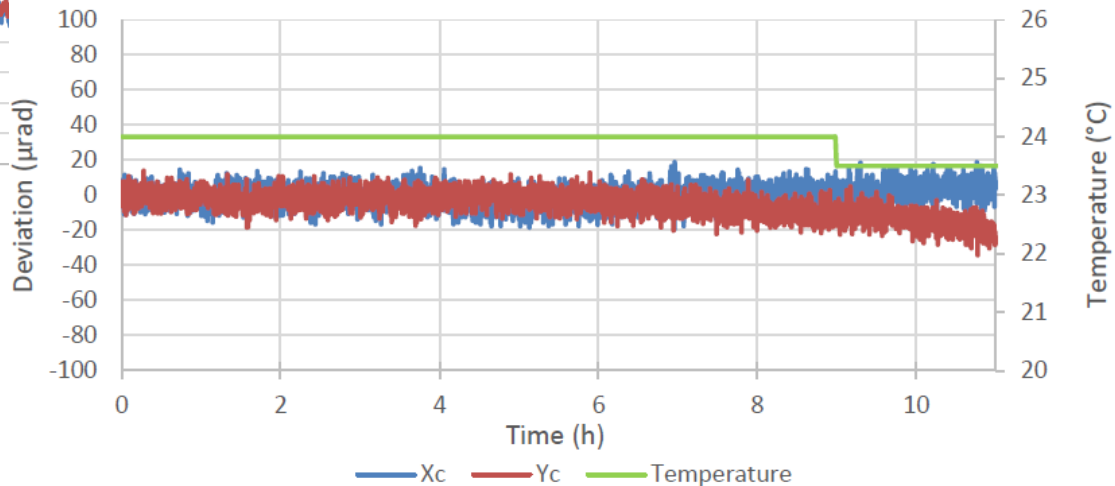
WP 3: Ultrafast laser Frontend development

- T3.1: 50-W femtosecond laser

Pointing Warm up Time



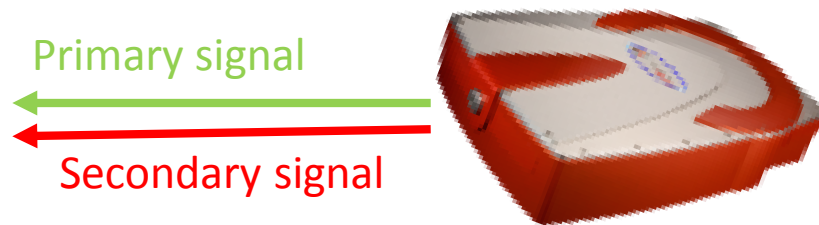
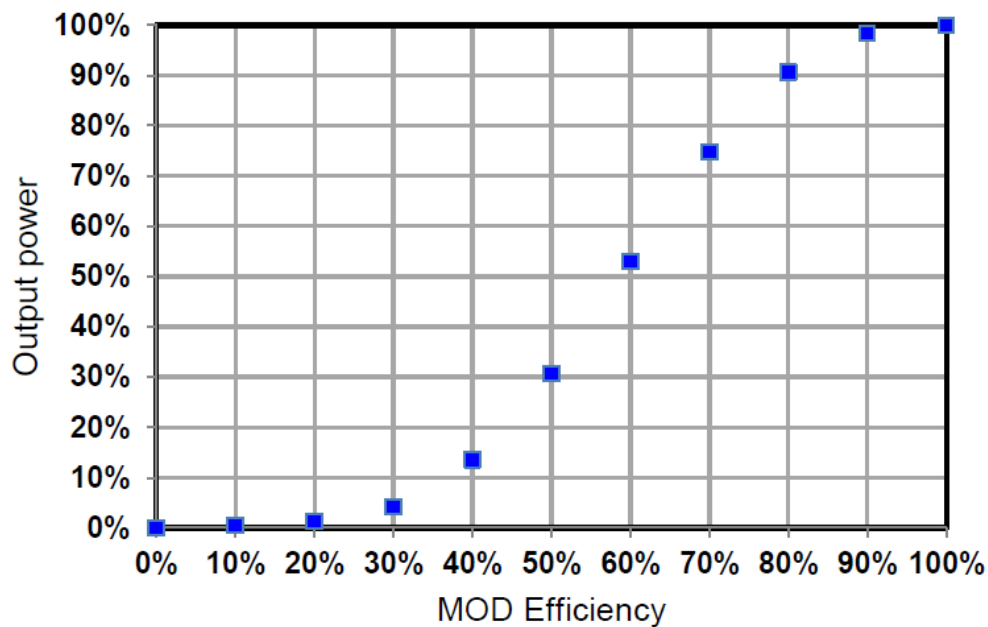
Pointing Stability



WP 3: Ultrafast laser Frontend development

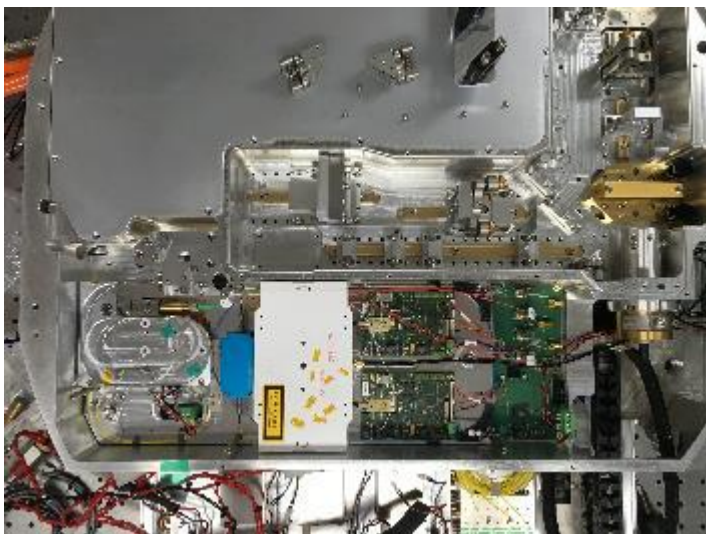
- T3.1: 50-W femtosecond laser

External modulator attenuation:



WP 3: Ultrafast laser Frontend development

- T3.2: 200-W femtosecond laser
 - Task started (~10 to 15% estimated)
 - Buying of components and testing of concepts
 - Preliminary results, but too early to conclude for best concept



- not fully characterized
- not compressed



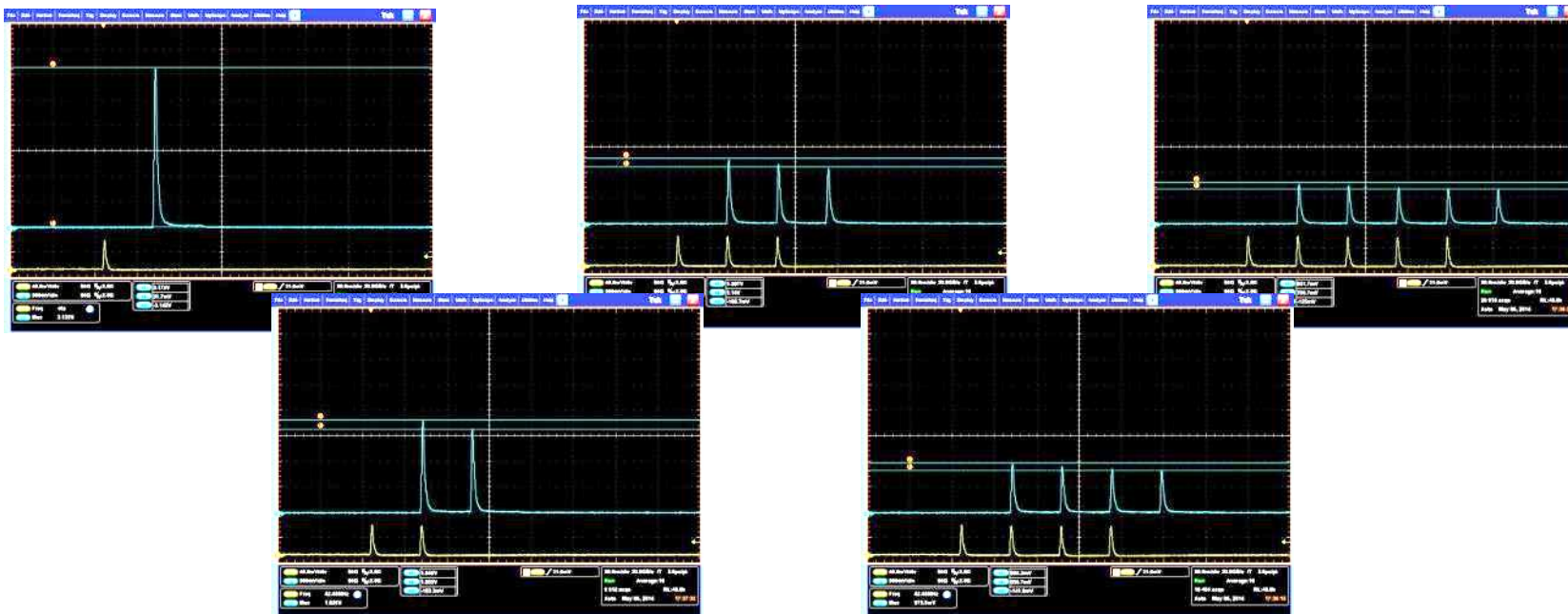
WP 3: Ultrafast laser Frontend development

- T3.3: Flexible user interface including high speed modulation a high power pulse train
 - Task started (~10% estimated)
 - Typical pulse repetition rate ranges (< 2 MHz)
 - Flexible burst mode
 - Synchronisation to scanner
 - Real pulse on demand & triggering by scanner control or...
 - ...fast changing of pulse divider or...
 - ...other approaches



WP 3: Ultrafast laser Frontend development

- T3.3: Flexible user interface including high speed modulation a high power pulse train



- Pulse separation within burst = oscillator periode: 25 ns
- Burst repetition rate flexible



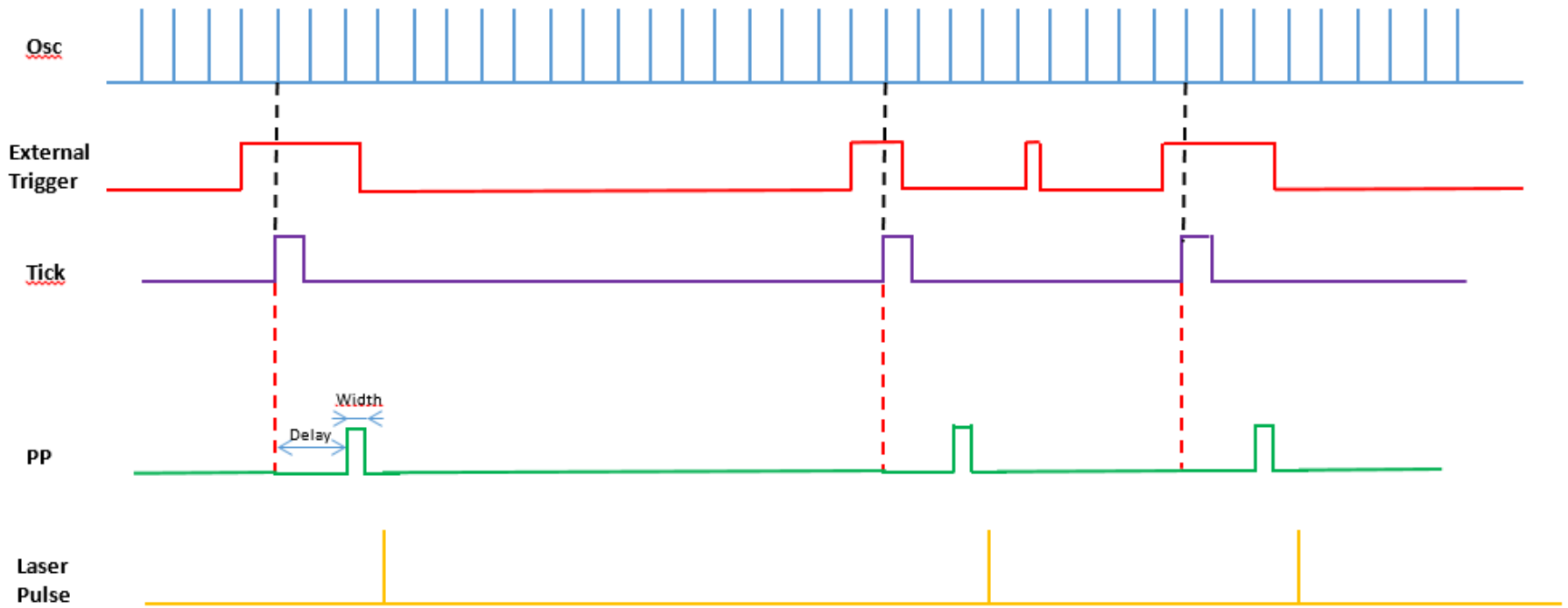
WP 3: Ultrafast laser Frontend development

- T3.3: Flexible user interface including high speed modulation a high power pulse train
 - User access to Pulse picker
 - Synchronisation between Laser and Scanner for high speed processing



WP 3: Ultrafast laser Frontend development

- T3.3: Flexible user interface including high speed modulation a high power pulse train



WP 3: Ultrafast laser Frontend development

- T3.3: Flexible user interface including high speed modulation a high power pulse train
 - Identify all critical system delay times
 - Suggest concepts for pulse-on-demand without “dead times” to endusers, discuss, decide, realize



- WP 4, 5, 6:
 - WP 4: Photonic components
 - Specifications for high efficiency diffractions gratings communicated to partners IFSW and AMO
 - WP 5: Thin disk multipass booster
 - first seed laser to be provided soon
 - Additional features integrated to facilitate thin disk multipass amplifier (zero order of ext. Mod OUT)
 - Discussions on control interface started but needs to become more concrete
 - WP 6: System development
 - Interfaces of seed lasers communicated to integrator LASEA (as far as possible at this stage)



- Next steps:
 - WP 3:
 - Ship and install 50-W laser (this month)
 - R&D work on 200-W laser, validate concept, and start demonstrator fabrication (should be in plan)
 - R&D work on user interface and pulse-on-demand requirements
 - Close contact to end users required in order to develop the right thing



High-Volume 3D Processing of Silicon – Process Development

**M. Lustfeld, A. Michalowski, M. Ametowobla,
G. Kunz, D. Brinkmeier, S. Karg**



BOSCH

Invented for life



BOSCH team involved in HIPERDIAS

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Timeline of BOSCH involvement in HIPERDIAS

Task	H1/16	H2/16	H1/17	H2/17	H1/18	H2/18	H1/19
1.1 Application specs		◆	D1.1: End-user application specs R: BOSCH; turned in: 06/16				
1.2 Process & system specs			◆	D1.2: Process & system specs			
1.3 Validation of progress			◆	D1.3: Prototype & progress validation R: BOSCH			
2.1 Process development					◆	D2.1: Process limits 3D Si processing; R: BOSCH	
2.4 Process upscaling						◆	D2.4: Strategy for high power processing; R: BOSCH
6.1 Definition of interfaces			◆	D6.1: Interface definition			
6.6 Test and Evaluation							◆ D6.6: System test & validation
7.4.1 Reference samples						◆	D7.5: Performance of the 500 W demonstrator; R: BOSCH



WP1	Definition of user requirements
-----	---------------------------------

Work completed in period 02/16 – 08/16**Task 1.1: Collection of end-user application specifications**

- Specified demonstrator geometry containing all end-user requirements
- Completed Deliverable 1.1

Task 1.2: Process and system specifications

- Deduced system requirements from product requirements
- Defined additional system requirements based on experience in Task 2.1
- Discussed requirements with partners in WP3-7

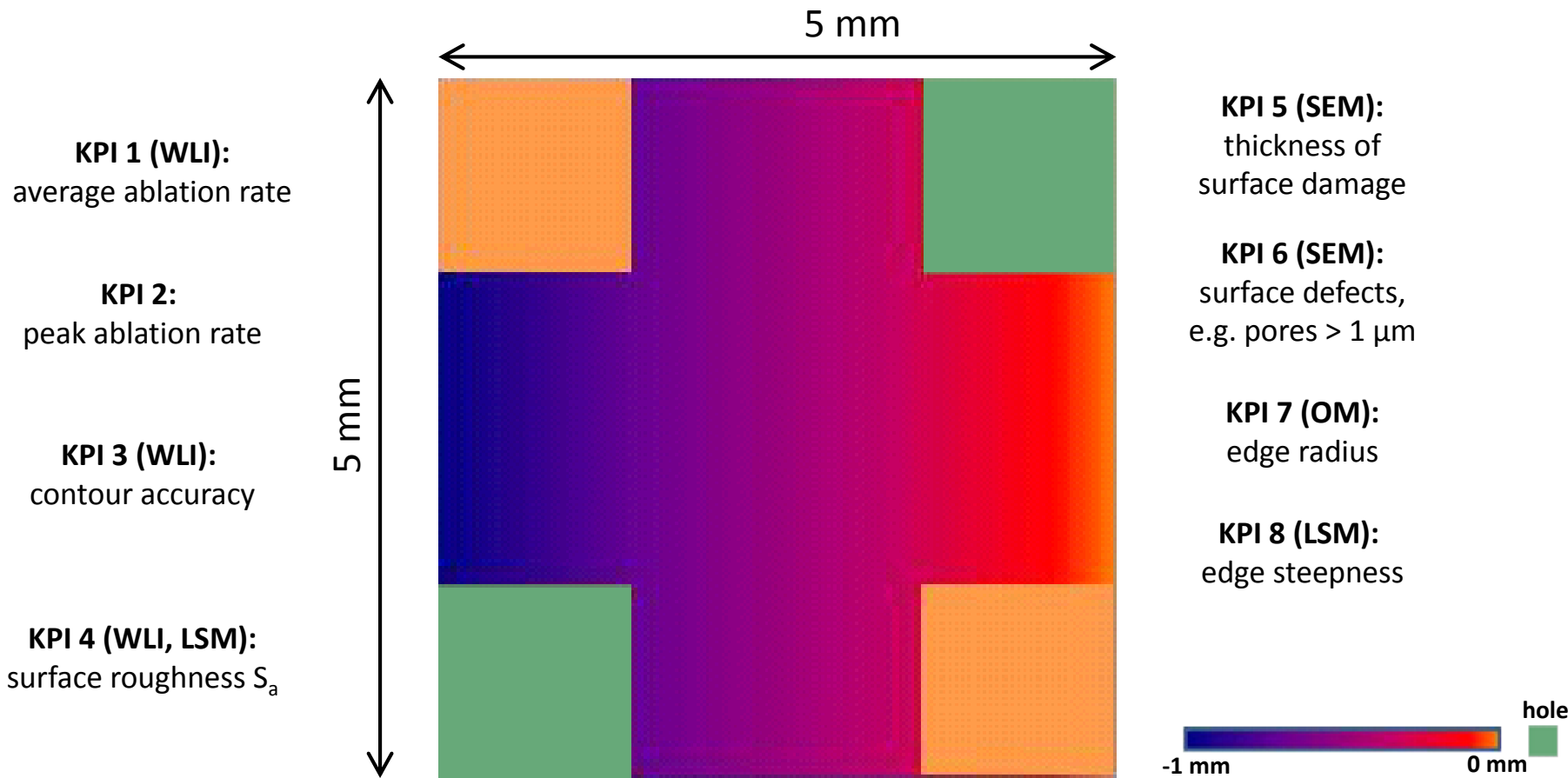
Task 1.3: Assessment of technical progress

- Deduced KPI's from demonstrator geometry
- Identified assessment methods to validate KPI's

Work in progress until 01/17

- Establish iterative feedback loop with partners in WP3-7 to adapt system requirements
- Adapt demonstrator geometry accordingly
- Qualify assessment methods for validation of KPI's

WP1 KPI's and their validation using the demonstrator geometry



KPI's	
name	target
av. ablation rate	1 mm ³ /s
peak ablation rate	3 mm ³ /s
contour accuracy	< 10 μm
surface roughness S_a	< 1 μm
surface damage	tbd.
surface defects $> 1\mu\text{m}$	none
edge radius	< 200 μm
edge steepness	> 70°

WLI: White Light Interferometry
 SEM: Scanning Electron Microscopy
 LSM: Laser Scanning Microscopy
 OM: Optical Microscopy



WP1	Implications of process requirements for the laser production system
-----	--

Performance and quality: Laser source and interface features

- Pulse duration $\tau_p < 1$ ps (increased ablation efficiency for reduced pulse duration)
- Max. pulse energy $E_p \geq 500$ μ J
- Pulse repetition frequency $f_{rep} \leq 2$ MHz (estimate)
- Min. 2 pulse burst desirable, flexible burst desirable
- Pulse divider from base frequency (variable repetition rate, unchanged pulse parameters)
- Synchronization with scanner (\rightarrow use of skywriting) \rightarrow e.g. precision switching of gate
- **Ideal:** synchronization of scanner speed and pulse repetition frequency \rightarrow increase processing speeds

Safety

- High total ablated volume \rightarrow heavy-duty exhaust system
- Very high power densities \rightarrow x-ray shielding?
- High power input: wafer cooling to avoid cracking?

WP2

Process Development

Work completed in period 02/16 – 08/16**Task 2.1: Fundamental process development 3D Si processing**

- Performed literature study on:
 - State of the art in laser processing of Si
 - Comparison to alternative Si micro structuring processes (mechanical, chemical)
- Ablated 3D Si demonstrator geometry
 - Qualified assessment methods of KPI's
 - Determined current state of KPI's
- Determined ablation efficiency as a function of fluence at medium laser power
 - 3 different laser sources (40 W – 50 W)
 - Pulse duration (1 ps, 6 ps, 10 ps)
 - Laser fluence: 0.1 J/cm² – 3 J/cm²
- Performed ablation experiments at high power (670 W) @ USTUTT

WP2

Process Development

Work in progress***Short-term: until 03/17***

- Continue literature study
- Continue studies on process fundamentals
 - Impact of processing in burst mode
 - Impact of very short pulse duration (< 1 ps)
 - Phenomena occurring during processing at very high fluence
- Proposal of set of optimum laser process parameters

Long-term (including WP 6.6 and WP 7.4.1)

- Design of experimental strategy for upscaling of the laser process
- Implementation of experimental strategy in collaboration with WP3-7
- Identification of phenomena occurring specifically at very high laser power
- Optimization of overall process

WP2

Literature Study

Alternative Si removal processes:

- **Mechanical milling:** High finishing quality requires ductile processing regime at very low feed rate
→ currently available technology too slow by several orders of magnitude [1] [2]
- **Chemical etching:** Challenge: Si texture causes anisotropic removal rates;
3D ablation requires elaborate masking setup → very slow processing

Laser processing of Si: Exemplary studies, recently published:

- [3]: ps-laser texturization of Si for photovoltaics at UV, VIS, IR wavelength
→ Sub-surface damage of Si (amorphization) to a depth of up to 2 μm below the ablated surface
- [4]: Minimizing the surface roughness for Si ablation with USP lasers
→ Trade-off between laser-induced surface structures (low fluence) and melt ejections (high fluence)
→ Surface roughness depends strongly on scanning strategy
- [5]: Quality & efficiency enhancement by processing in burst mode (“ablation-cooled material removal”)

[1] T.J.K. Rusnaldy, H.S. Kim, INT J MACH TOOL MANU 47:52 (2007); [2] M. Arif, M. Rahman, W.Y. San, J MANUF PROCESS 14:52 (2012)

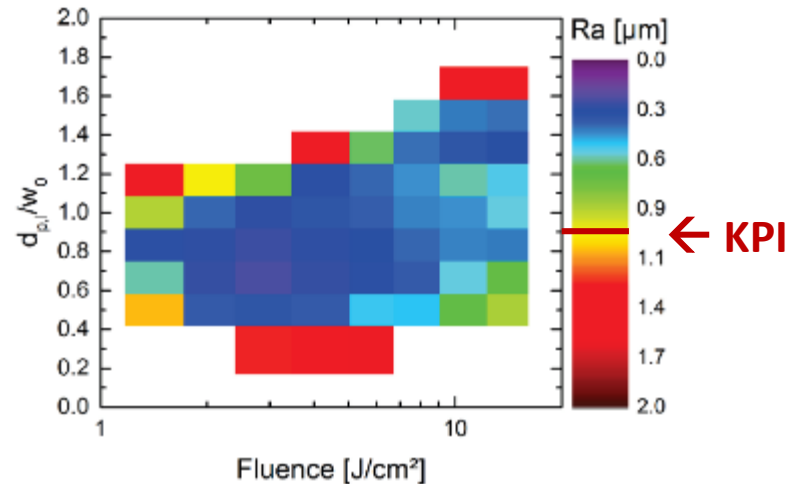
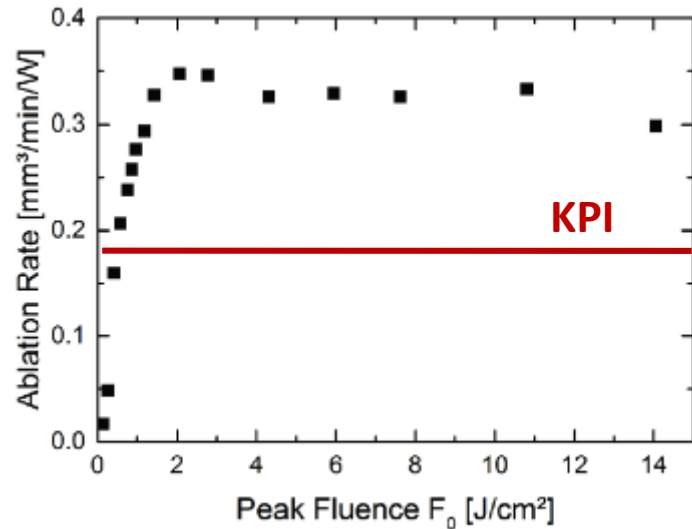
[3] S. Binetti *et al.*, APPL SURF SCI 371:196 (2016); [4] M. Domke *et al.*, J LAS MICRO/NANO ENG 11:100 (2016); [5] C. Kerse *et al.*, NATURE 537:84 (2016)

WP2

Literature Study: Exemplary available data

Minimizing the surface roughness for Si ablation with USP lasers [4]

- Non-linear relation between fluence and ablation depth
- Surface roughness: Function of fluence and scanning strategy

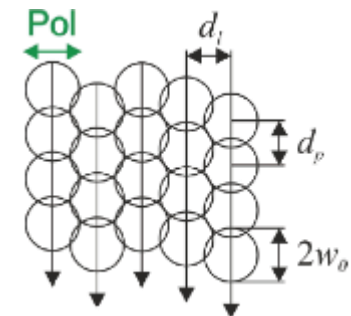


➔ Scalability to high power ablation (> 2 orders of magnitude)?

Parameters

wavelength	λ	520 nm
pulse duration	τ_p	380 fs
repetition rate	f_{rep}	200 kHz
maximum power	P_{max}	2 W
focus radius	d_0	6 μm

Scanning strategy

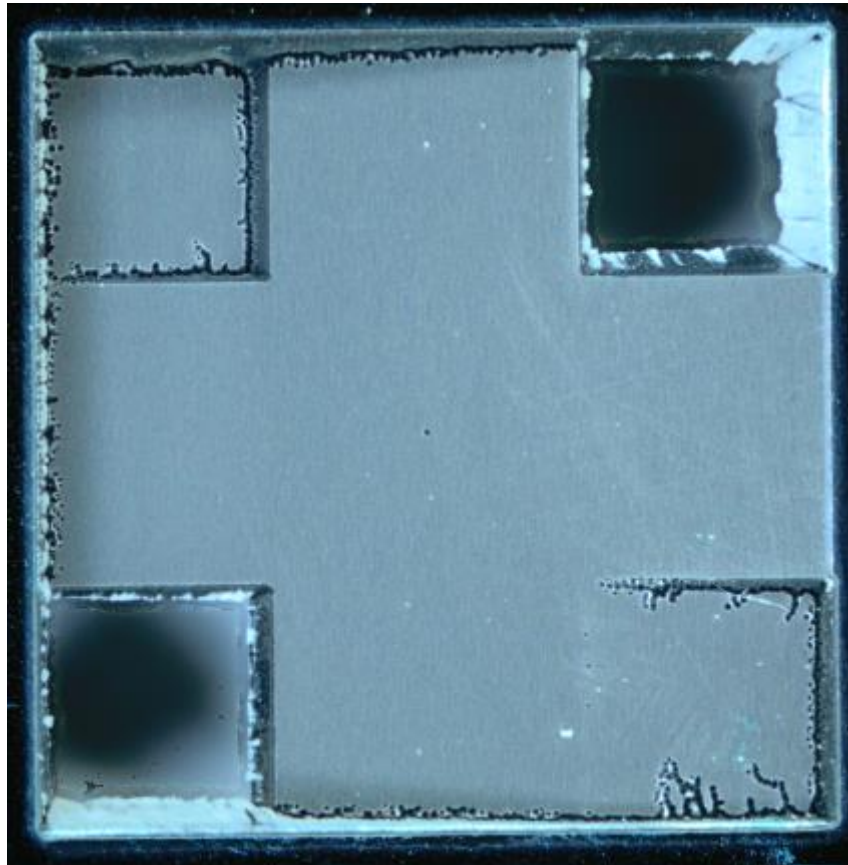


[4] M. Domke *et al.*, J LAS MICRO/NANO ENG 11:100 (2016)



WP2

Experimental work at BOSCH: Ablation of demonstrator geometry (laser source: TruMicro)



Parameters

wavelength	λ	1030 nm
pulse duration	τ_p	6 ps
repetition rate	f_{rep}	400 kHz
maximum power	P_{max}	50 W
focus radius	d_0	70 μm

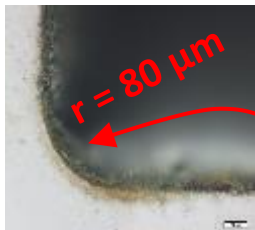
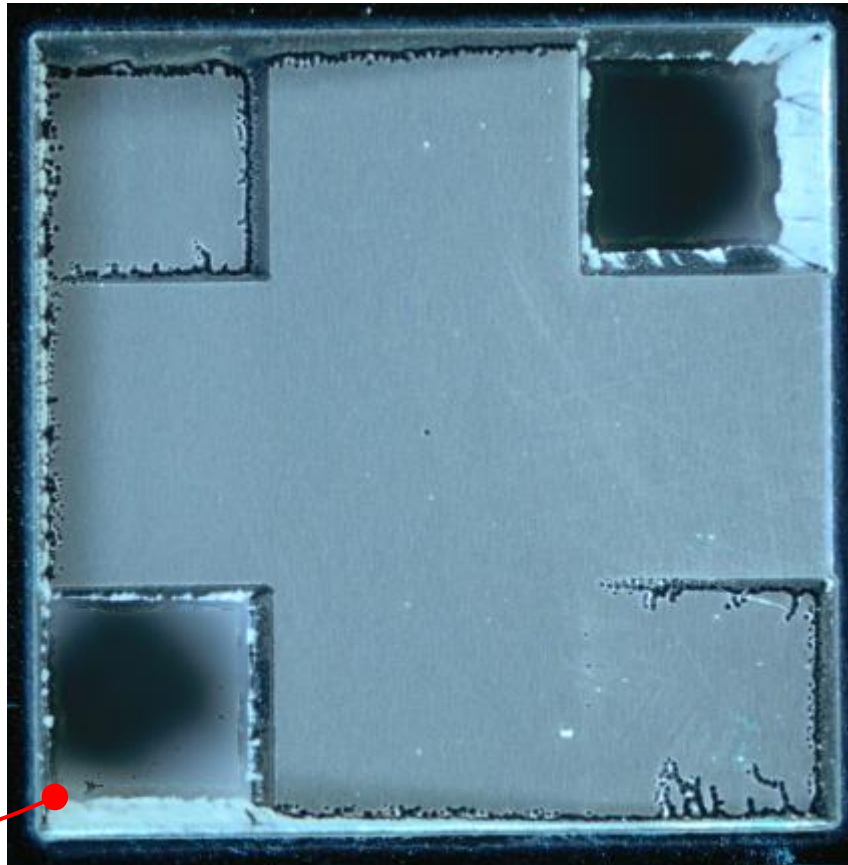
Selected KPI's

name	measured	target
av. ablation rate	0,045 mm ³ /s	1 mm ³ /s
edge steepness	81°	> 70°
surface roughness S_a	< 1 (15) μm	< 1 μm
edge radius	80 μm	< 200 μm



WP2

Experimental work at BOSCH: Ablation of demonstrator geometry (laser source: TruMicro)



Parameters

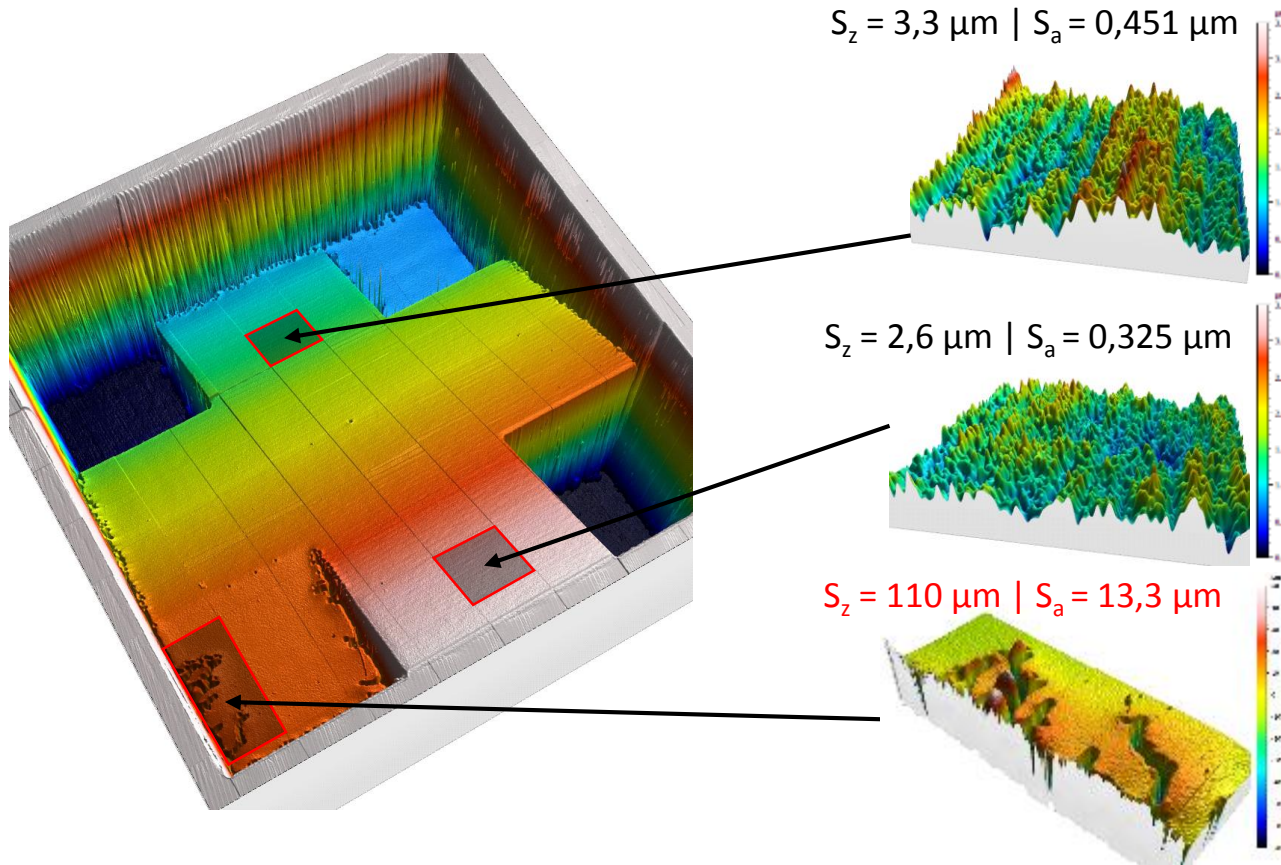
wavelength	λ	1030 nm
pulse duration	τ_p	6 ps
repetition rate	f_{rep}	400 kHz
maximum power	P_{max}	50 W
focus radius	d_0	70 μm

Selected KPI's

name	measured	target
av. ablation rate	0,045 mm ³ /s	1 mm ³ /s
edge steepness	81°	> 70°
surface roughness S_a	< 1 (15) μm	< 1 μm
edge radius	80 μm	< 200 μm

WP2

Experimental work at BOSCH: Ablation of demonstrator geometry: surface roughness



Parameters

wavelength	λ	1030 nm
pulse duration	τ_p	6 ps
repetition rate	f_{rep}	400 kHz
maximum power	P_{max}	50 W
focus radius	d_0	70 μm

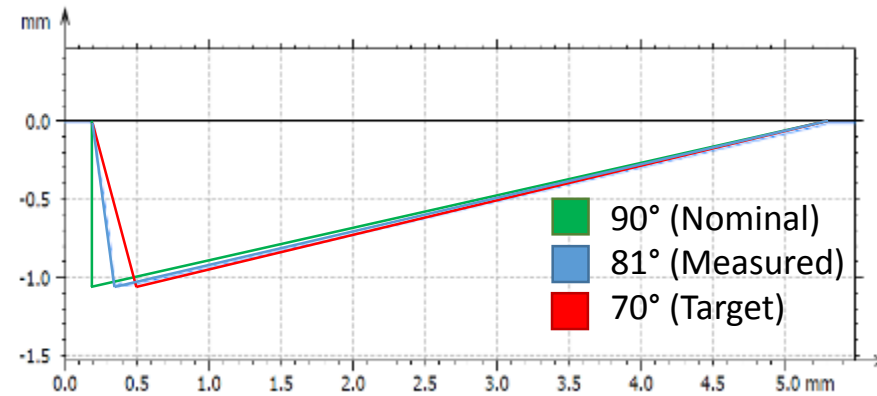
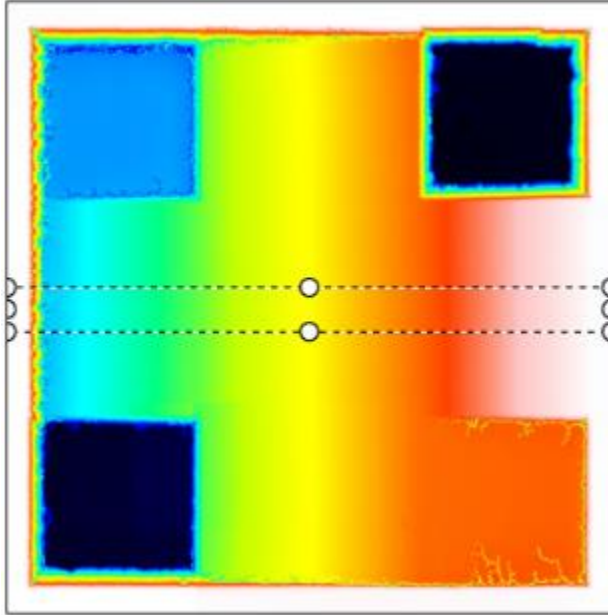
Selected KPI's

Name	measured	target
av. ablation rate	0,045 mm ³ /s	1 mm ³ /s
edge steepness	81°	> 70°
surface roughness S_a	< 1 (15) μm	< 1 μm
edge radius	80 μm	< 200 μm



WP2

Experimental work at BOSCH: Ablation of demonstrator geometry: edge steepness



Parameters

wavelength	λ	1030 nm
pulse duration	τ_p	6 ps
repetition rate	f_{rep}	400 kHz
maximum power	P_{max}	50 W
focus radius	d_0	70 μm

Selected KPI's

name	measured	target
av. ablation rate	0,045 mm ³ /s	1 mm ³ /s
edge steepness	81°	> 70°
surface roughness S_a	< 1 (15) μm	< 1 μm
edge radius	80 μm	< 200 μm



WP2 Experimental work at BOSCH: Fundamental studies

Objectives of fundamental studies:

- Suitability of laser sources (3 USP lasers):
- Determined relation: laser fluence – ablation efficiency
- Determined relation: ablation rate – surface quality
- Determined scalability of literature values to medium laser power

Procedure:

- Efficiency curve:
 - Ablated square geometry (1 mm²): 20 – 50 samples (0.1 – 3 J/cm²) per parameter set
 - Measured ablation depth by WLI
- Surface quality (roughness S_a):
 - Assessed ablated surface quality by LSM/WLI

Used Laser Sources

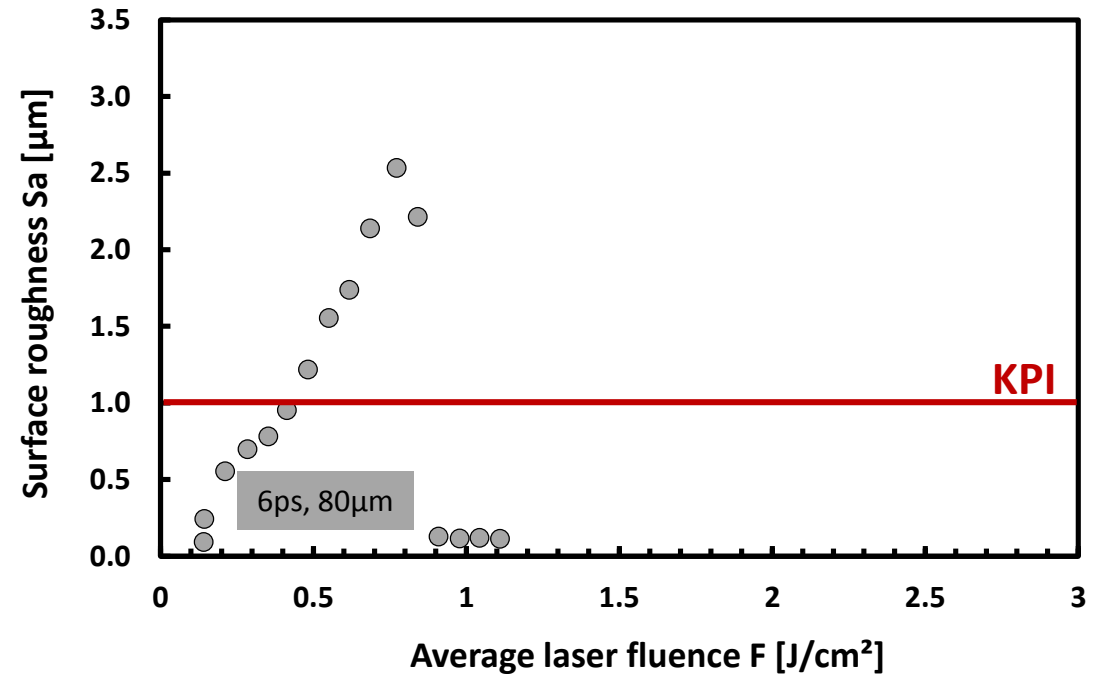
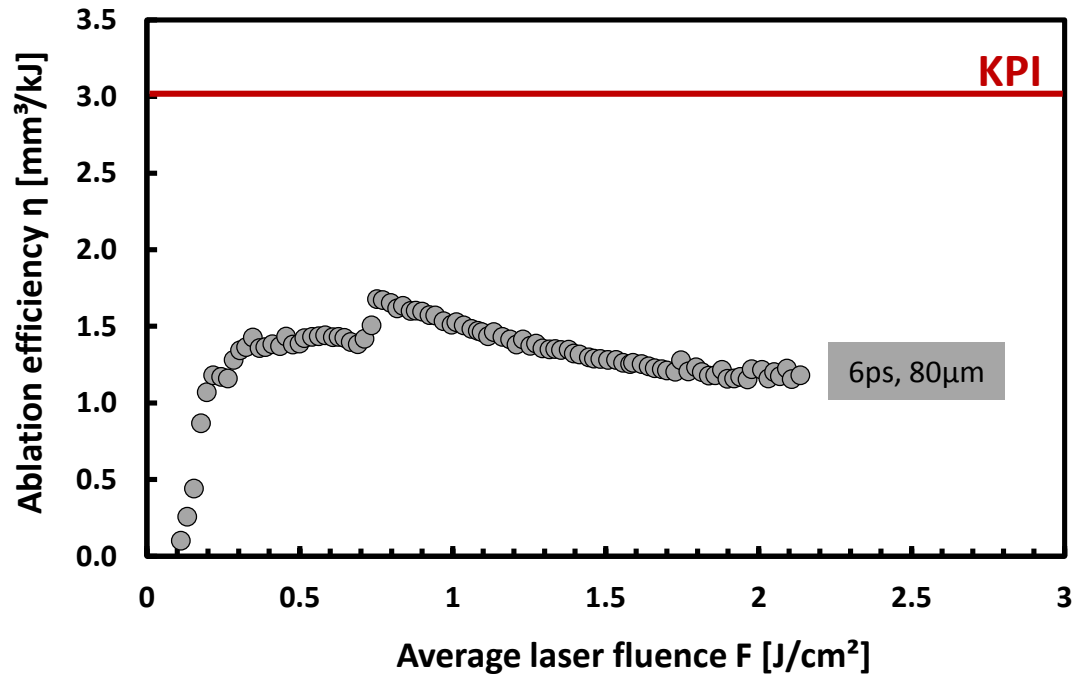
	A: TruMicro	B: Picoblade	C: TruMicro FE
λ	1030 nm	1064 nm	1030 nm
τ_p	6 ps	10 ps	1 ps
f_{rep}	400 kHz	1000 kHz	400 kHz
P_{max}	50 W	40 W	40 W
d_0	80 μm	55 μm	55 μm
burst	no	yes	no



WP2

Experimental work at BOSCH: Fundamental studies

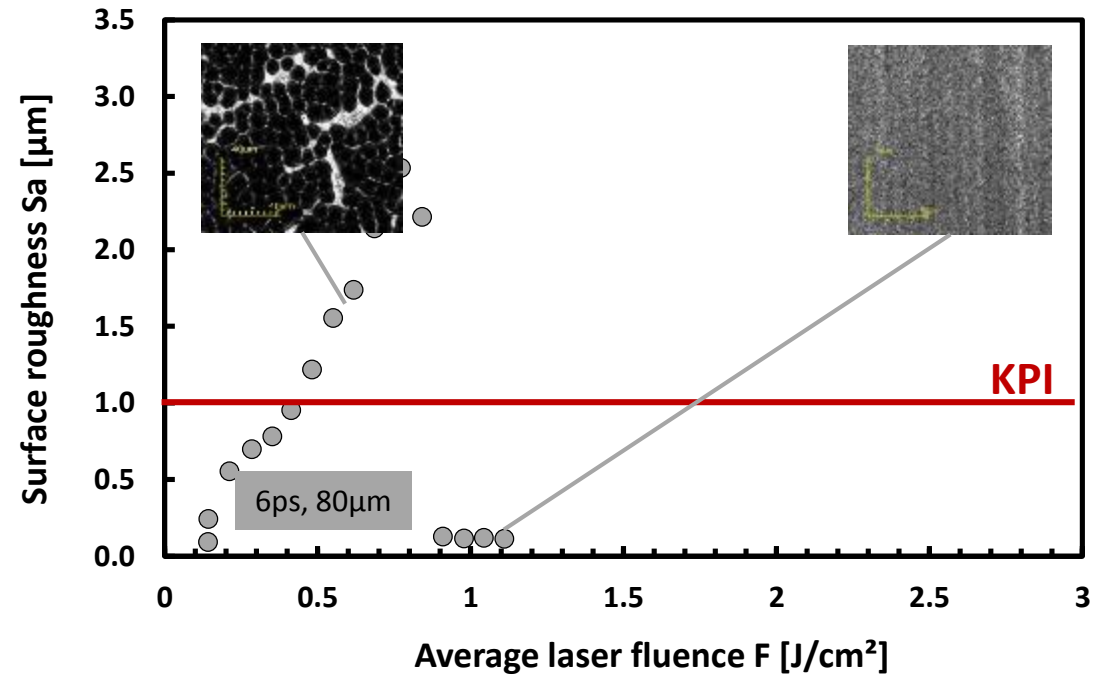
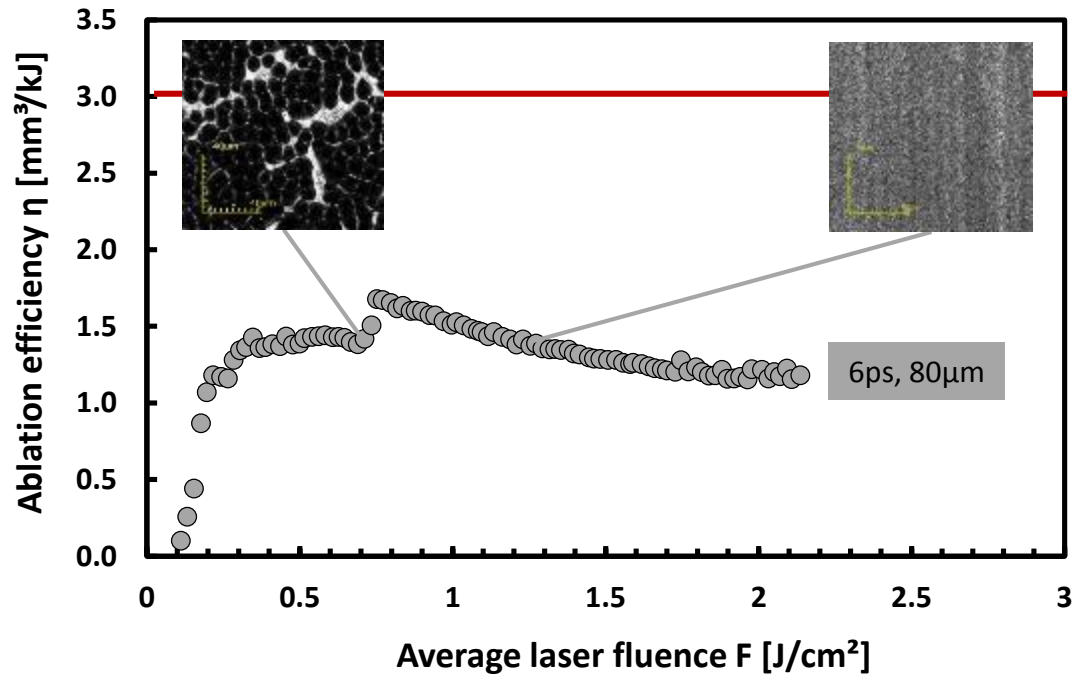
Experimental series A: TruMicro 5050, $\tau_p = 6 \text{ ps}$, $\lambda = 1030 \text{ nm}$, $d_0 \approx 80 \text{ }\mu\text{m}$



WP2

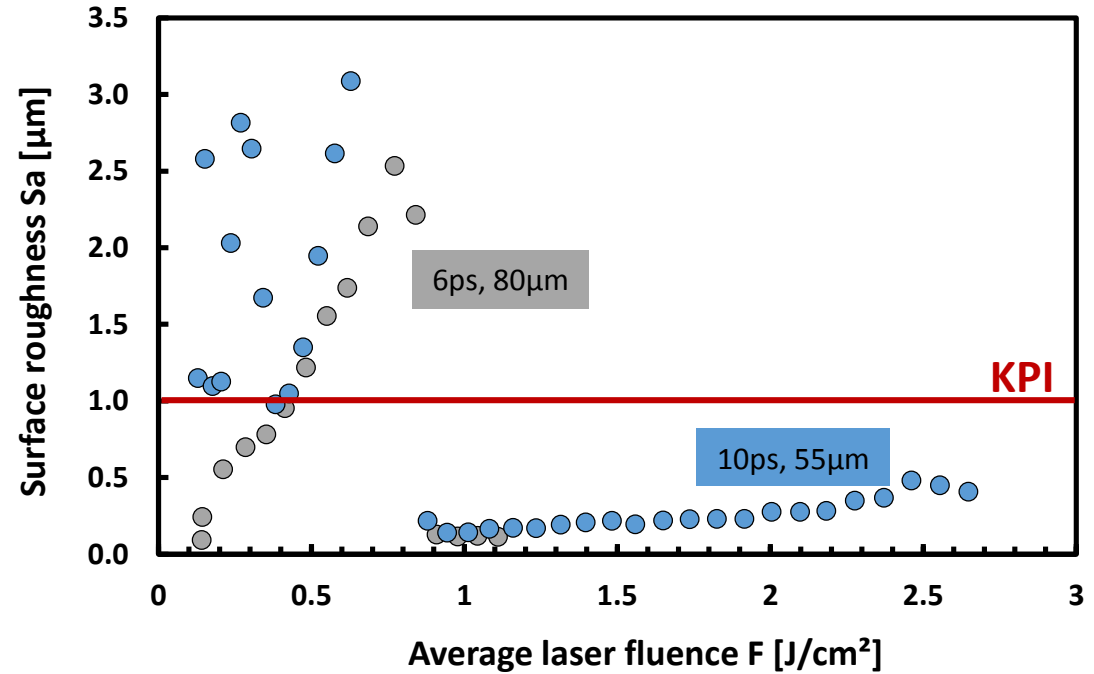
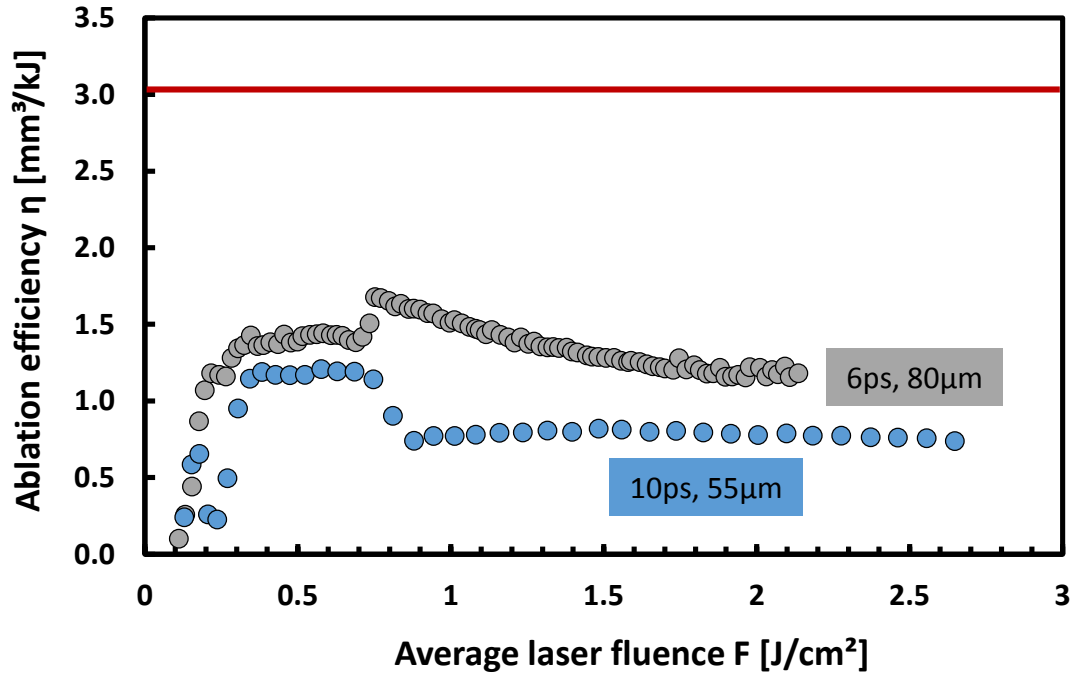
Experimental work at BOSCH: Fundamental studies

Experimental series A: TruMicro 5050, $\tau_p = 6 \text{ ps}$, $\lambda = 1030 \text{ nm}$, $d_0 \approx 80 \mu\text{m}$



WP2 Experimental work at BOSCH: Fundamental studies

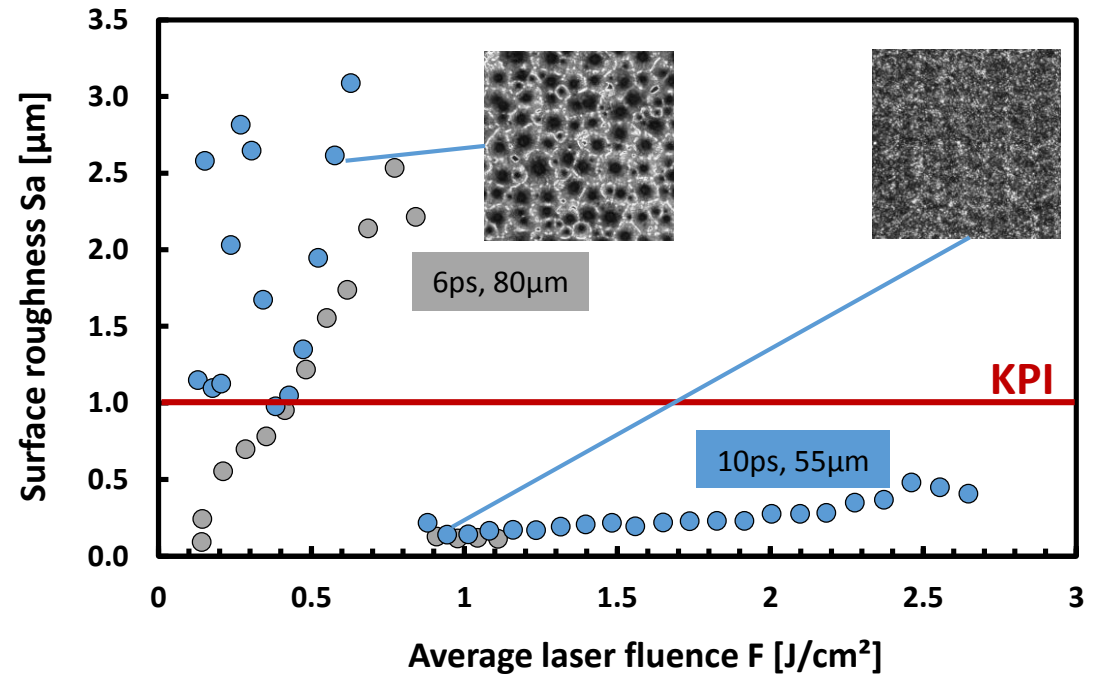
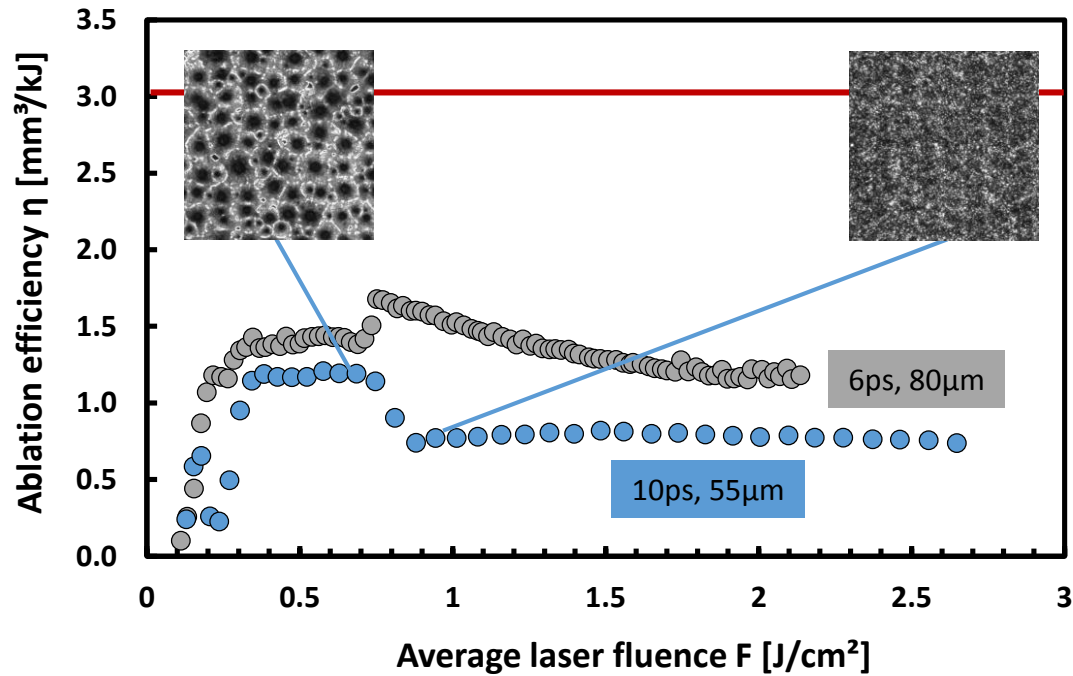
Experimental series B: Lumentum PicoBlade, $\tau_p = 10 \text{ ps}$, $\lambda = 1064 \text{ nm}$, $d_0 \approx 55 \mu\text{m}$



WP2

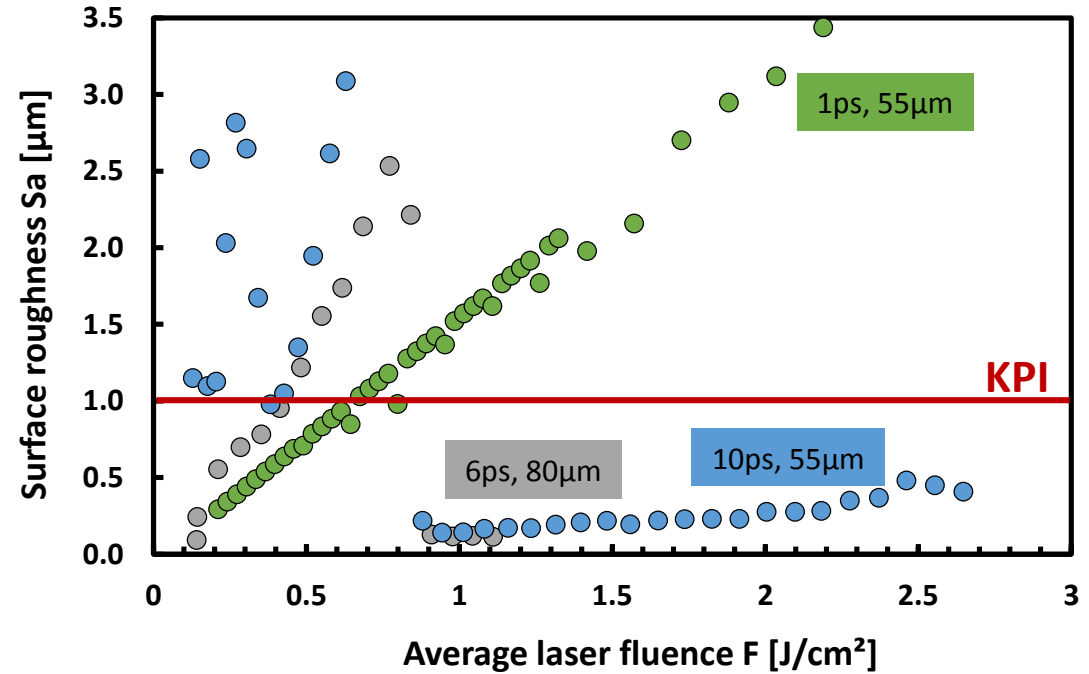
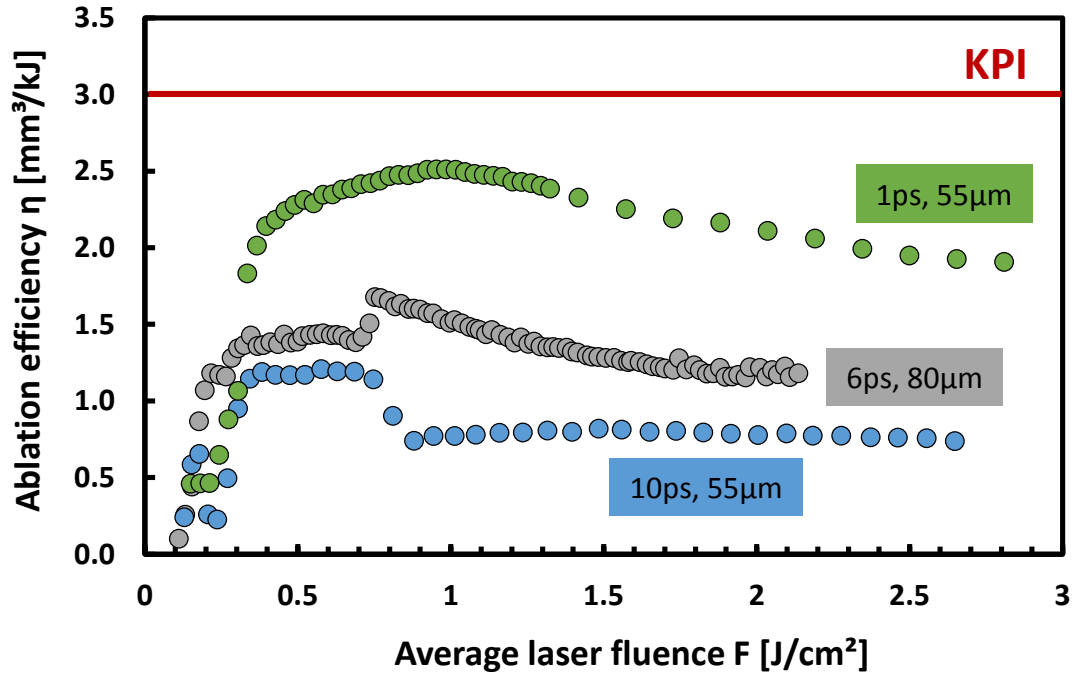
Experimental work at BOSCH: Fundamental studies

Experimental series B: Lumentum PicoBlade, $\tau_p = 10$ ps, $\lambda = 1064$ nm, $d_0 \approx 55$ μm



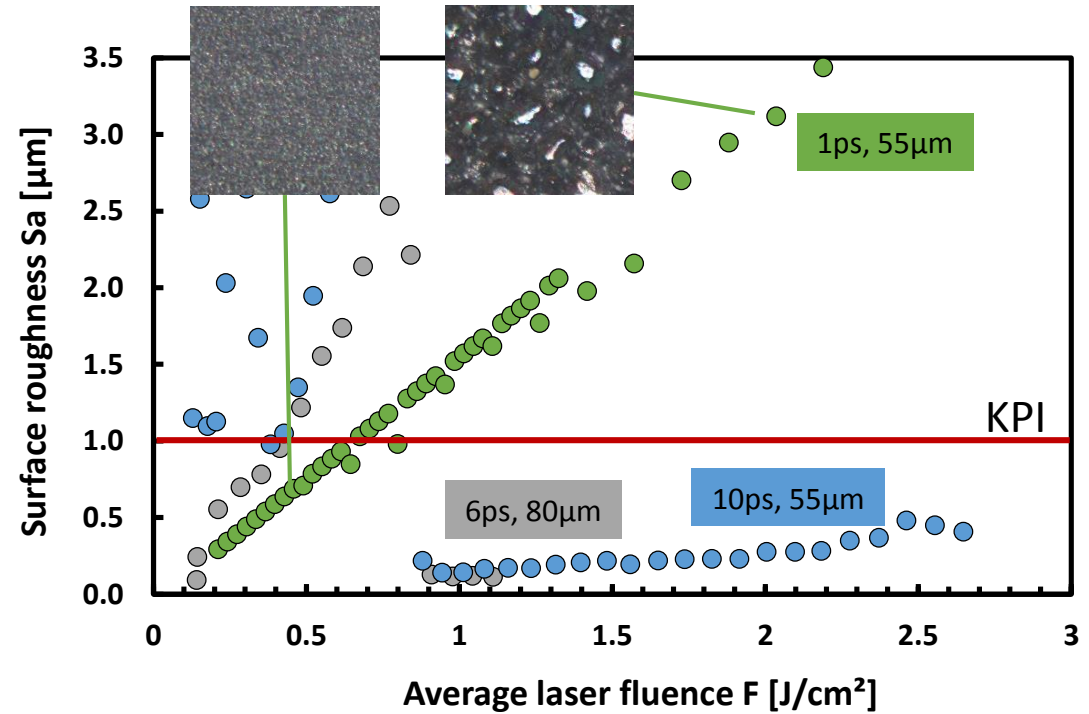
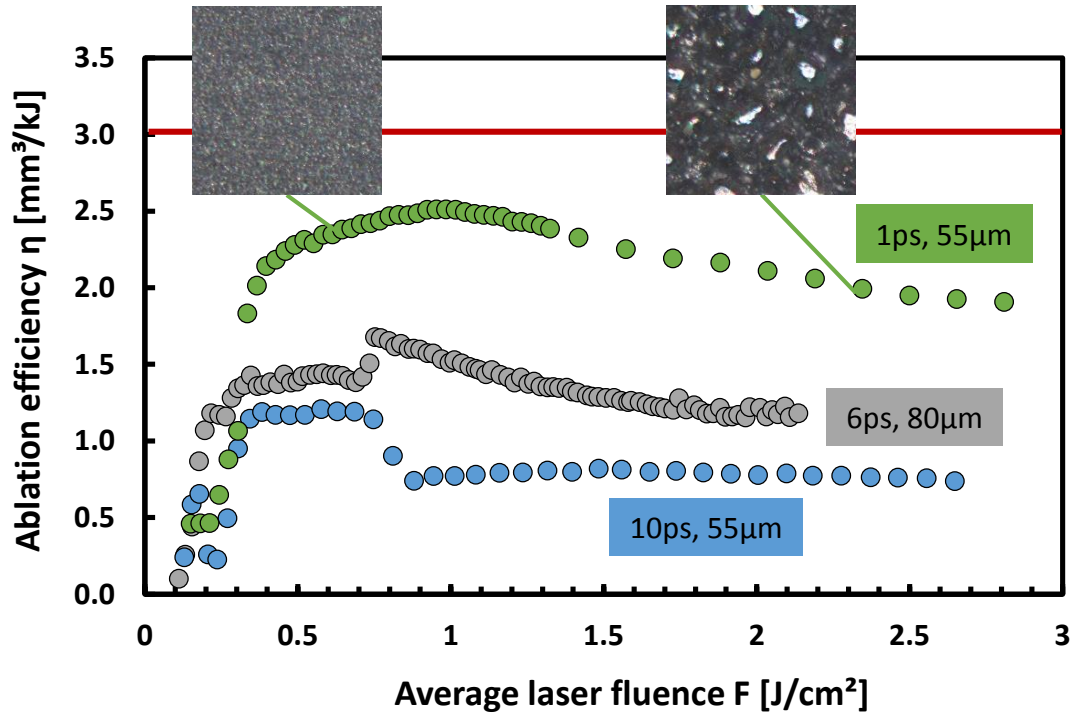
WP2 Experimental work at BOSCH: Fundamental studies

Experimental series C: Trumpf TruMicro 5050 Femto Edition, $\tau_p = 1 \text{ ps}$, $\lambda = 1030 \text{ nm}$, $d_0 \approx 55 \mu\text{m}$



WP2 Experimental work at BOSCH: Fundamental studies

Experimental series C: Trumpf TruMicro 5050 Femto Edition, $\tau_p = 1 \text{ ps}$, $\lambda = 1030 \text{ nm}$, $d_0 \approx 55 \mu\text{m}$



WP2 Experiments conducted by BOSCH at USTUTT

High-volume ablation on amplified TruMicro5000 @ USTUTT

- Objective: Assess process scalability to high laser power
- Amplified high-power laser system (670 W)
- Short total experimental times (max: 30 s)
- High max. scan speed (16 m/s)
- No wafer cooling applied
- High energy input causes wafer cracking above threshold values of:
 - max. specific line energy: 170 J/m at 4 m/s scan speed
 - max. energy input on 10x10 mm² square: approx. 3.5 kJ
- **Achieved average ablation rate: 0.29 mm³/s (including down times)**

Parameters (source: USTUTT)

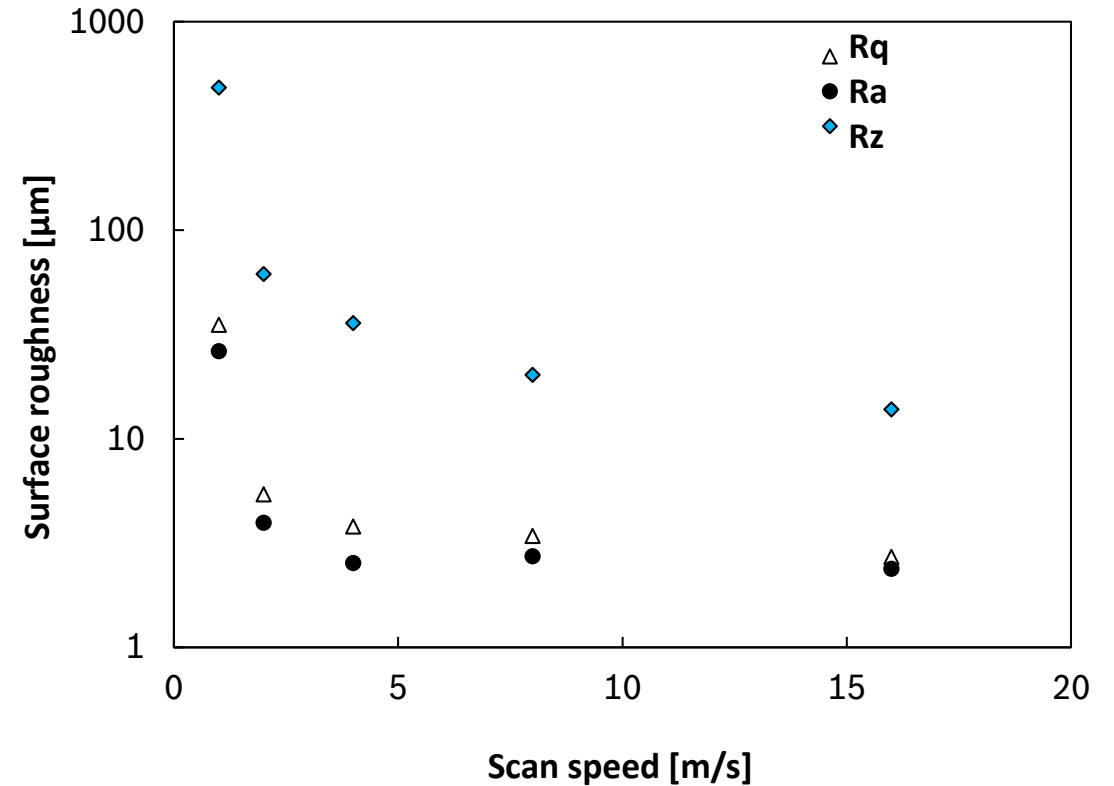
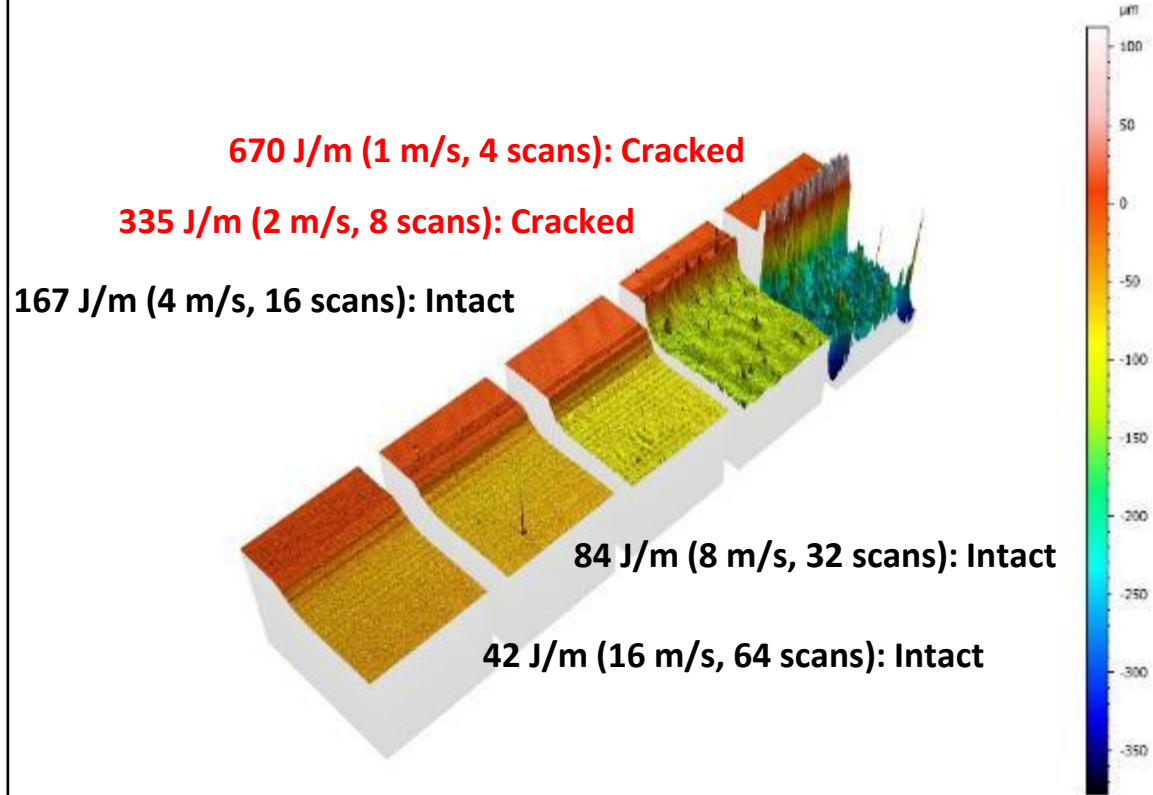
wavelength	λ	1030 nm
pulse duration	τ_p	6 ps
repetition rate	f_{rep}	300 kHz
maximum power	P_{max}	670 W
focus radius (x)	d_{fx}	140 μ m
focus radius (y)	d_{fy}	420 μ m
focal length	F	340 mm
beam quality factor	M^2	3
Si wafer diameter	D	200 mm
Si wafer thickness	h	1.35 mm
optics	Intelliscan20	



WP2

Experiments conducted by BOSCH at USTUTT

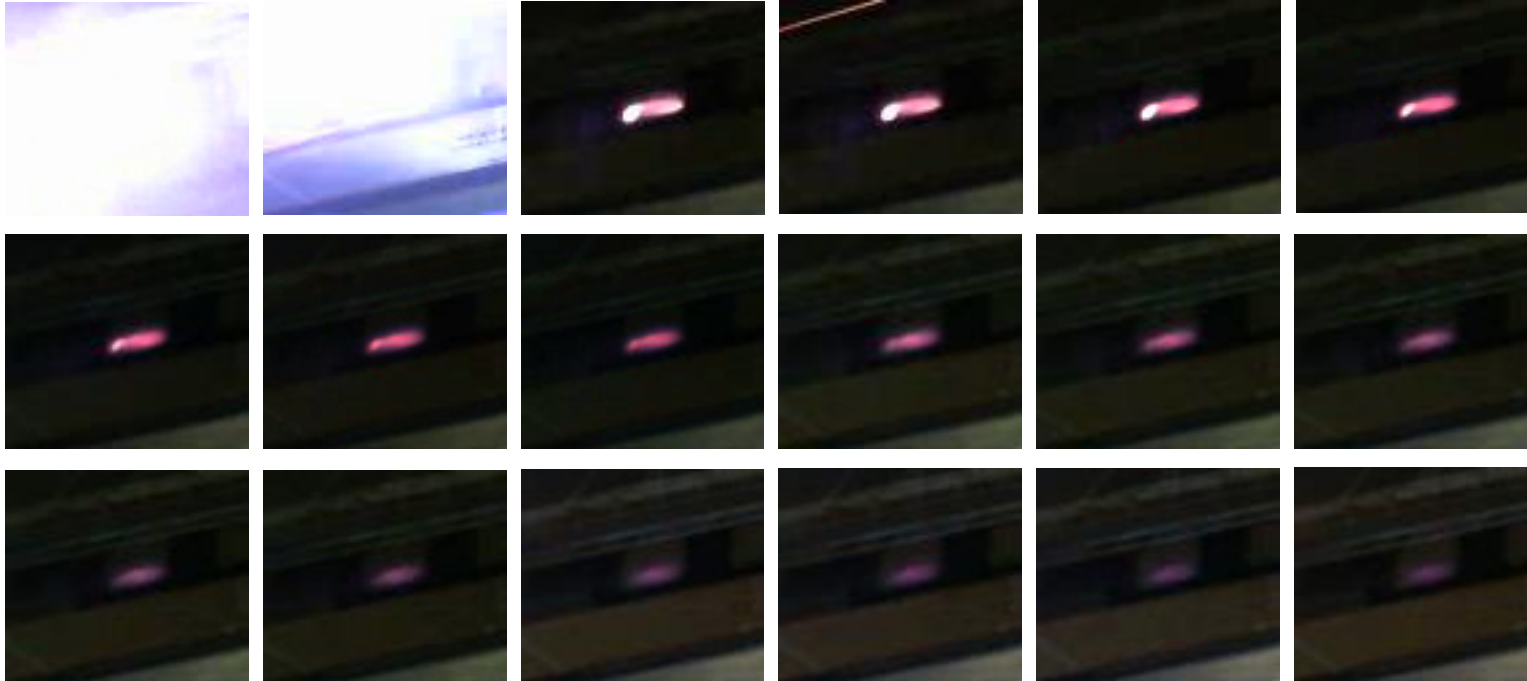
Result: Surface quality depends on specific line energy (J/m)



WP2

Experiments conducted by BOSCH at USTUTT

Camera pictures ($\Delta t = 40$ ms) \rightarrow ablated surface continues to glow subsequently to processing



Conclusion & Outlook

Summary

- Laser ablation: potential, but challenging process for 3D Si structuring
- 8 KPI's to determine process maturity
- Demonstrator geometry allows to track progress of KPI's
- Laser fluence: significant process parameter:
 - Ablation efficiency optimum between 0.5 and 1.0 J/cm²
 - Surface quality deteriorates above efficiency optimum
 - But: above threshold fluence, surface quality improves substantially
- Major challenge: Upscaling of process to reach productivity KPI (average ablation rate of 1 mm³/s)
- High-power laser experiments (BOSCH at USTUTT): heat accumulation results in wafer cracking

Focus on short- and medium term R&D work @ Bosch:

- Continue fundamental research on KPI enhancement
 - Include burst mode, fs ablation, investigate high-fluence ablation
- Specify system requirements based on experimental experience
- Design of experiments for process upscaling

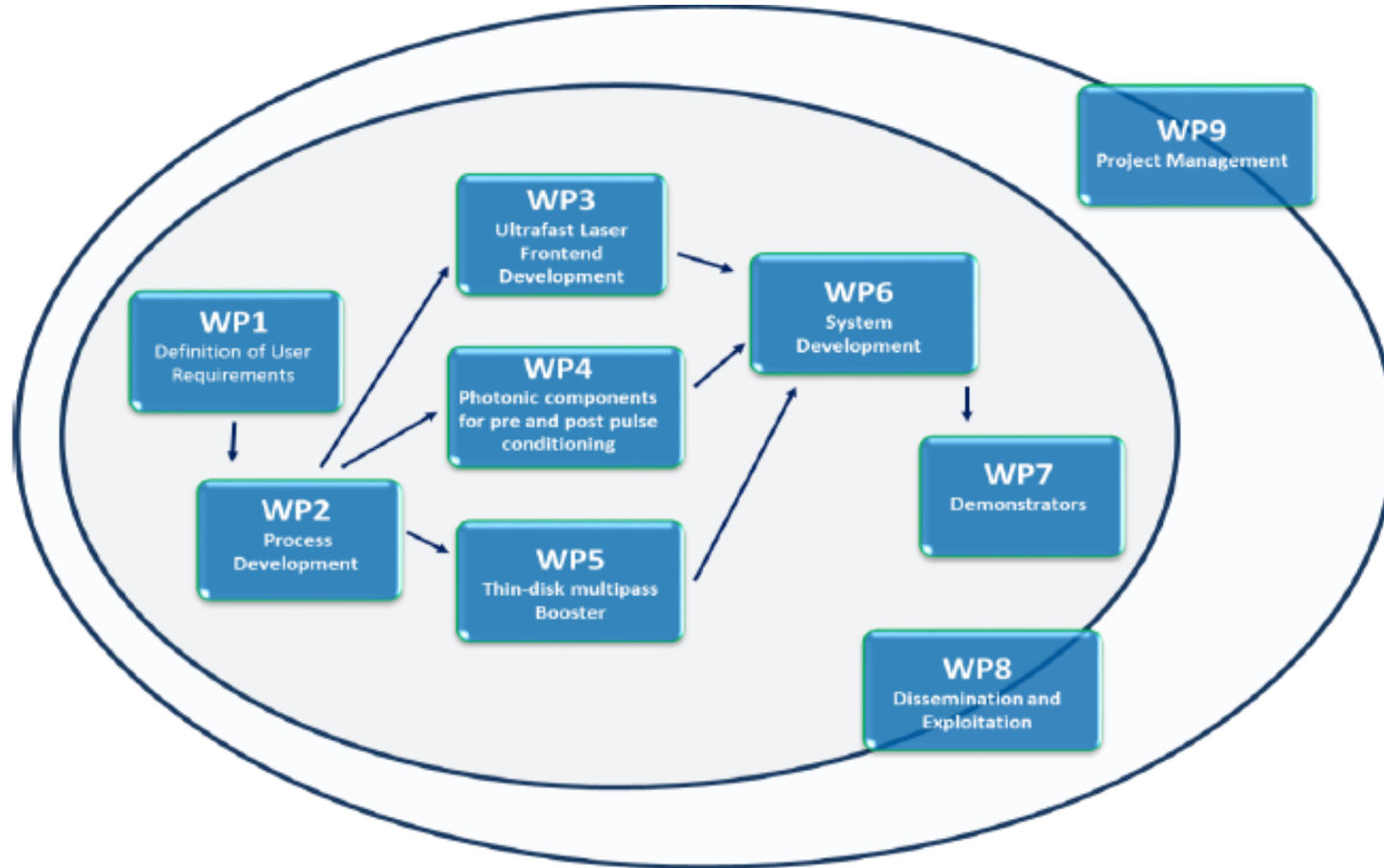
Class 4 Laser Professionals AG



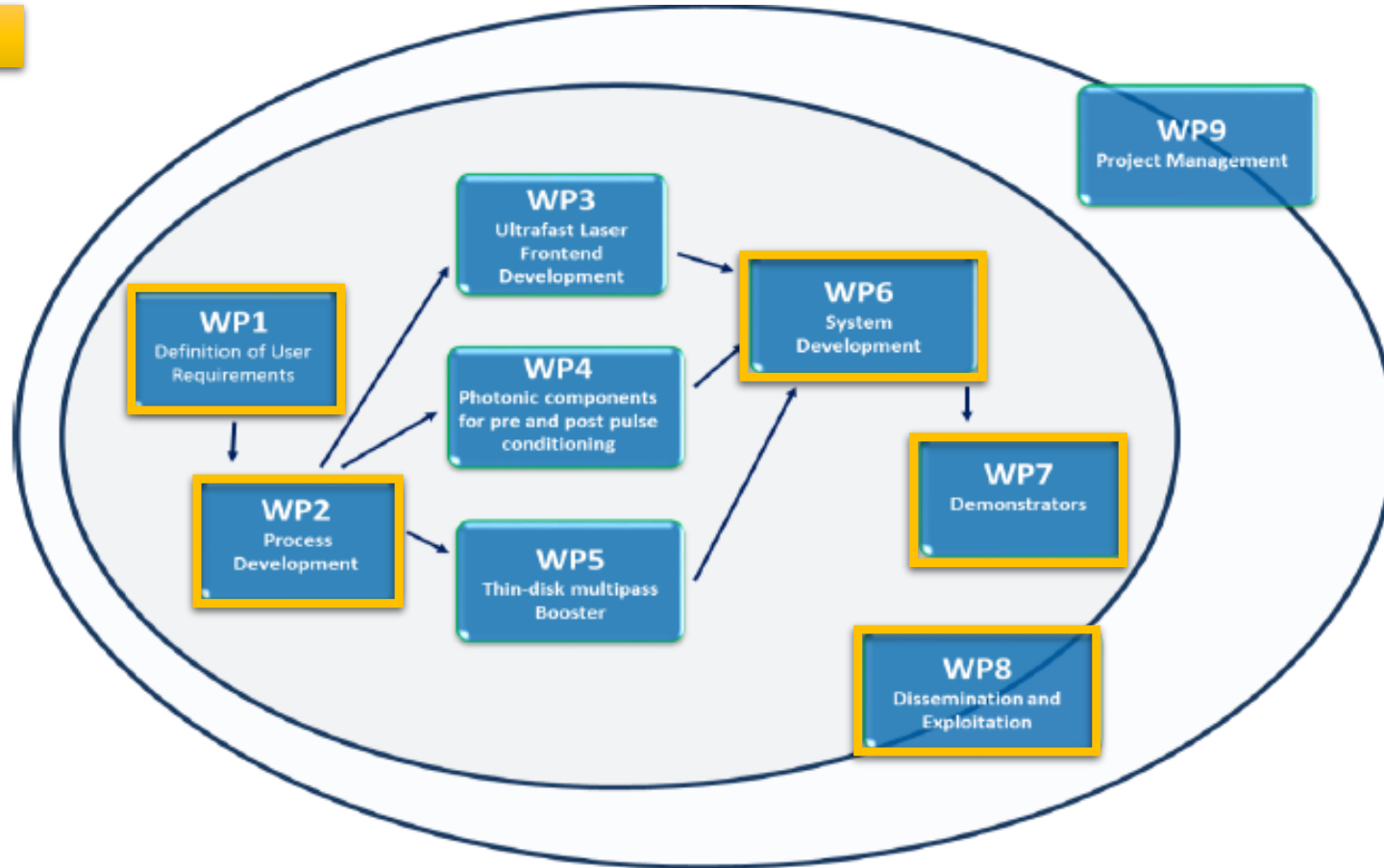
Noémie Dury



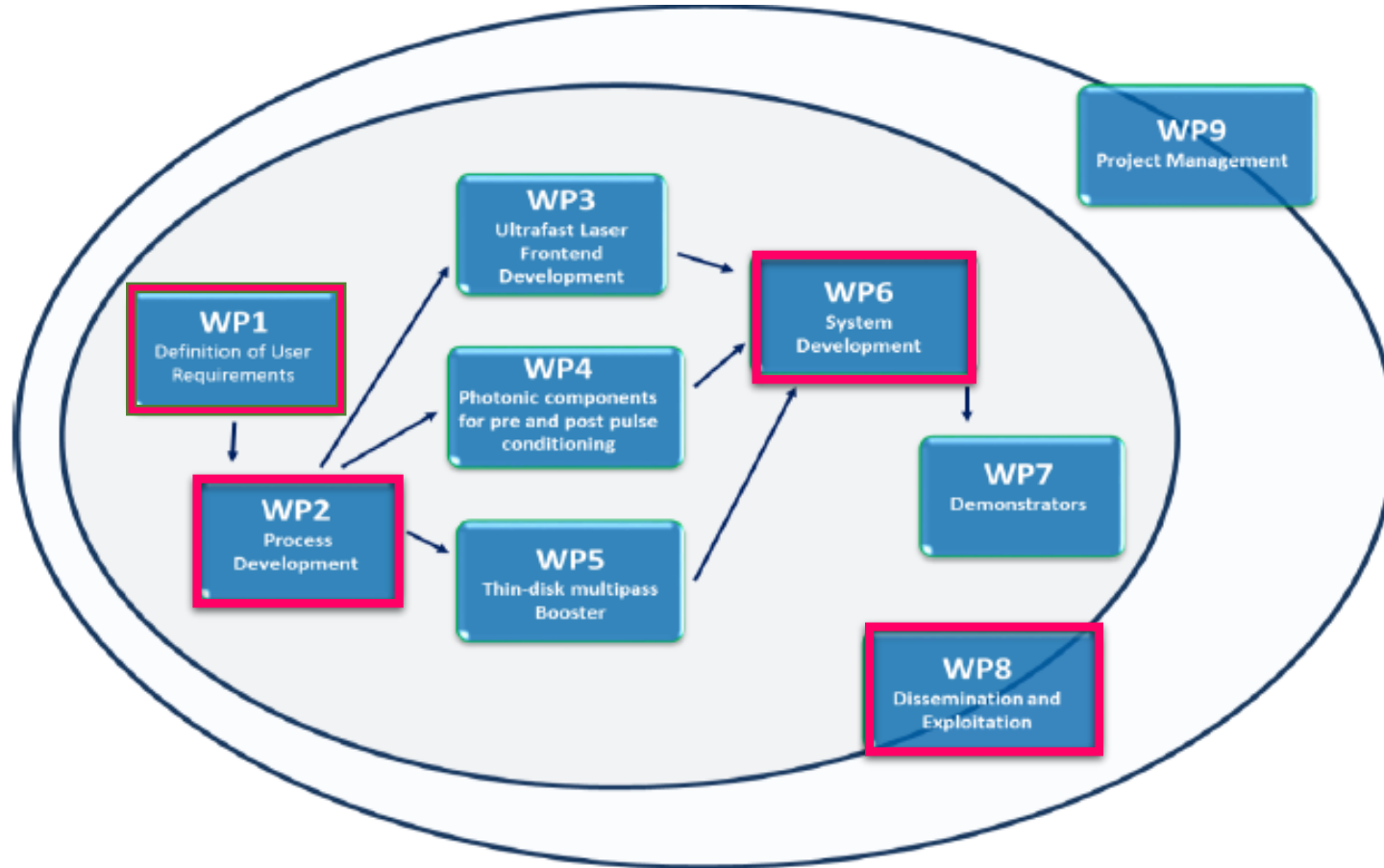
Work Packages



Class 4 Laser's Work Packages



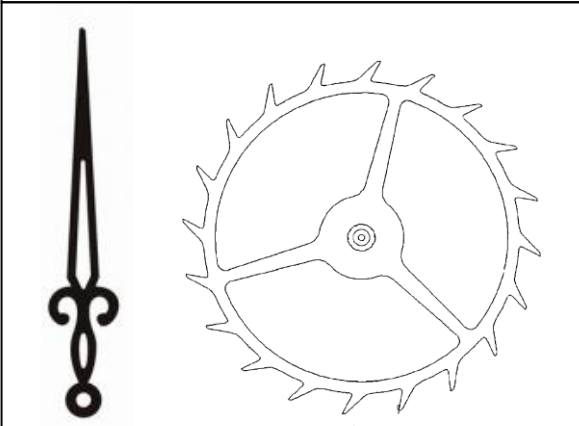
Work Packages presented today



WP1

Definition of user requirements

Benchmarking shape
Standardized watch arm
Standardized Gear



Key Performance Indicator	Unit	Target Value
Parts thickness	mm	0.1 – 0.5
Material covered	Metal, ceramic, sapphire	
General dimensions tolerances	μm	From ± 5 to ± 20
Specific dimensions tolerances	μm	From ± 2 to +-5
Smallest holes	μm	From 50 to 100
Maximal side steepness (taper)	Relative to dimension tolerances	
Average cutting speed (relative to shape and thickness)	mm/min	≥ 300
Shape deviation	μm	+ - 2
Surface roughness (non-functional)	μm	0.4 (N5)
Surface roughness (functional)	μm	0.1 (N3)

Informal partnership with a big watch making company for validation of the parts



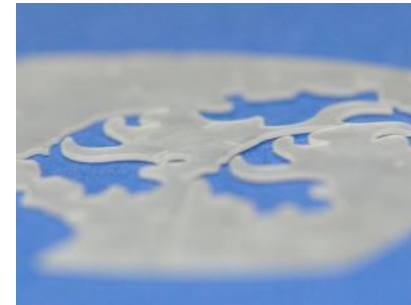
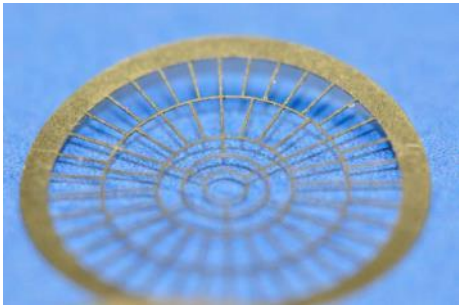
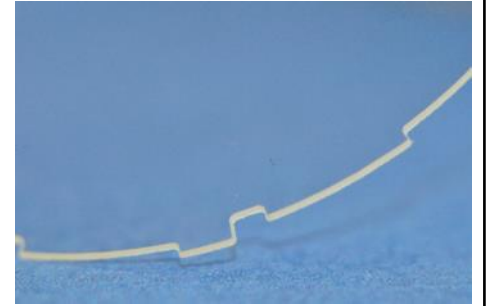
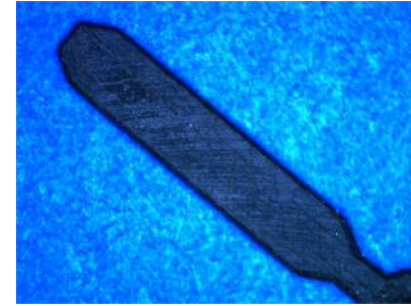
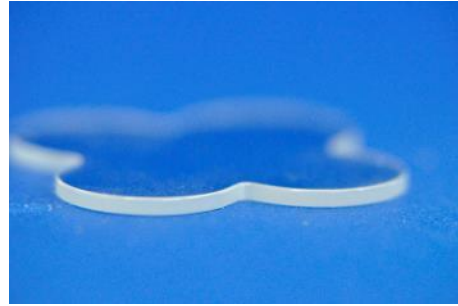
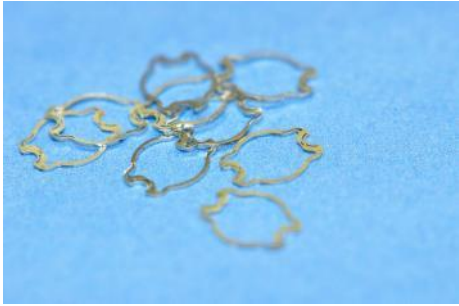
WP1	Definition of user requirements		
WP1 - M01-M12 (January 17) - Definition of User Requirements C4L - 2.5 MM = 446.25 H			
Definition of application requirements Process development pre tests			
Task 1.1 : M01- M04 (May 16) Collection of application specifications	Task 1.2 : M02 - M12 (January 17) Process and system specifications	Task 1.3: M04 - M12 (January 17) Assessment and validation of technical progress	Task 1.4: M01 - M12 (January 17) Interface requirements
Installation of the laser needed for the trials at C4L Assistance of E6 for the first trials to define the laser specs	Started in March : cutting and ablation trials for benchmarking for diamond ablation and cutting of watch parts . Calculation of the foreseen needed laser parameters	C4L & E6 Define necessary characterization and measurement methods. Define benchmark processes; define key performance indicators (KPI) for quantitative progress assessment. September 16	C4L sends AMP the dimensions and already known spec of the machine --> KW8
E6 make a document to summarize their need for diamond polishing	C4L & E6 - first ablation trials to determine the ablation threshold / required / pulse duration / laser parameters for th diamond ablation		What do the customer need. Will feed the WP6 T6.1 - E6
C4L make a document to summarize their need for cutting of watch parts.	the cutting trials for the watch componants will be started when the system to combine axes with rotating optic is available at C4L : planned october/ November 2016		fill in the table from Lasea
Deliverable sent CW26	C4L & E6 prepare a common document with enduser requirement and system manufacturer requirement this document is then sent to AMP with cc USTUTT and BOSCH.		
	fill in the table from Lasea		



WP2

Process Development

Work completed



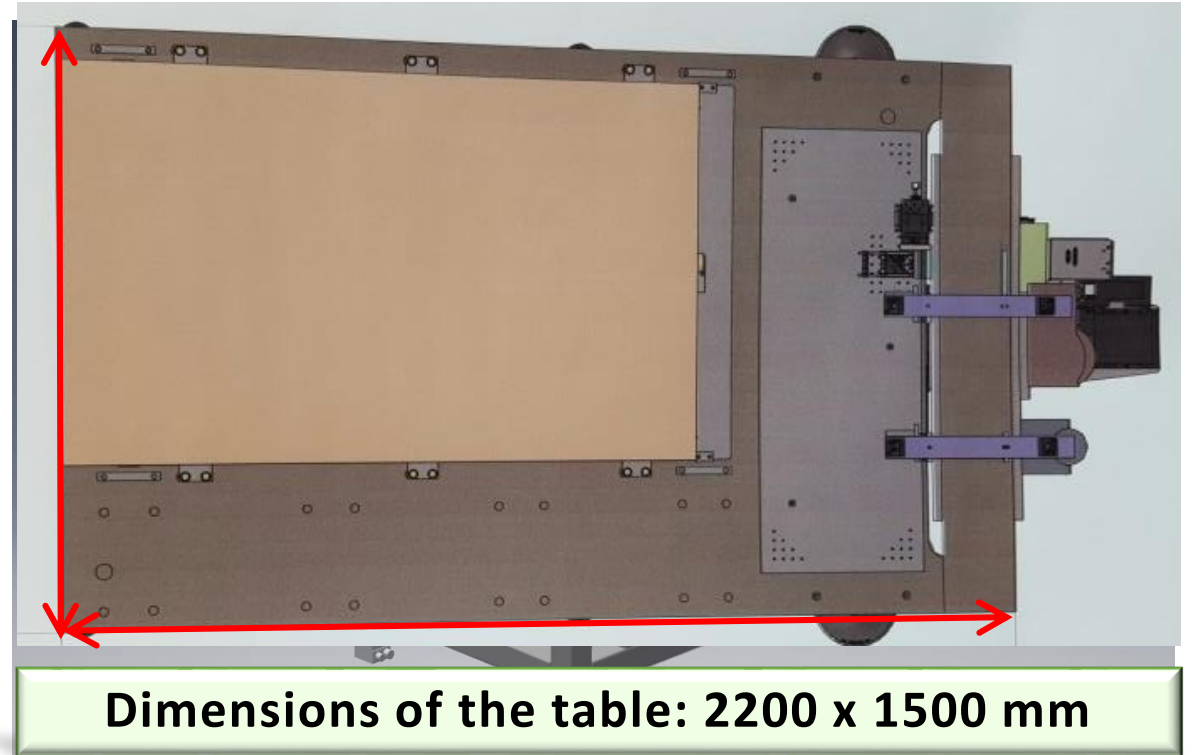
WP2	Process Development	
WP2 - M04 (May 16) - M30 (July 18) - Process Development C4L - 13 MM = 2320.5 H		
Process developement for watch parts cutting and diamond polishing		
Task 2.2 : M04-M24 (January 18) Fundamental process development fine cutting of metals (LEAD)	Task 2.3 : M04 - M24 (January 18) Fundamental process development diamond ablation	Task 2.4: M22 (November 17) - M30 (July 18) Upscaling of applications for high throughput
Start in March : cutting trials for benchmarking. Calculation of the forseen needed laser parameters	Start in March : ablation trials for benchmarking. Calculation of the forseen needed laser parameters	
the cutting trials for the watch componants will be started when the system to combine axes with rotating optic is available at C4L : planned october 2016	C4L & E6 - first ablation trials to determine the ablation threshold / required / pulse duration / laser paameters for th diamond ablation	



WP6

System development

Work completed



WP6

System development : Scanning system

- Development of topography sensor to overcome flatness issue and surface defects
- Topography sensor scans surface and creates a BITMAP image as below

The diagram illustrates the measurement system components and their interaction:

- Measurement System:** Contains an SLD - Super luminescent diode and a Spectrometer, connected via a 50% / 50% beam splitter to a Reference path (a).
- Beam coupling / Dichroic mirror:** Directs the laser beam into the scanner system.
- Scanner system:** Scans the beam across the workpiece.
- Focusing Lens:** Focuses the beam onto the workpiece.
- Workpiece:** The surface being scanned.

The photograph shows the physical implementation of this system, including a computer monitor displaying the software interface.

The BITMAP image shows a feature to be ablated, with a zoomed-in view of the feature's geometry. The microscope picture shows the ablated surface, which is highly reflective and textured.

BITMAP image of feature to ablate

Microscope picture of ablated surface



WP6	System development
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Next 6 months

WP6 - M03-M42 - System development (LEAD)

C4L - 28.5 MM = 5087.25 H

Development of the system for Watch parts cutting and diamond polishing

Task 6.4: M08 - M36 (January 19) System layout and build-up (LEAD)	Task 6.2 : M03 - M15 (April 17) Task 6.5: M08 - M24 (January 18) Definition of laser & optics sizes, optics Integration of laser and optics (LEAD) specifications (incl. fibre)	Task 6.3: M08 - M22 (November 17) Task 6.6: M12 - M42 (July 19) Development of the interfaces (LEAD) Test and validation
5 axes system design for 3 optical stations and 2 different lasers	optimisation of the OCT vision and scanning device for diamond polishing	
System build up		



WP8

Dissemination & Exploitation (partner activities)

One talk during the
EPMT / EPHJ / SMT fair in Geneva,
presenting Hiperdias

